

# Scanning Electron Microscopy

An Introduction by Lorenz Lechner

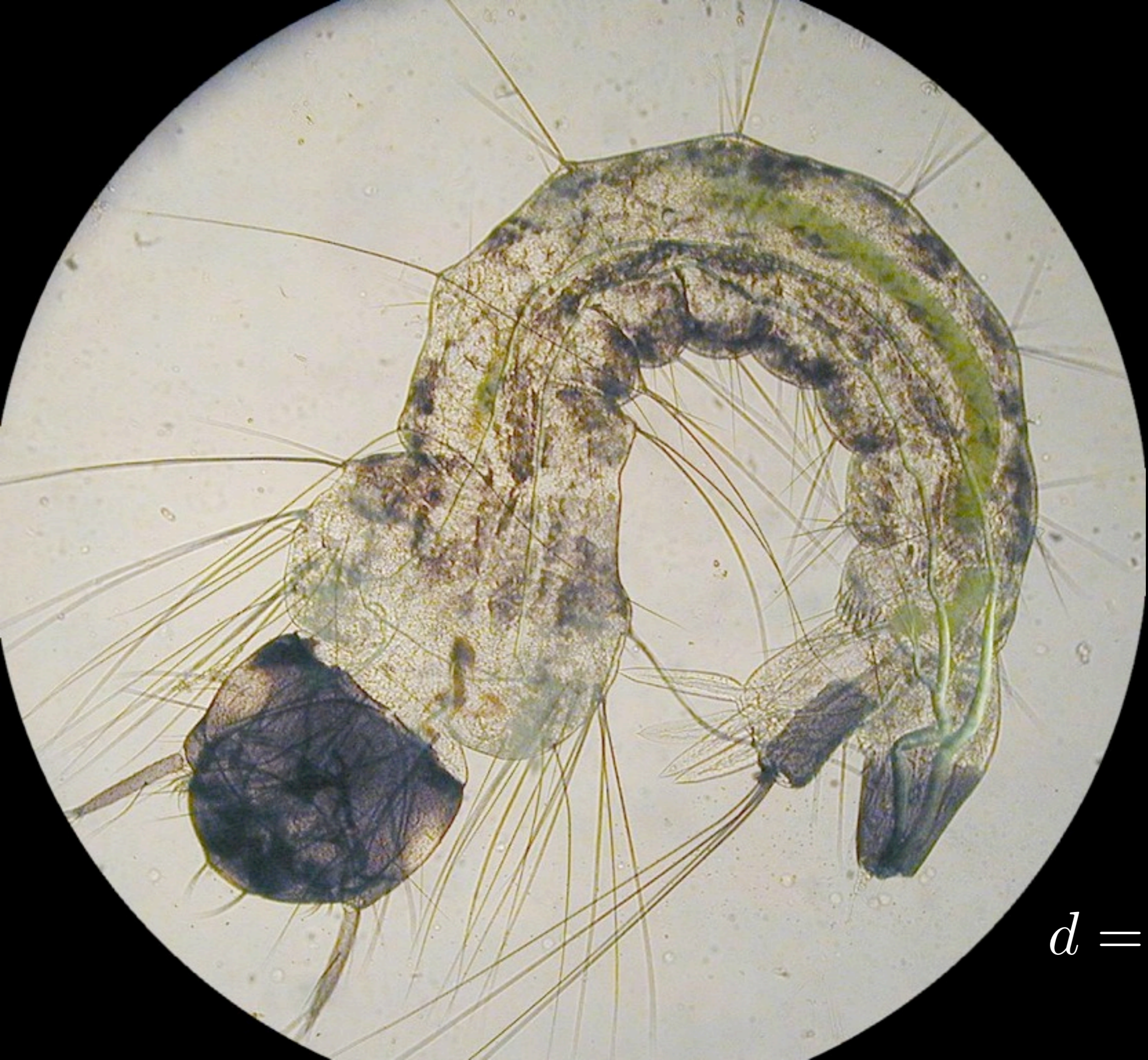
# Learning Goals

- Basic Operating Principles
- SEM Hardware
- Understand/acquire SEM images
- SEM Applications
- *Focused Ion Beam Microscopy*



# Overview

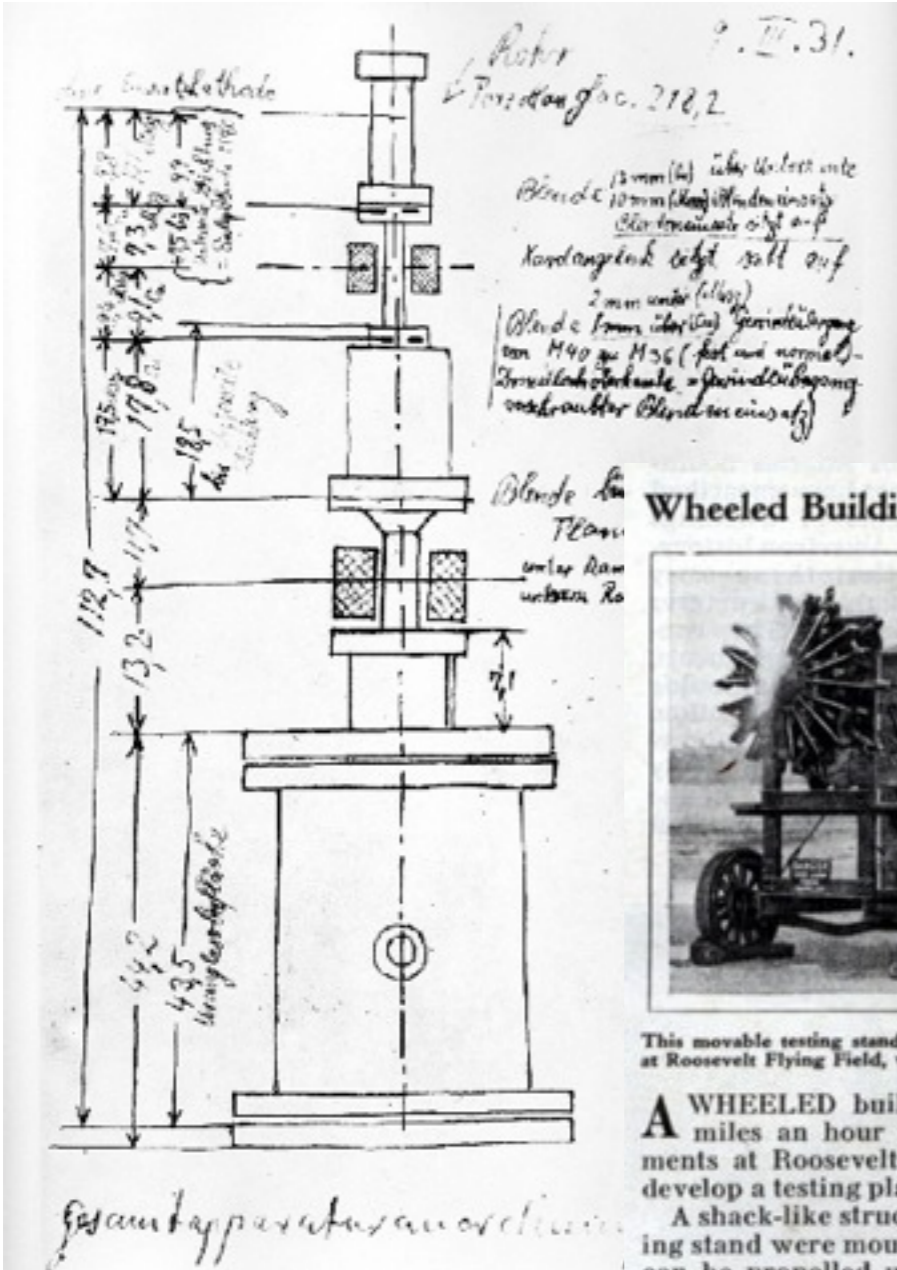




$$d = \frac{\lambda}{2n \sin \alpha}$$



**Some history...**



**Wheeled Building Travels 70 mph**



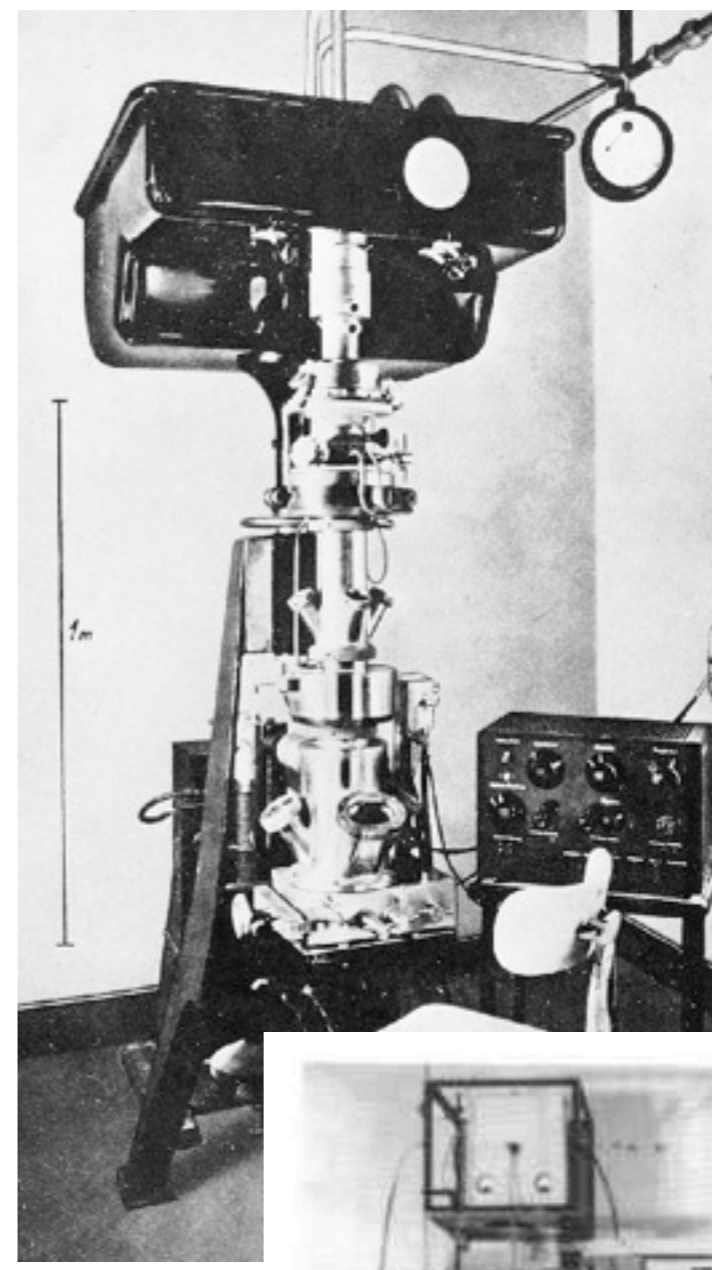
This movable testing stand for airplane engines, developed at Roosevelt Flying Field, will travel seventy miles an hour.

**A** WHEELED building which travels 70 miles an hour is the result of experiments at Roosevelt Field, Long Island, to develop a testing plant for airplane engines. A shack-like structure and an engine testing stand were mounted on a chassis which can be propelled under its own power at better than mile-a-minute speed. The advantage of the novel device lies in the fact that engine tests may be conducted at any part of the field, owing to the mobility of the testing stand.

**Machine Magnifies 10,000 Times**

**U**SING electrons instead of light rays to "see" tiny objects, a German scientist has developed a machine which, by magnification in two stages, enlarges objects about 10,000 times. Maximum enlargement usually possible with optical instruments is 3,500 times. Glass lenses cannot be used in the electron microscope. Electric or magnetic fields take their place, bending the electron streams as lenses bend or focus light rays.

Modern Mechanix (Nov. 1934)



Ernst Ruska + Max Knoll

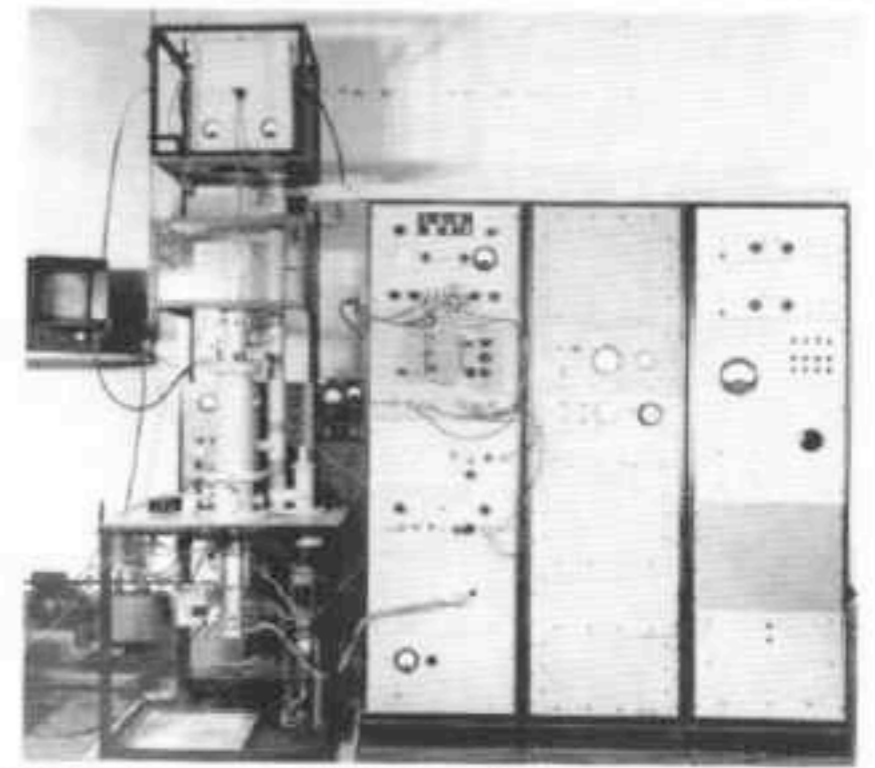


Fig. 12 Photograph of SEM 1 taken in 1953.

# This is not an SEM...

...since transmission electron microscopy is fundamentally different!



# Basic Operating Principle

**Hardware**





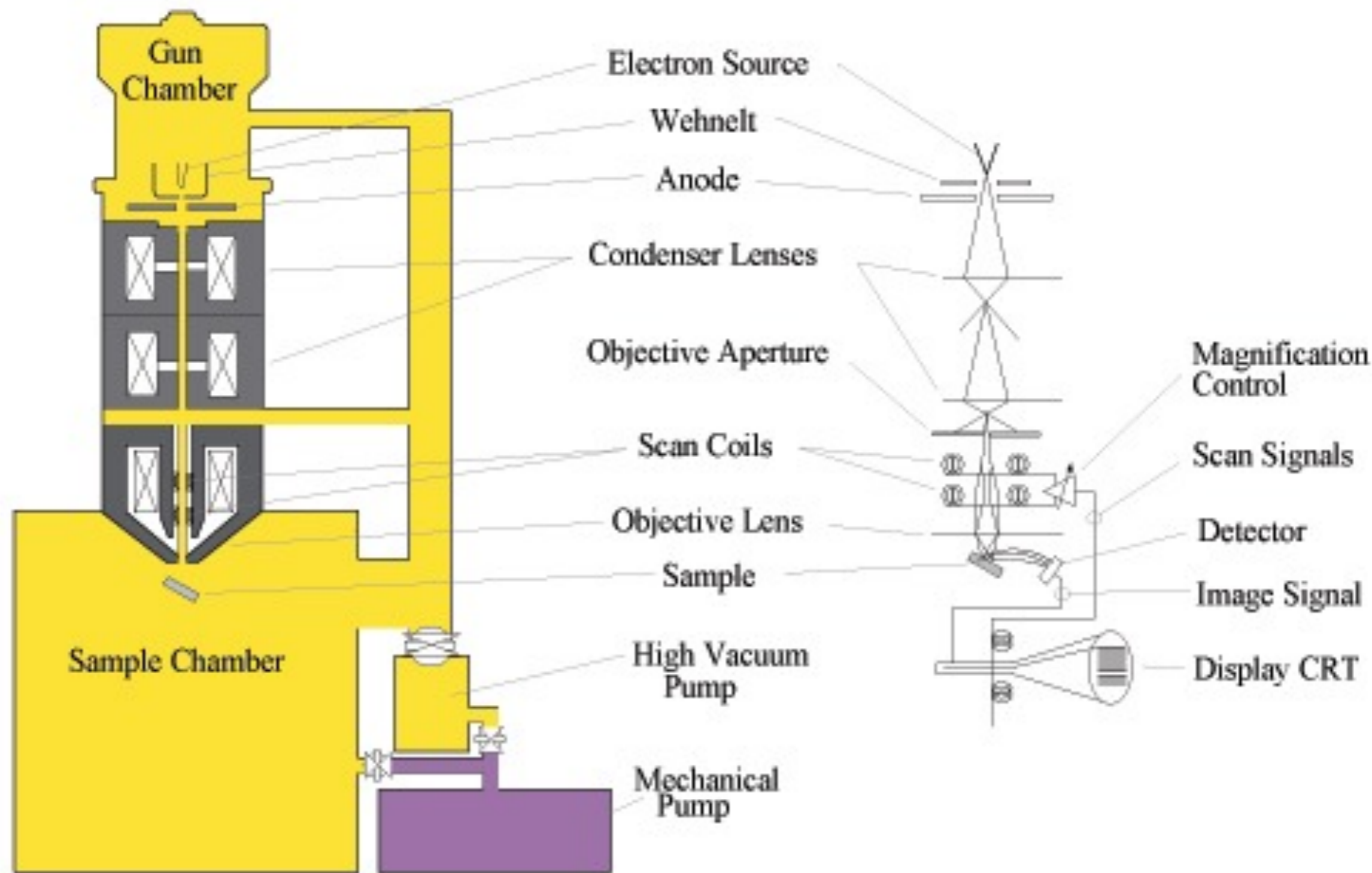
GEMINI

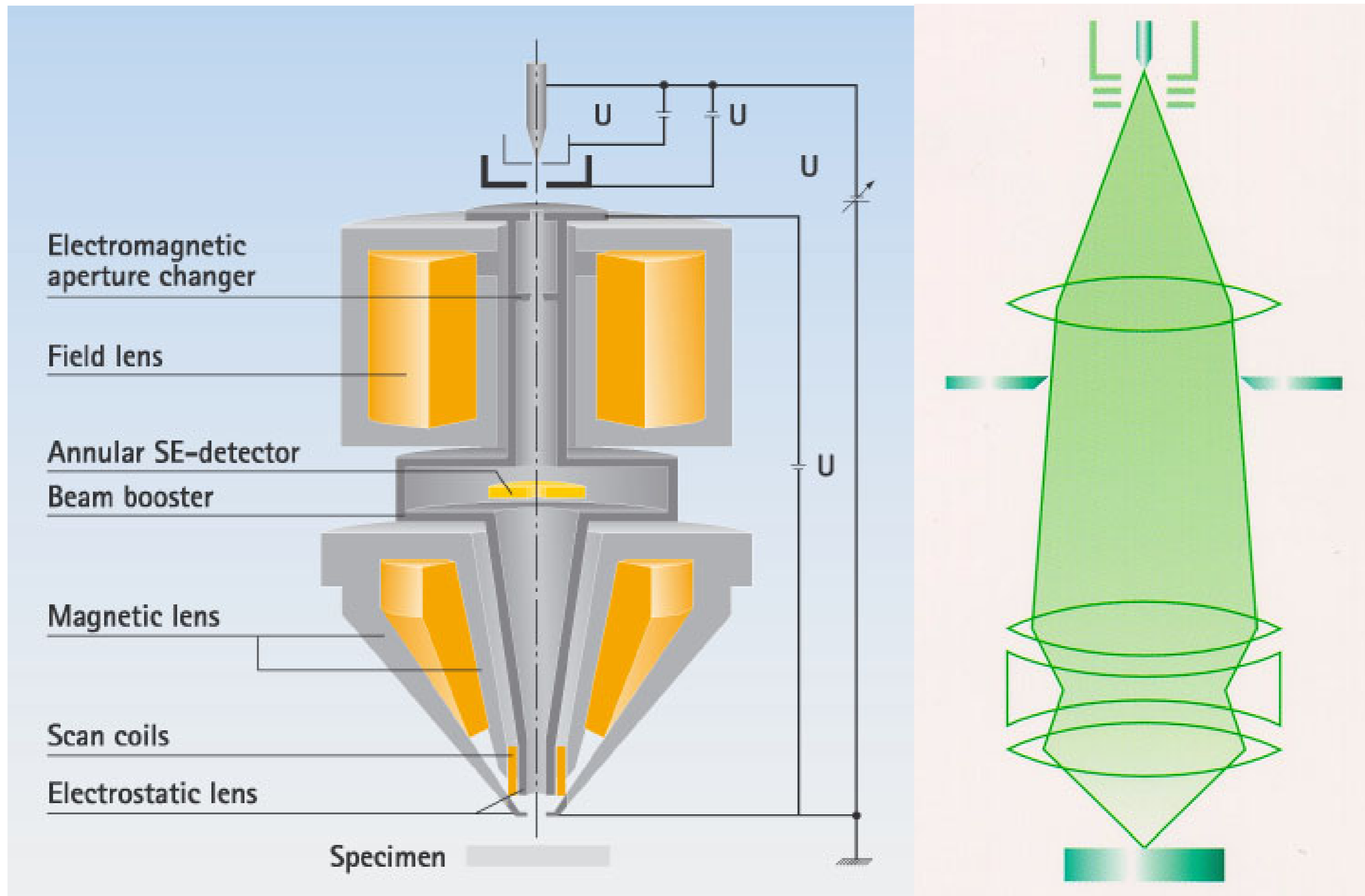


SUPRA 40



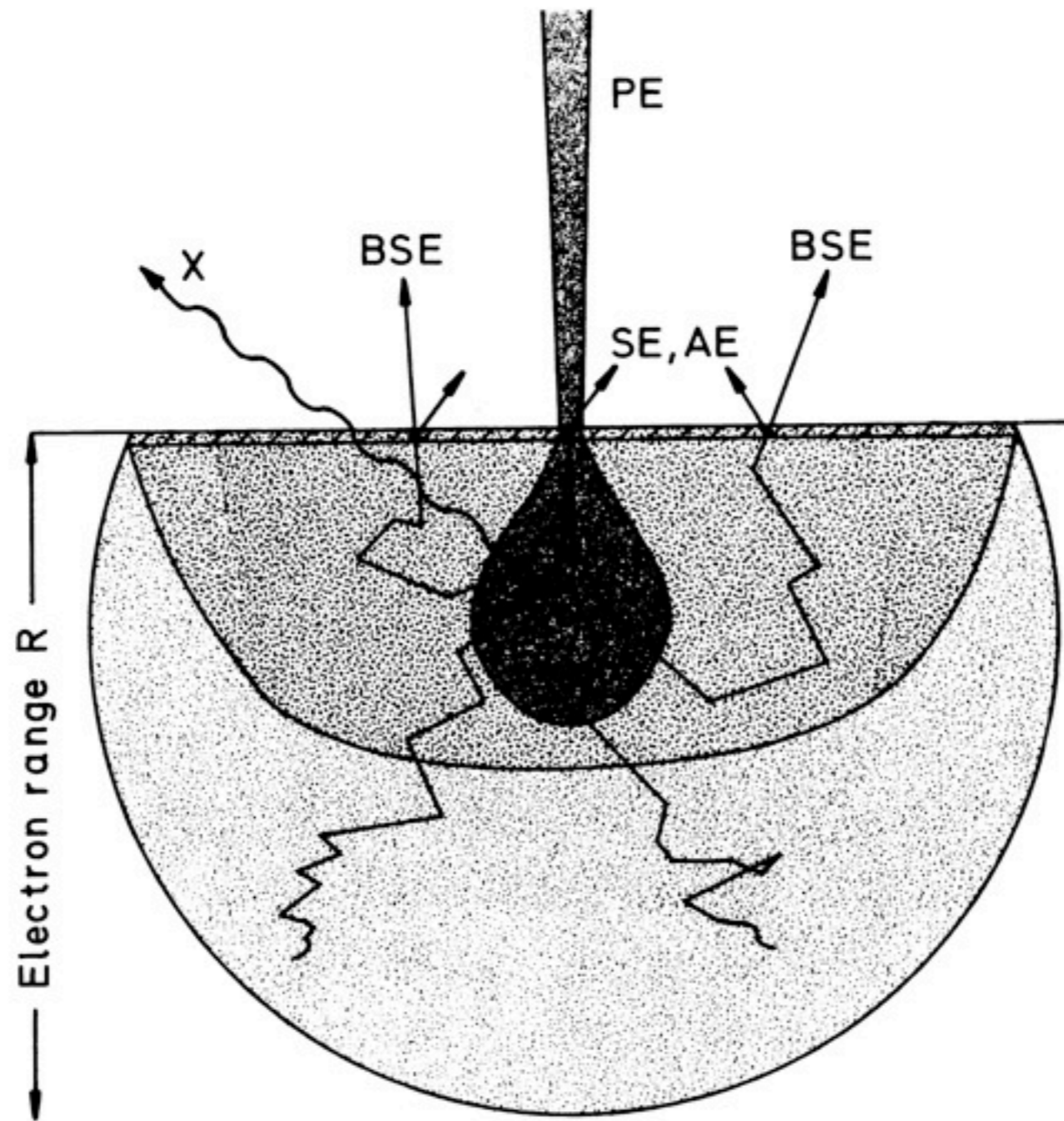




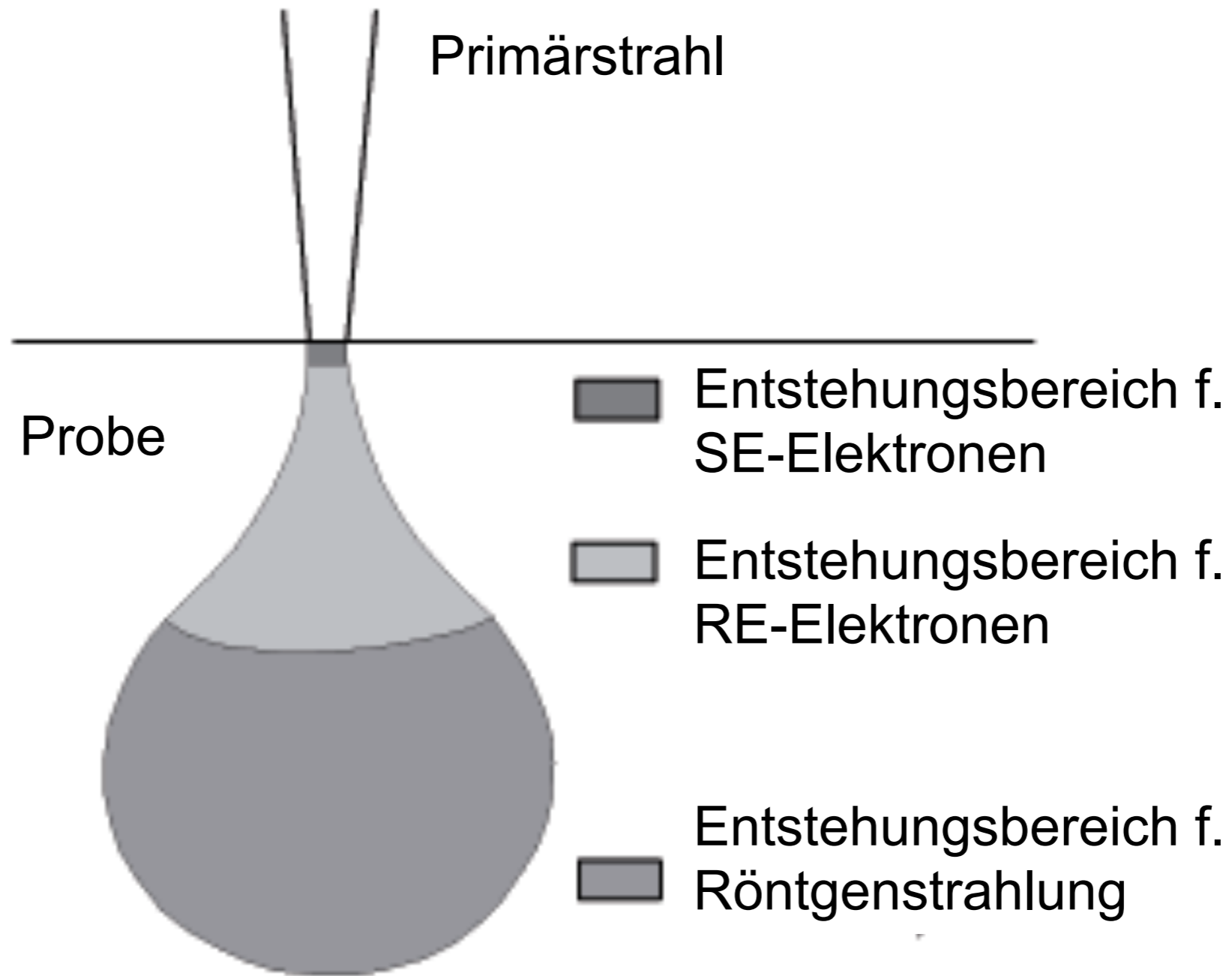


# Electron Optics

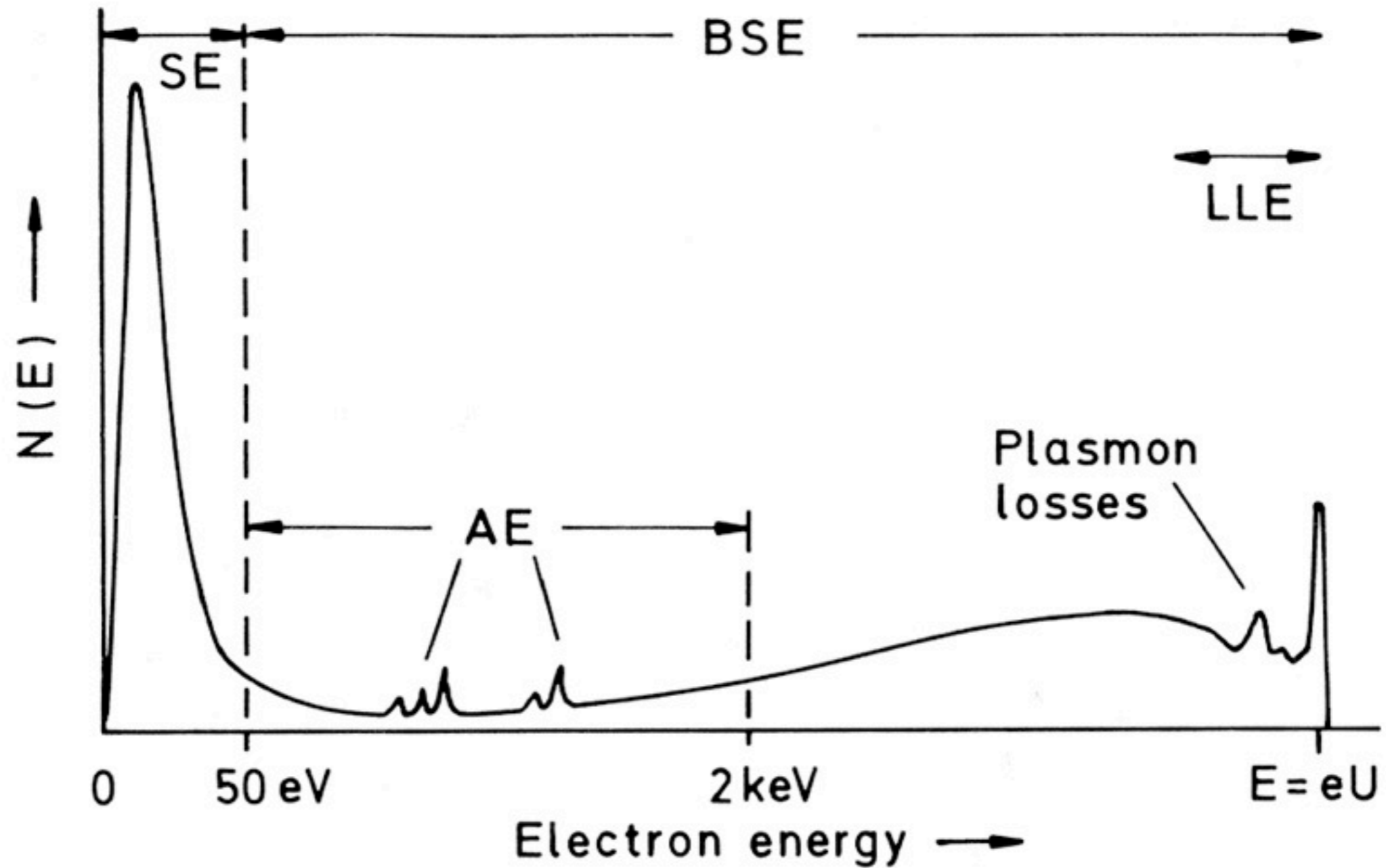
# Electron Interaction



# Interaction Volume



# Electron Species



# Electrons Energy

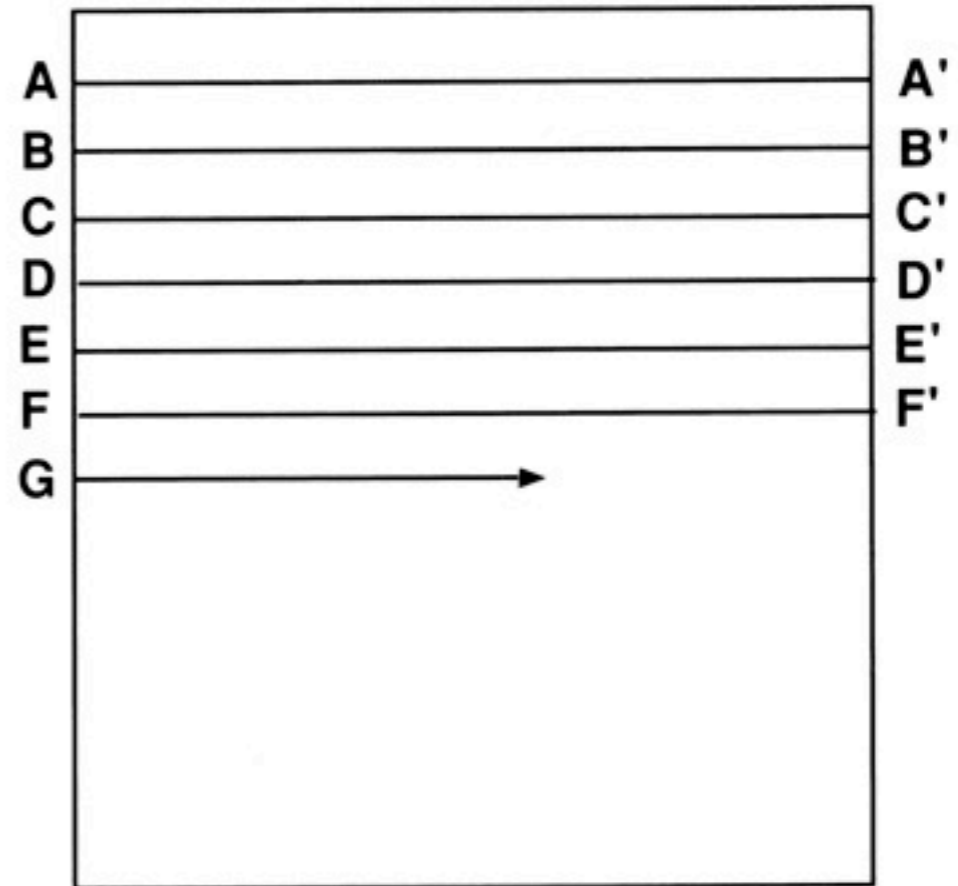
# SEM Imaging

# Fundamentals

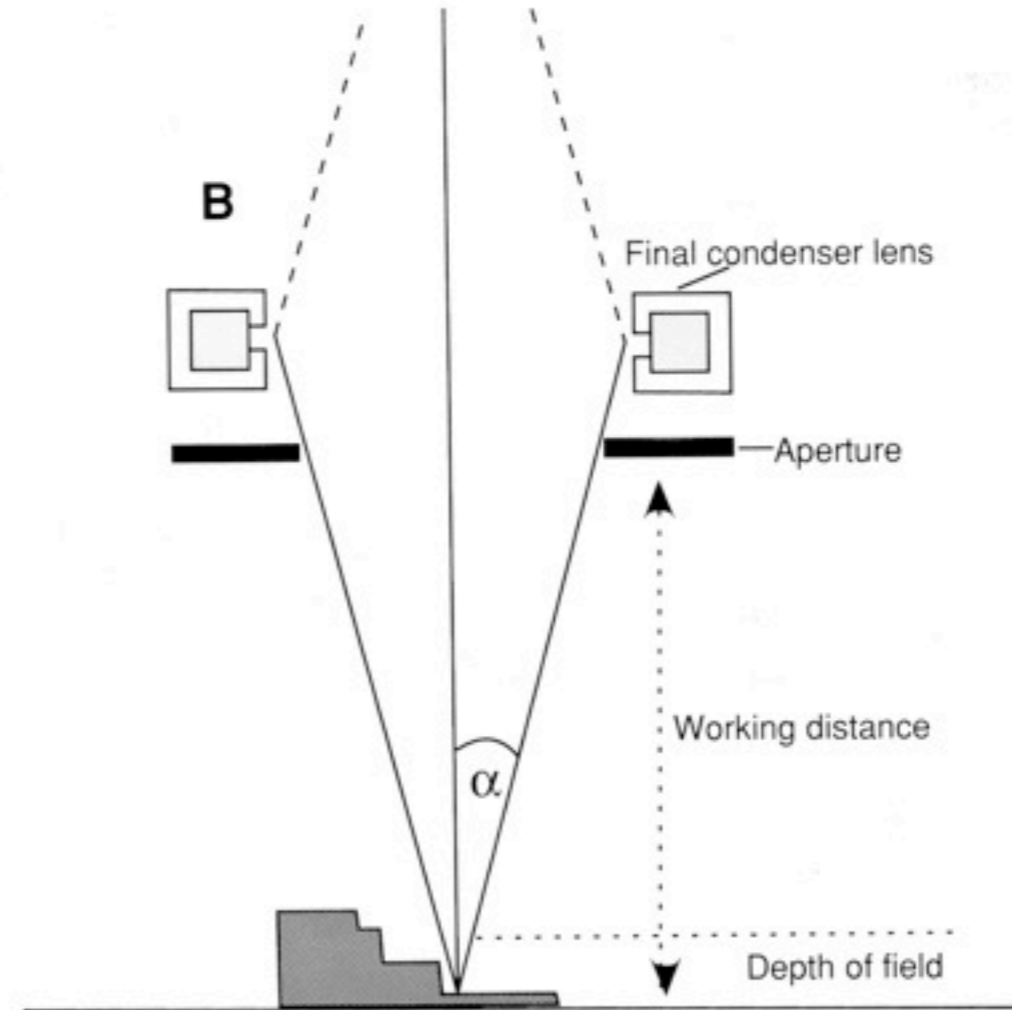
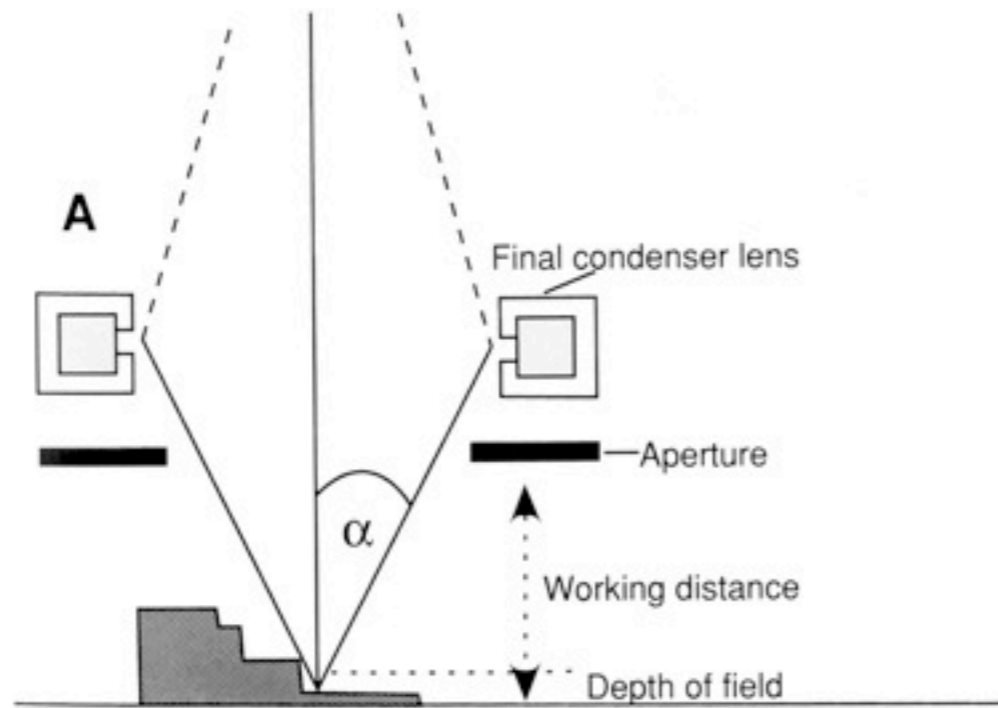
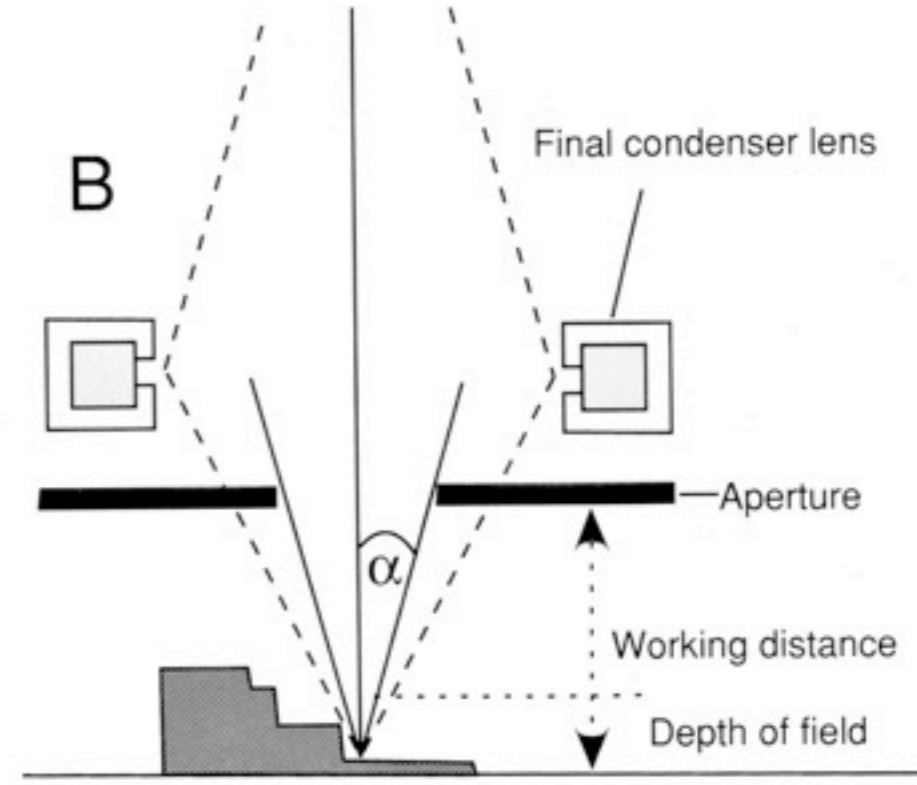
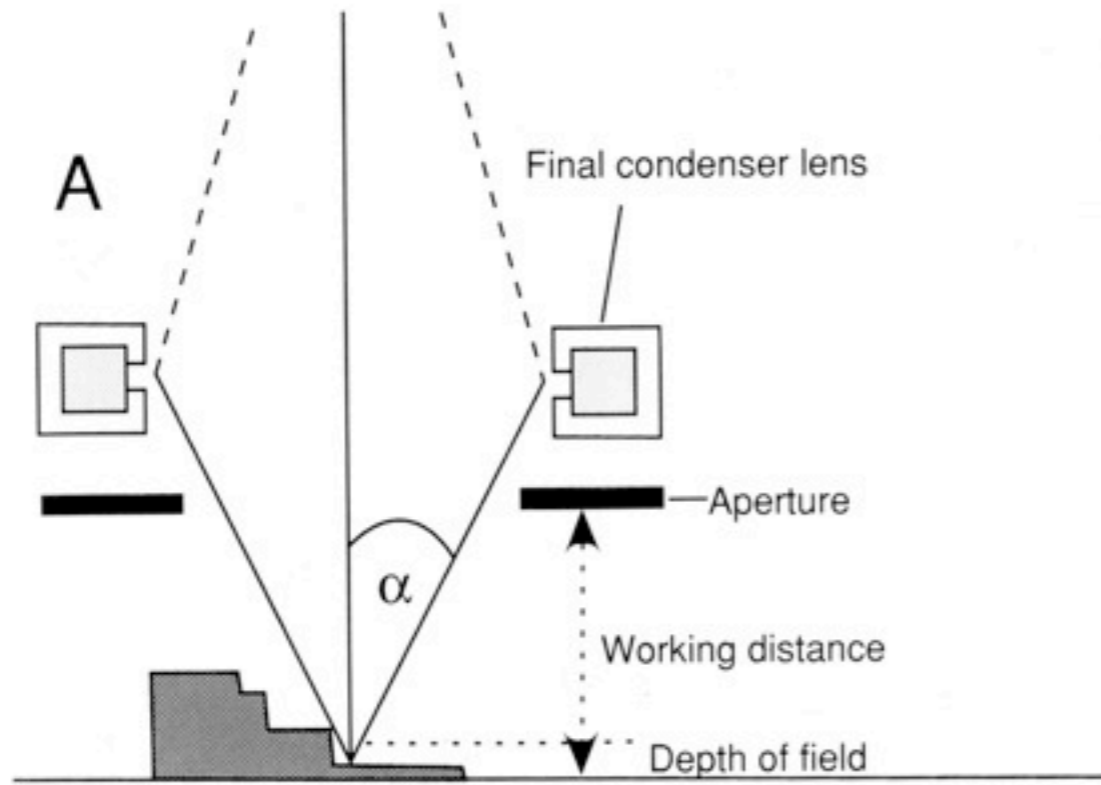


# Scanning

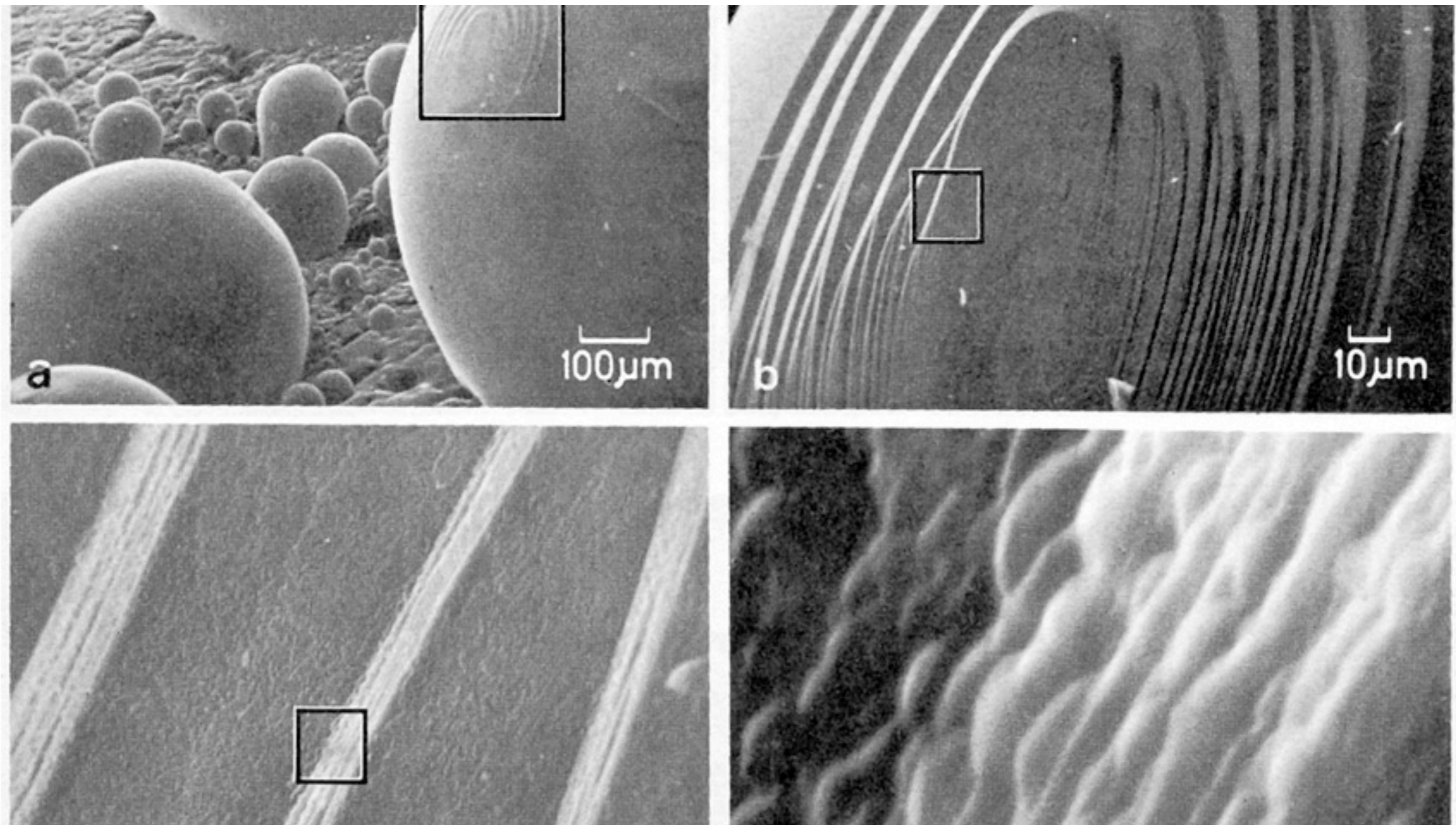
## Electron Microscopy



**Figure 7-4** The focused beam of electrons is scanned in a raster pattern over the specimen surface. The first scan is from A to A', with the beam moving down and then scanning line B to B', etc. (Redrawn from Postek, et al, 1980.)



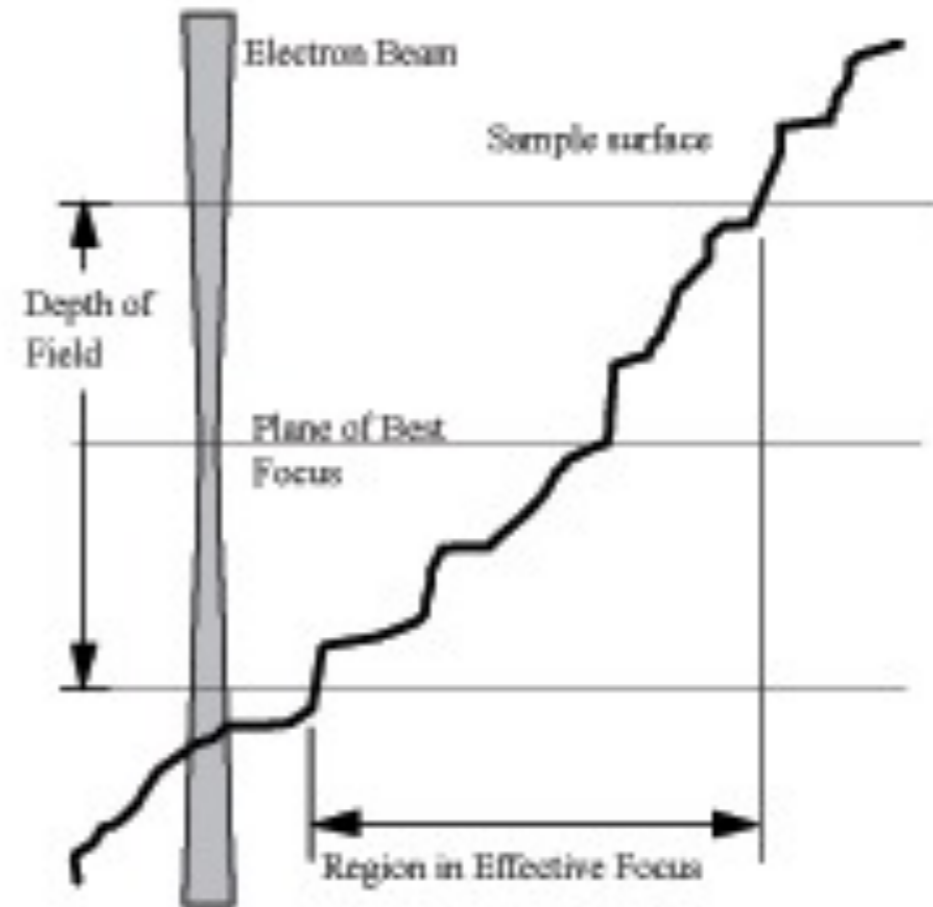
# Electron Beam Shape



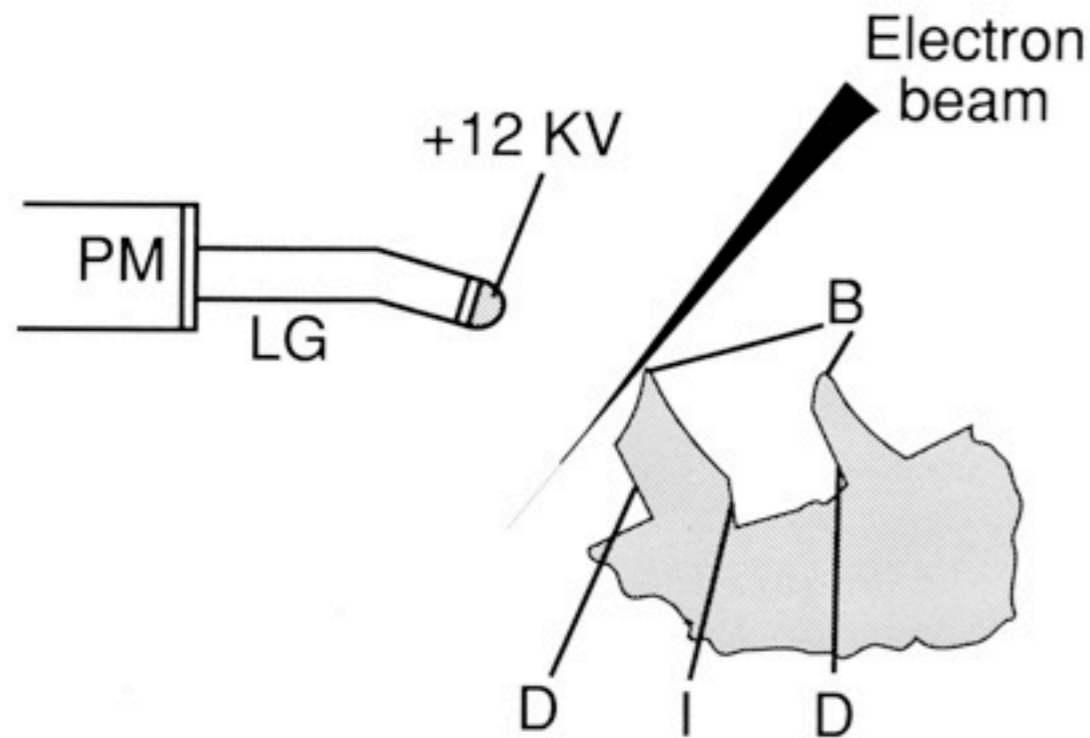
**Large Depth of Focus**

# “Infinite Focus”

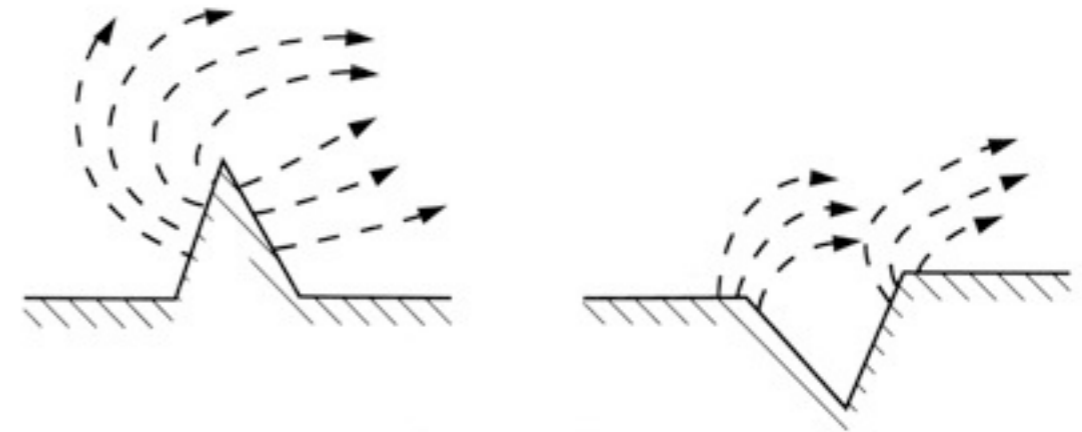
For small aperture  
And  
Large working distance



# Contrast Mechanisms



**Figure 7-16** Three dimensionality and contrast are due to the yield of secondary electrons from various parts of the specimen. Areas marked B face the beam and are in line of sight with the detector so that they will appear bright, I (intermediate brightness) faces the beam but fewer secondaries reach the detector since it is not in line of sight, D is dark in appearance since the beam does not strike this area and no secondaries are generated.



**Figure 7-18** The edge effect, or enhanced electron emission, occurs along the edges of thin raised areas since secondary electrons may exit from both sides of the structure.

# Secondary Electrons

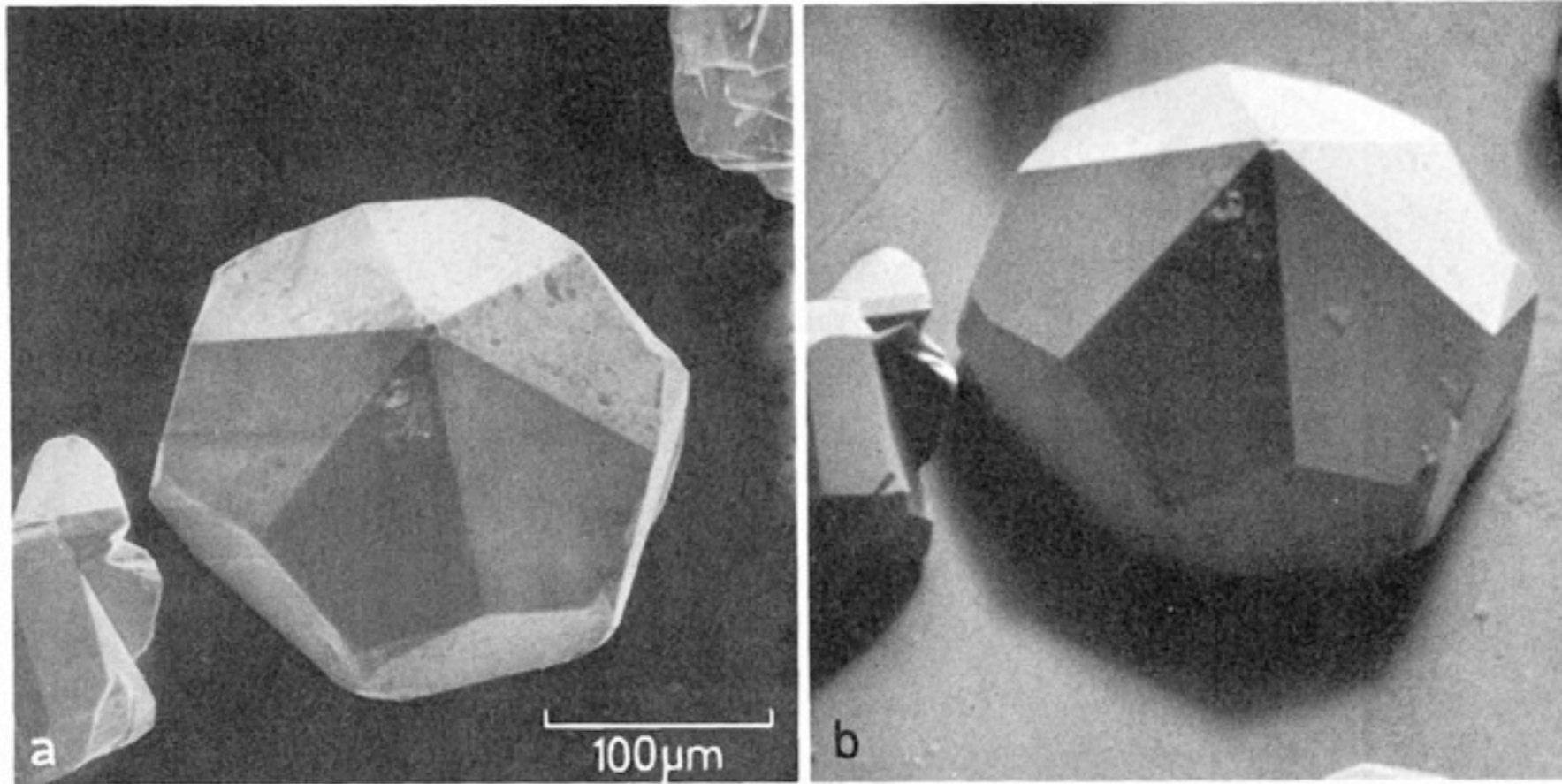


Fig. 6.5a, b

Fig. 6.5a, b. Illustration of the surface tilt and shadow contrast with micrographs of  $\text{Ge}_{38}\text{P}_8\text{I}_8$  crystals in the (a) SE and (b) BSE mode

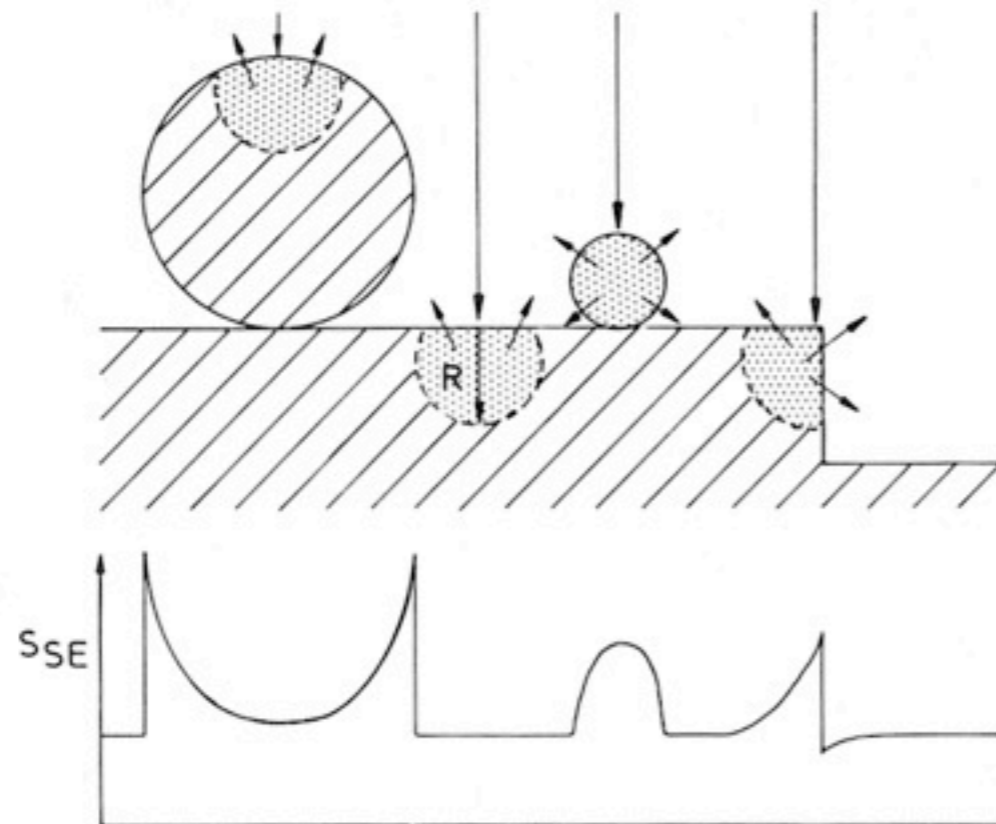
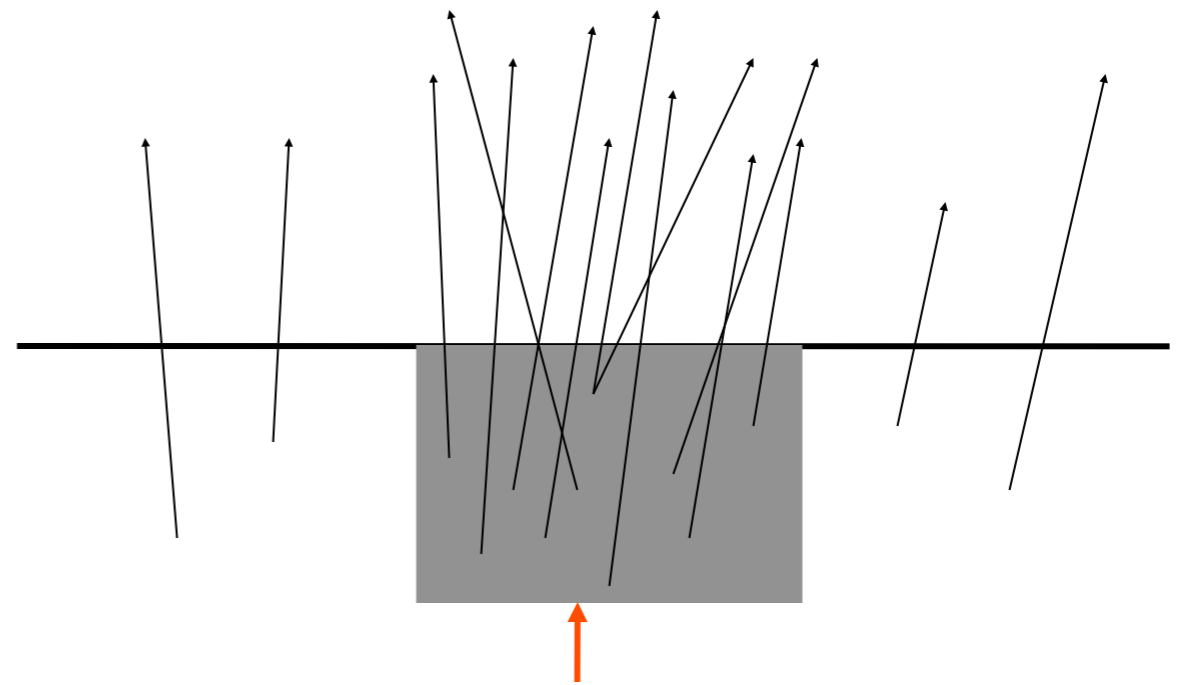
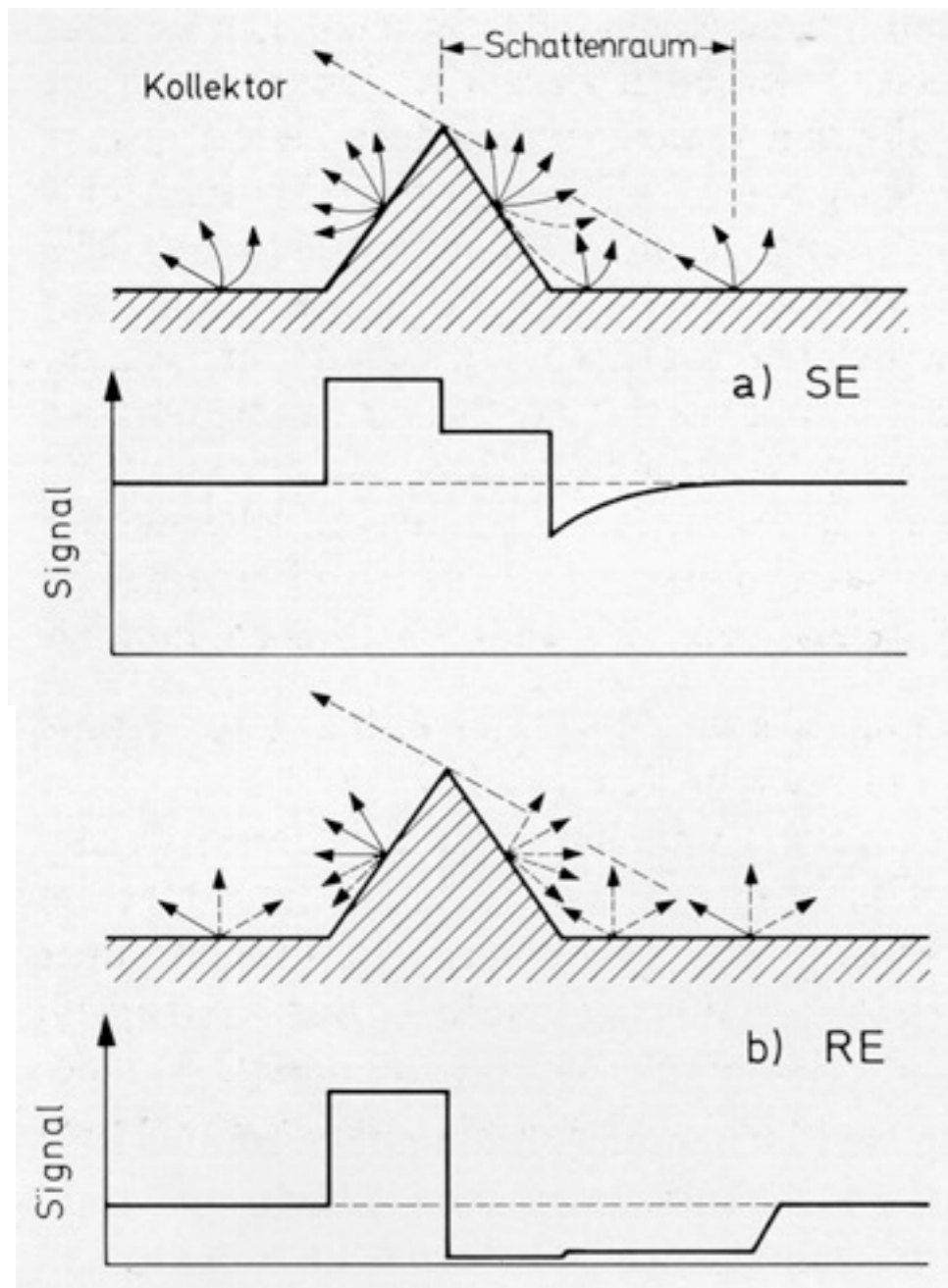


Fig. 6.6. SE signal intensity across spheres with diameters larger and smaller than the electron range  $R$  and increase of the SE signal at an edge caused by diffusion contrast

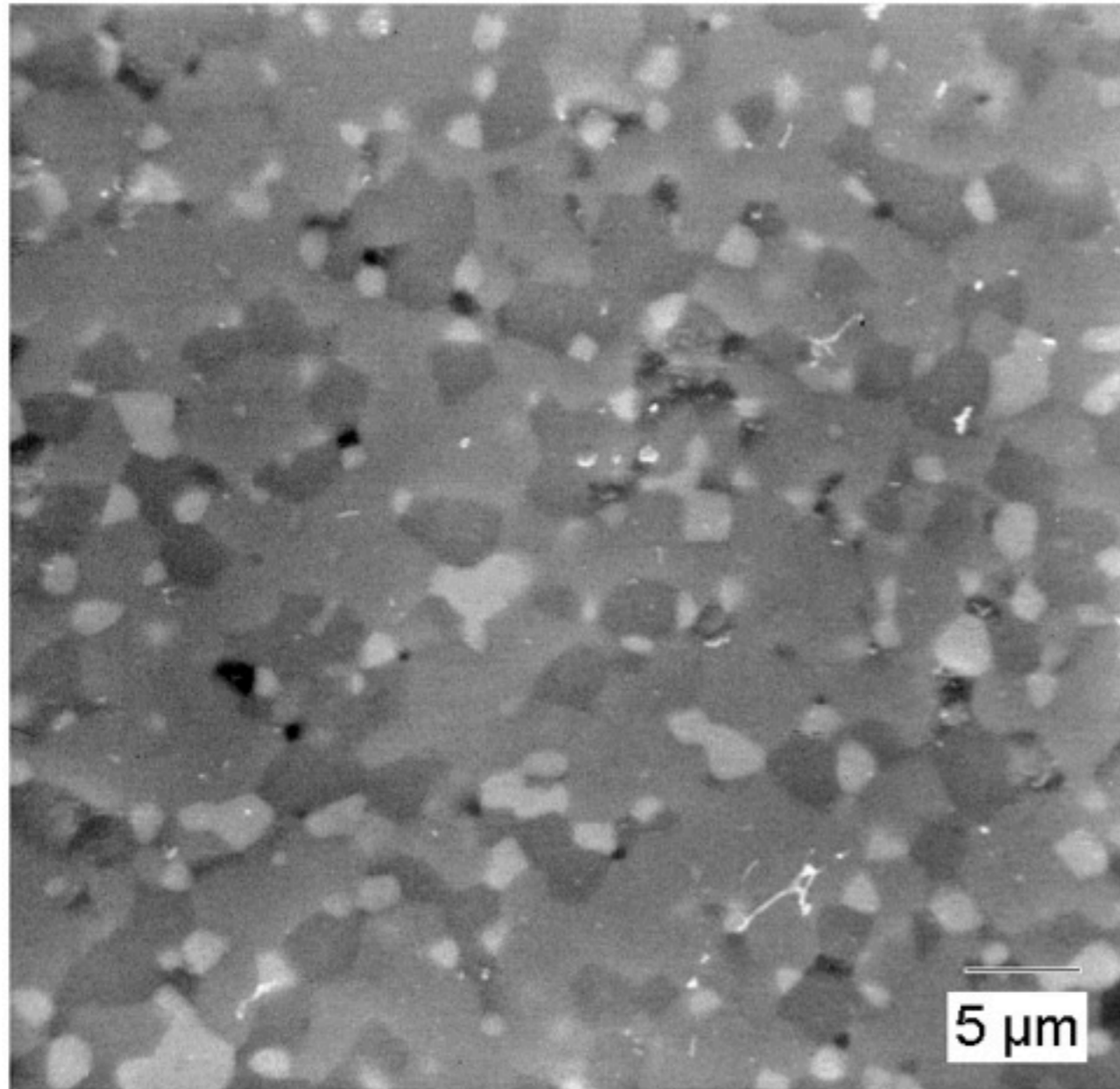




# Backscattered Electrons



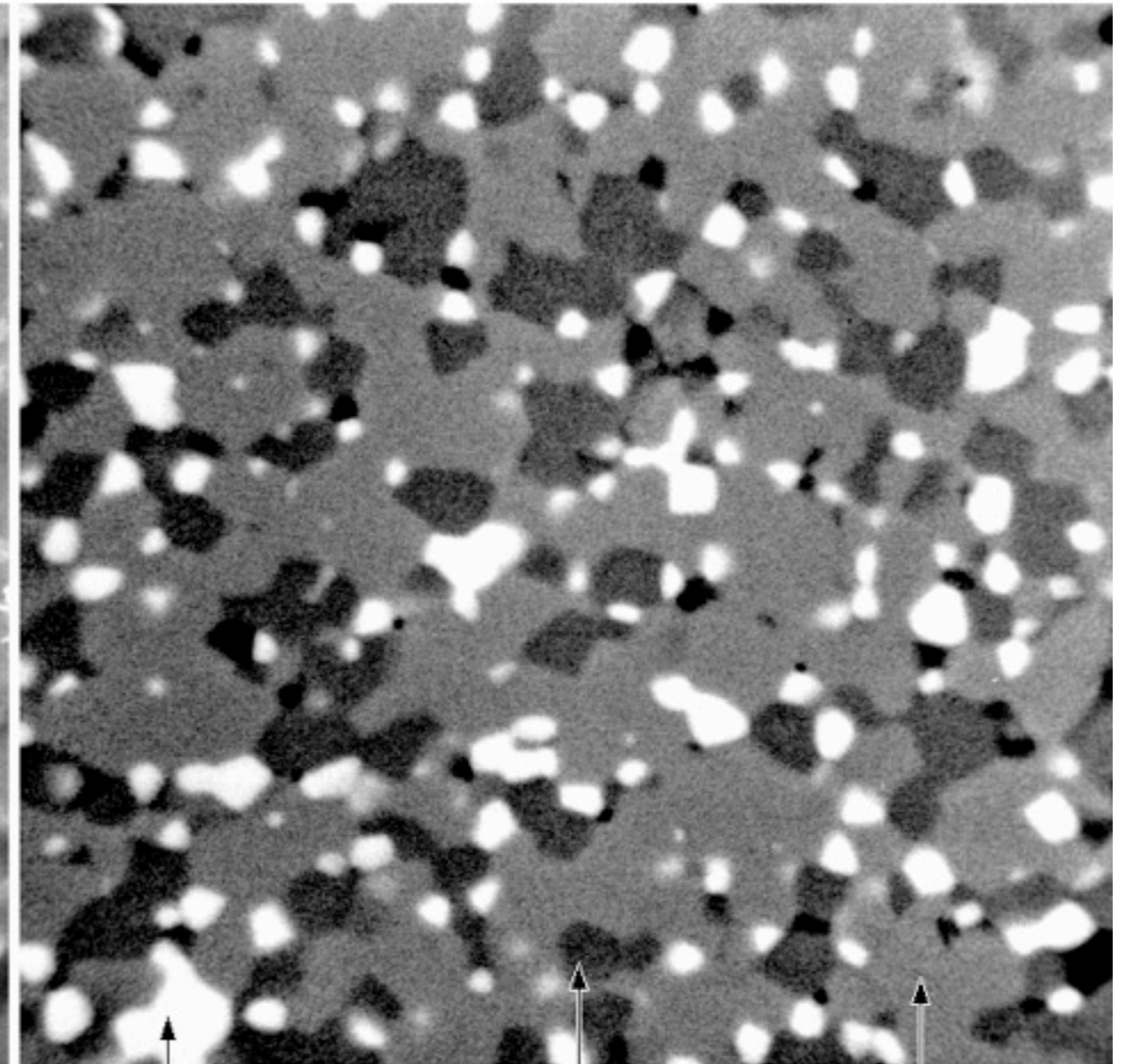
SE-Bild



Präparation: Anschliff

File: MgCaTi-Oxid

RE-Bild

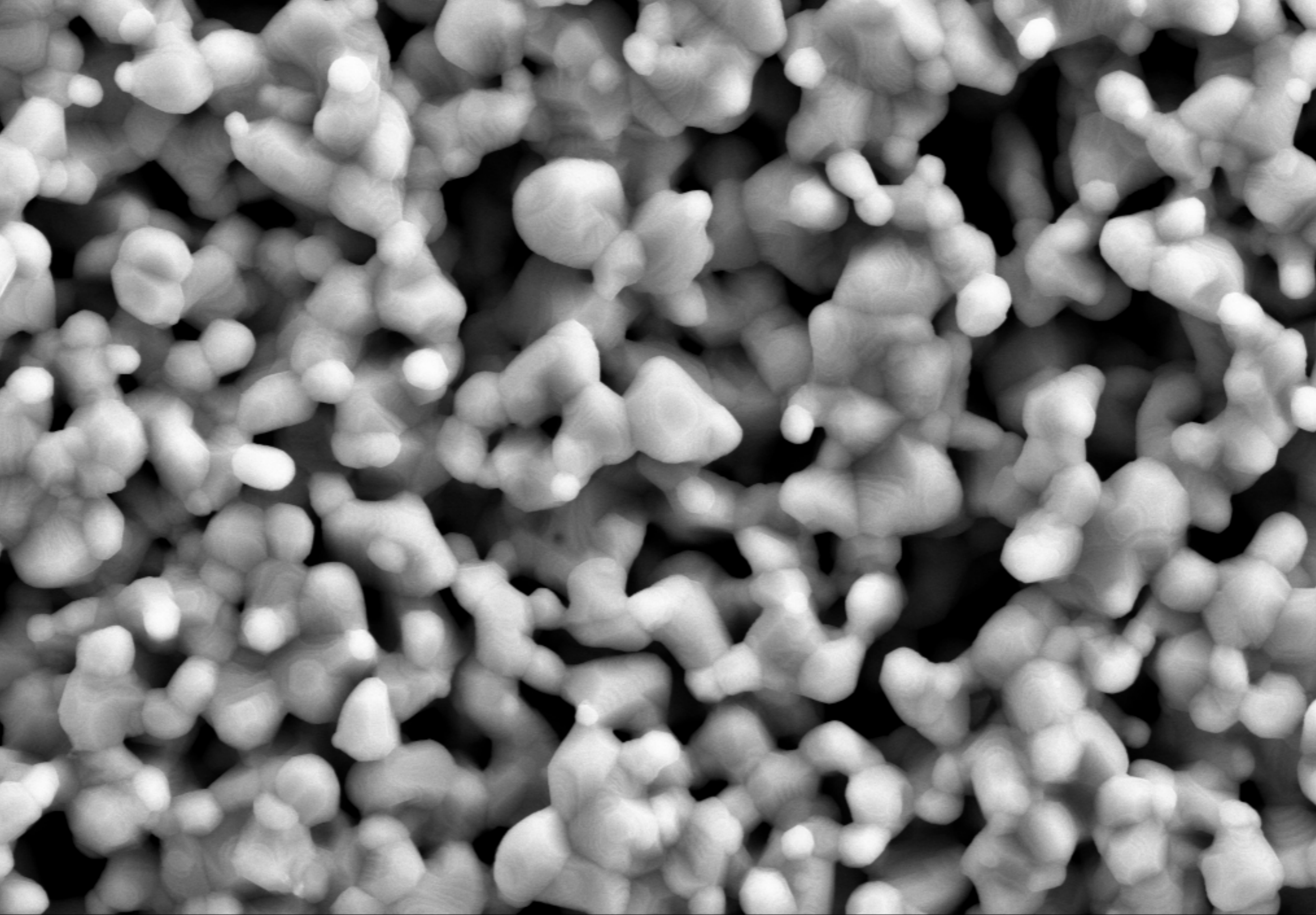


CaTiO<sub>3</sub>

Mg<sub>2</sub>TiO<sub>4</sub>

MgTiO<sub>3</sub>

# Accelerating Voltage



2μm

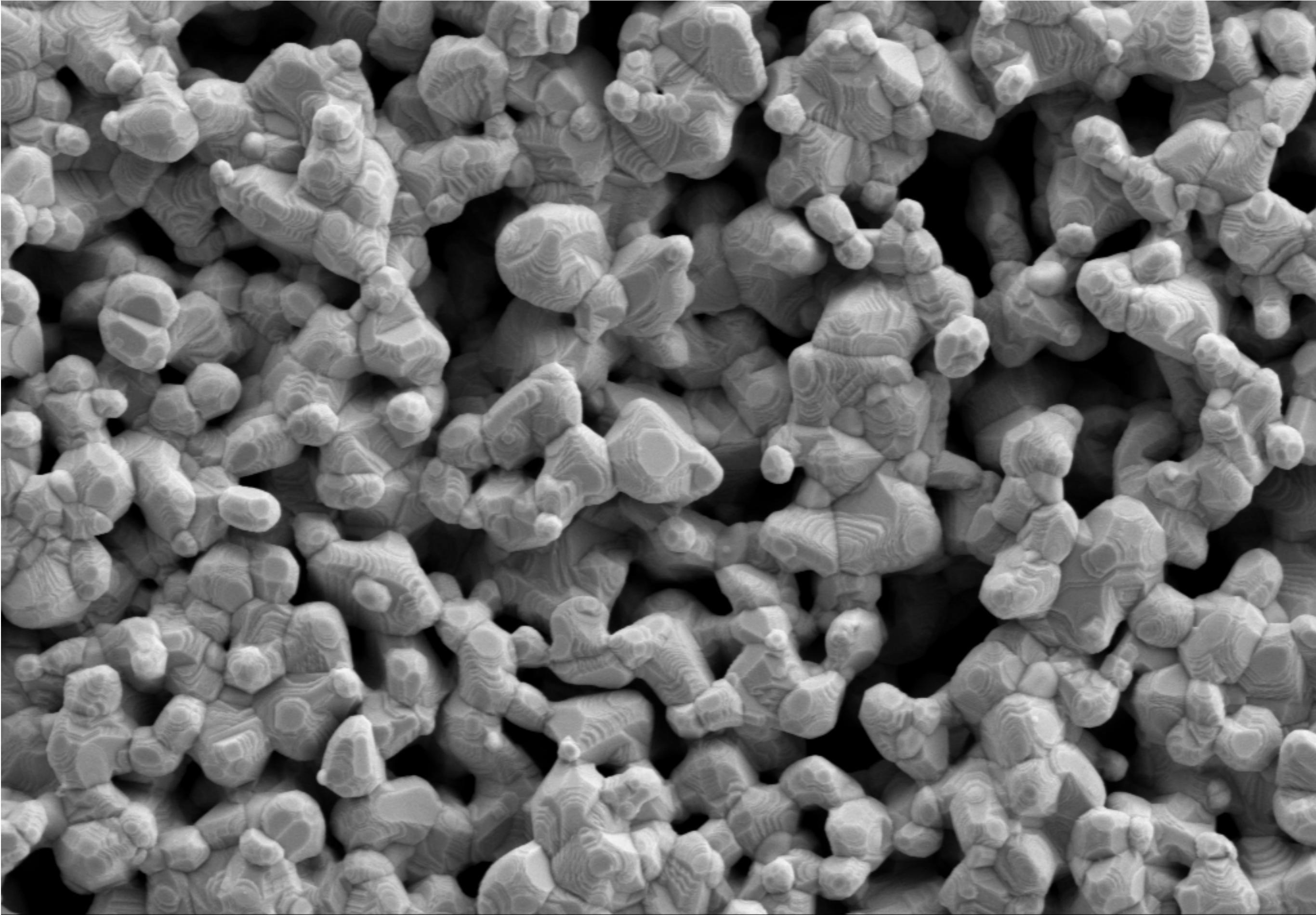


Signal A = SE2

EHT = 15.00 kV

WD = 7 mm



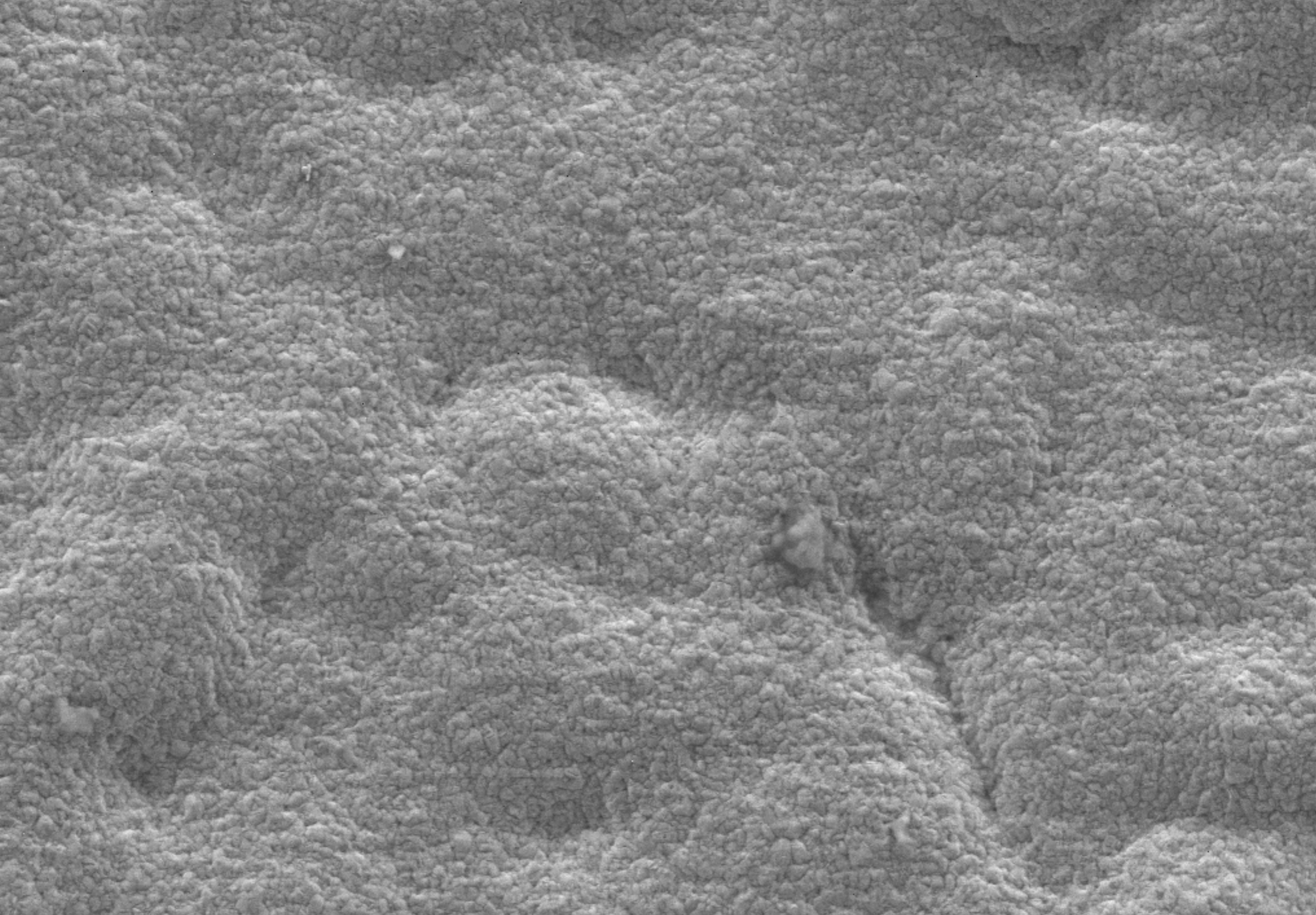


2  $\mu$ m

Signal A = SE2

EHT = 5.00 kV

WD = 7 mm



10µm

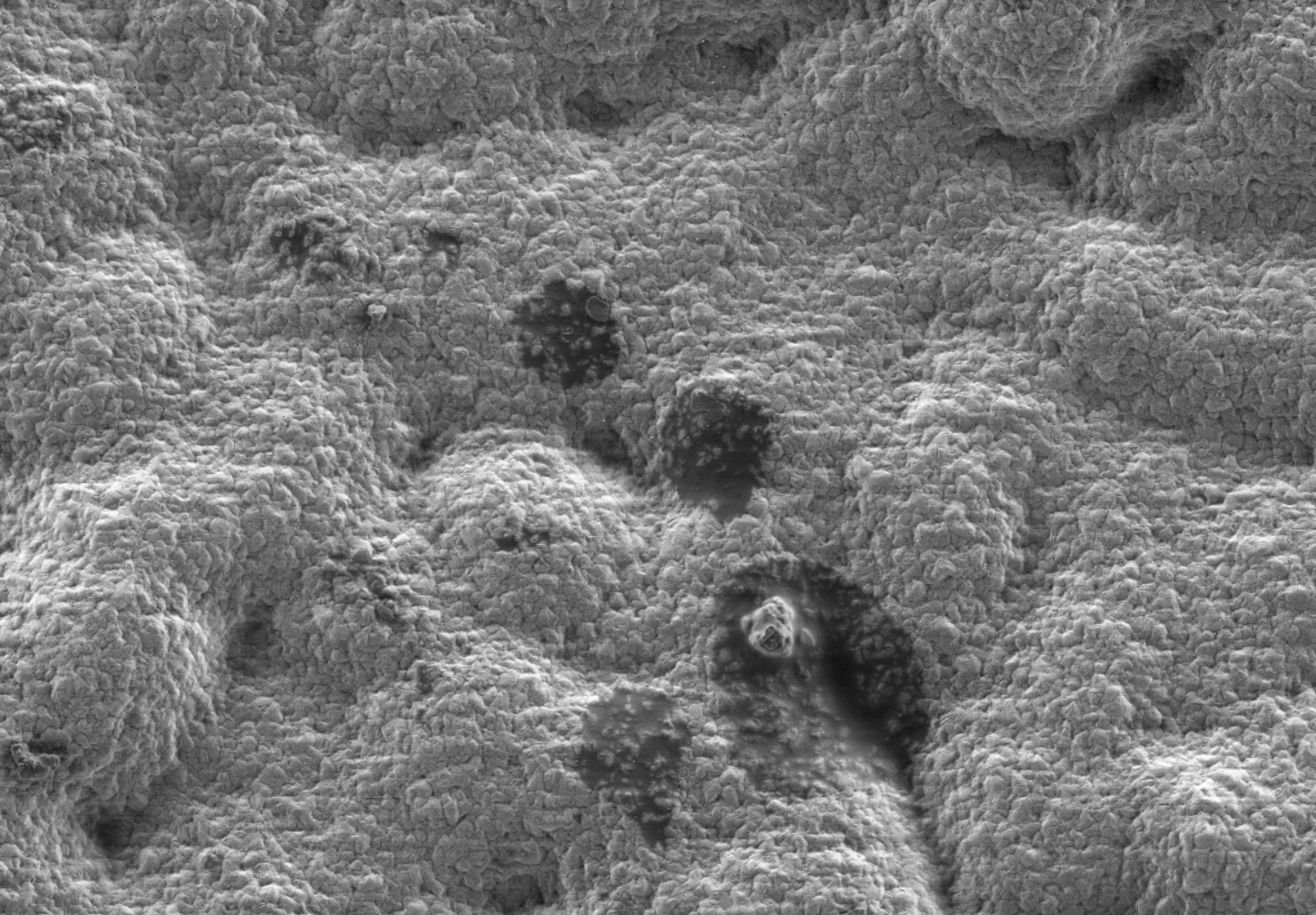


Signal A = SE2

EHT = 10.00 kV

WD = 3 mm





10µm

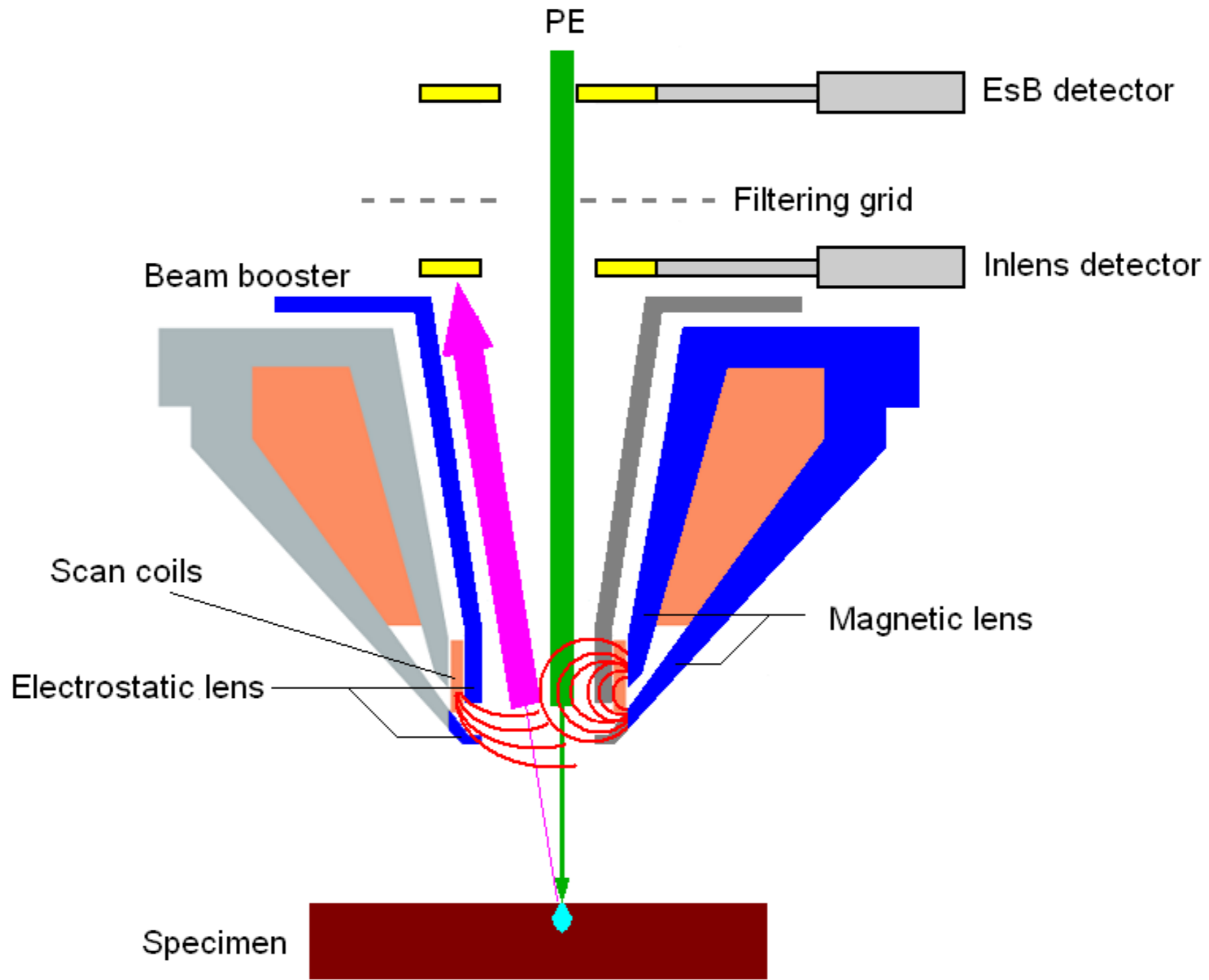


Signal A = SE2

EHT = 1.00 kV

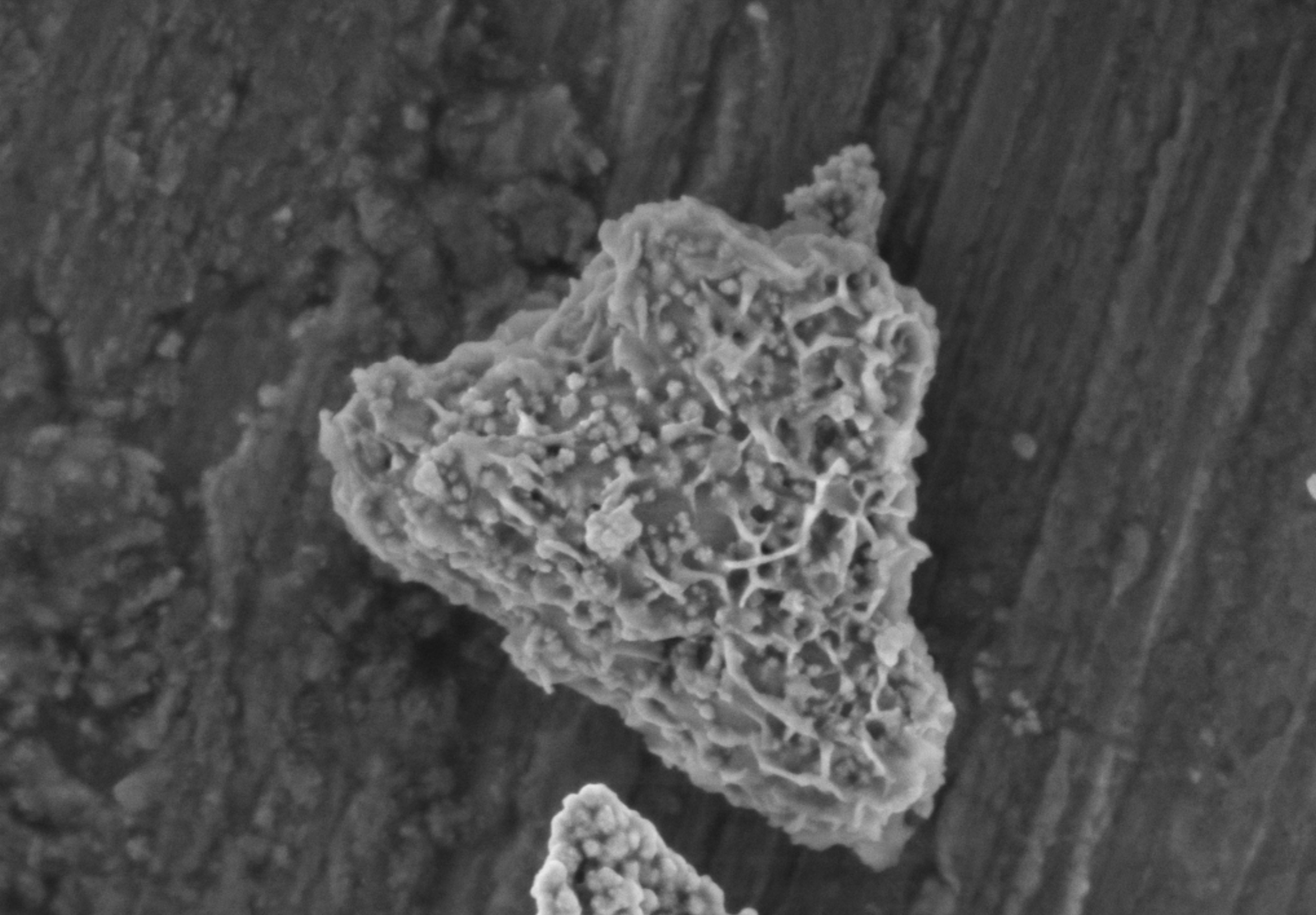
WD = 3 mm

# Detectors



# In-lense Detector





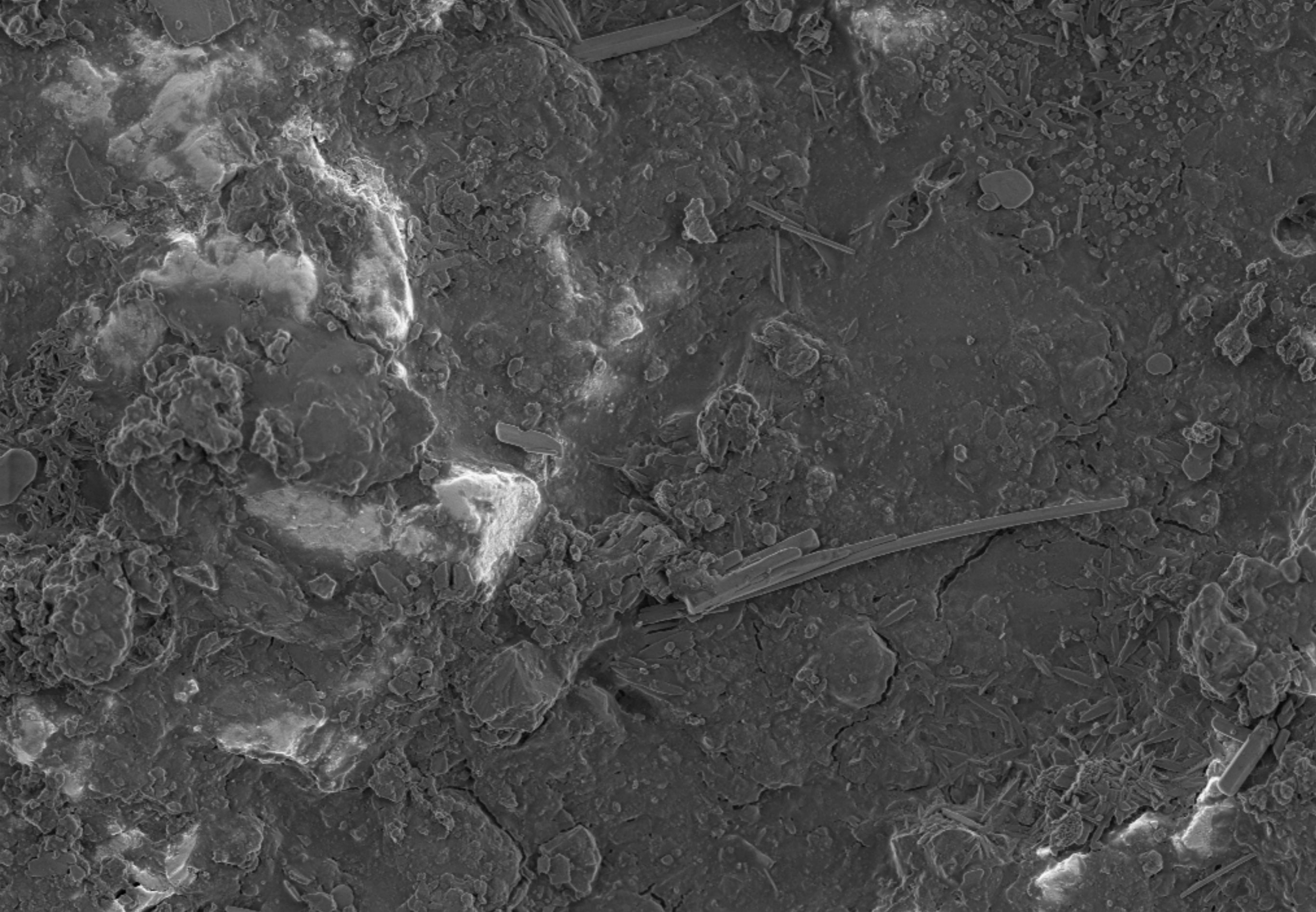
200nm



Signal A = InLens

EHT = 1.50 kV

WD = 3 mm



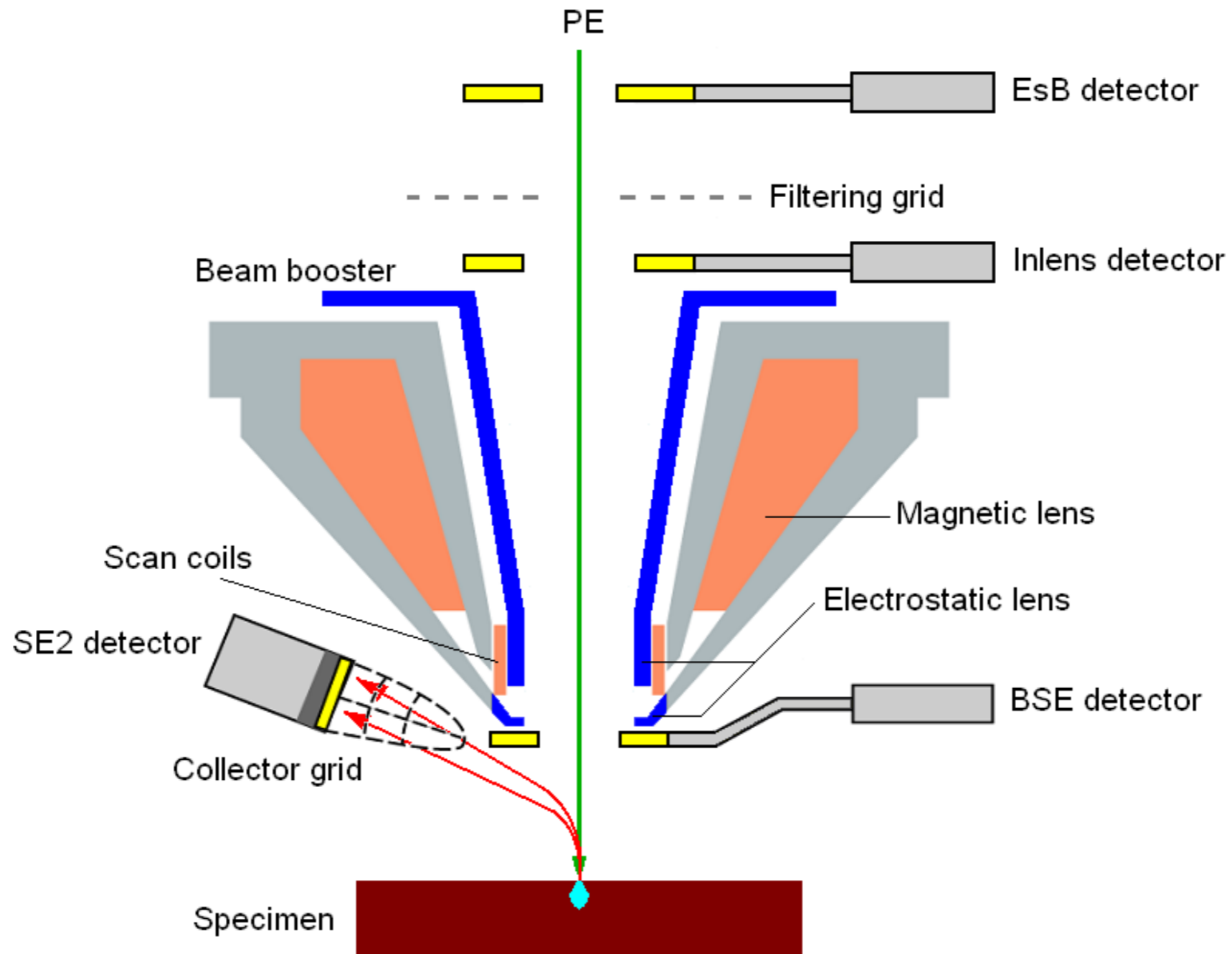
2 $\mu$ m  
|-----|

Signal A = InLens

EHT = 0.80 kV

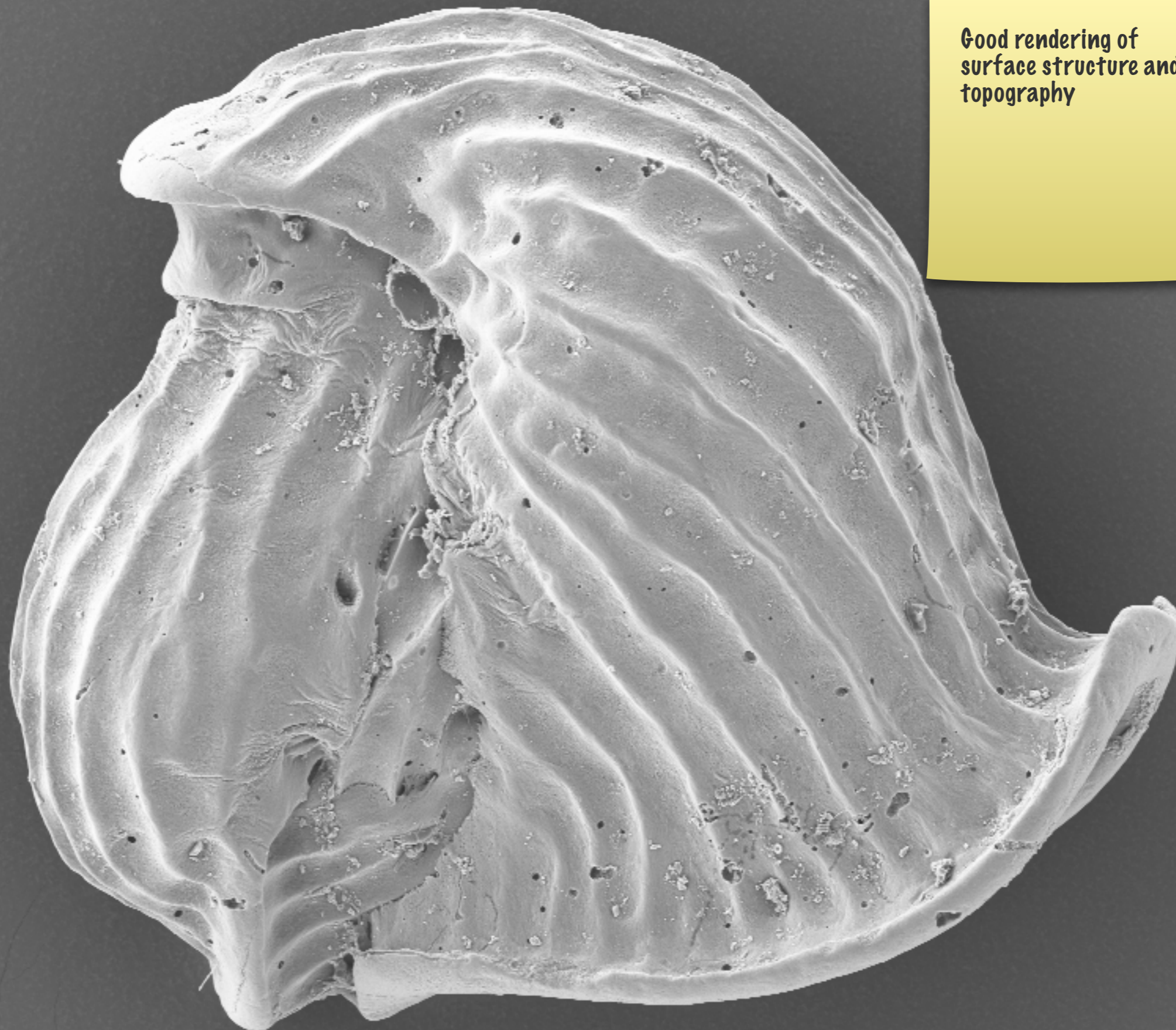
WD = 3 mm





# Everhart-Thornley Detector

Good rendering of  
surface structure and  
topography



100µm

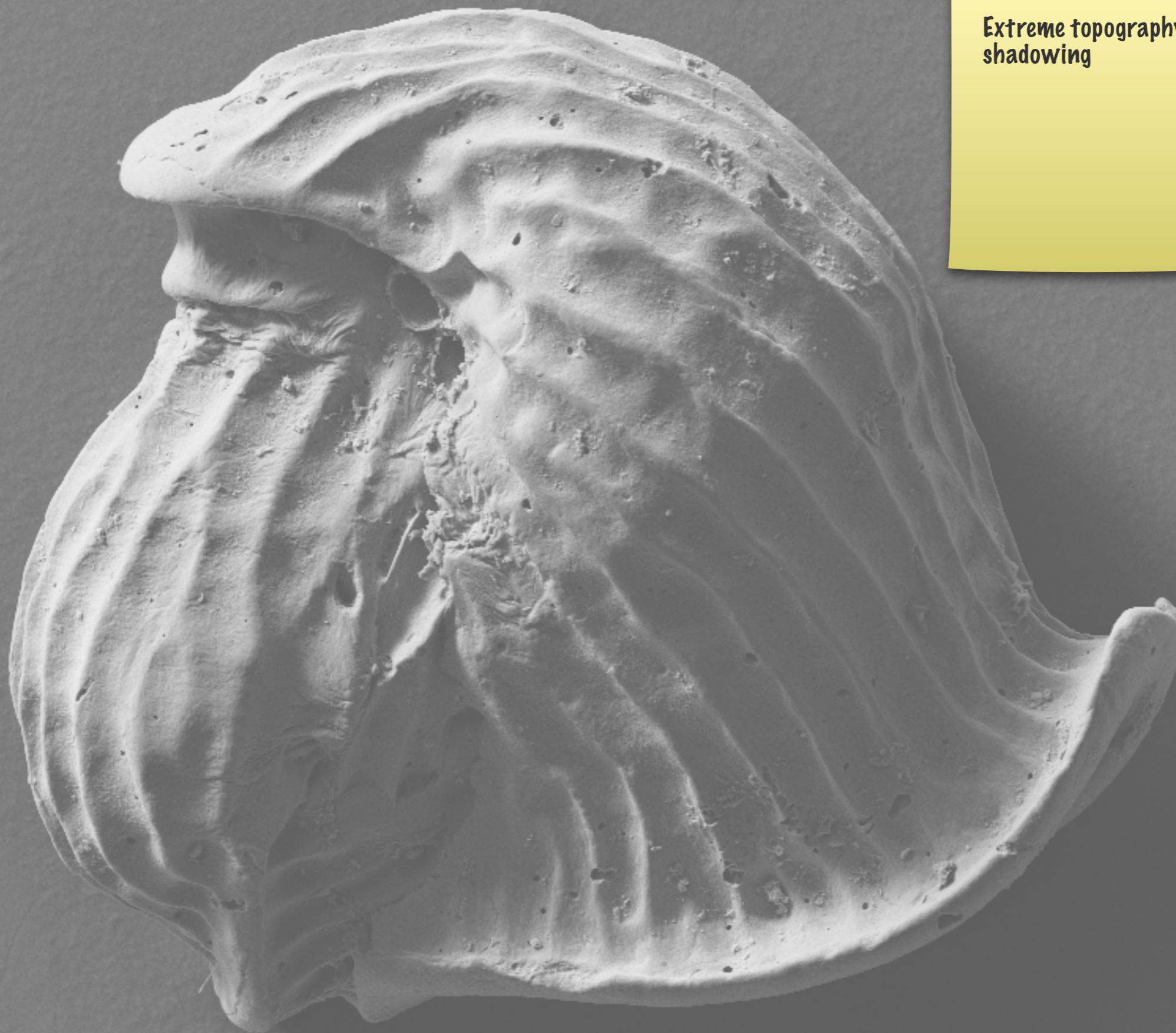
Signal A = SE2

EHT = 10.00 kV

WD = 11 mm



Extreme topography and shadowing

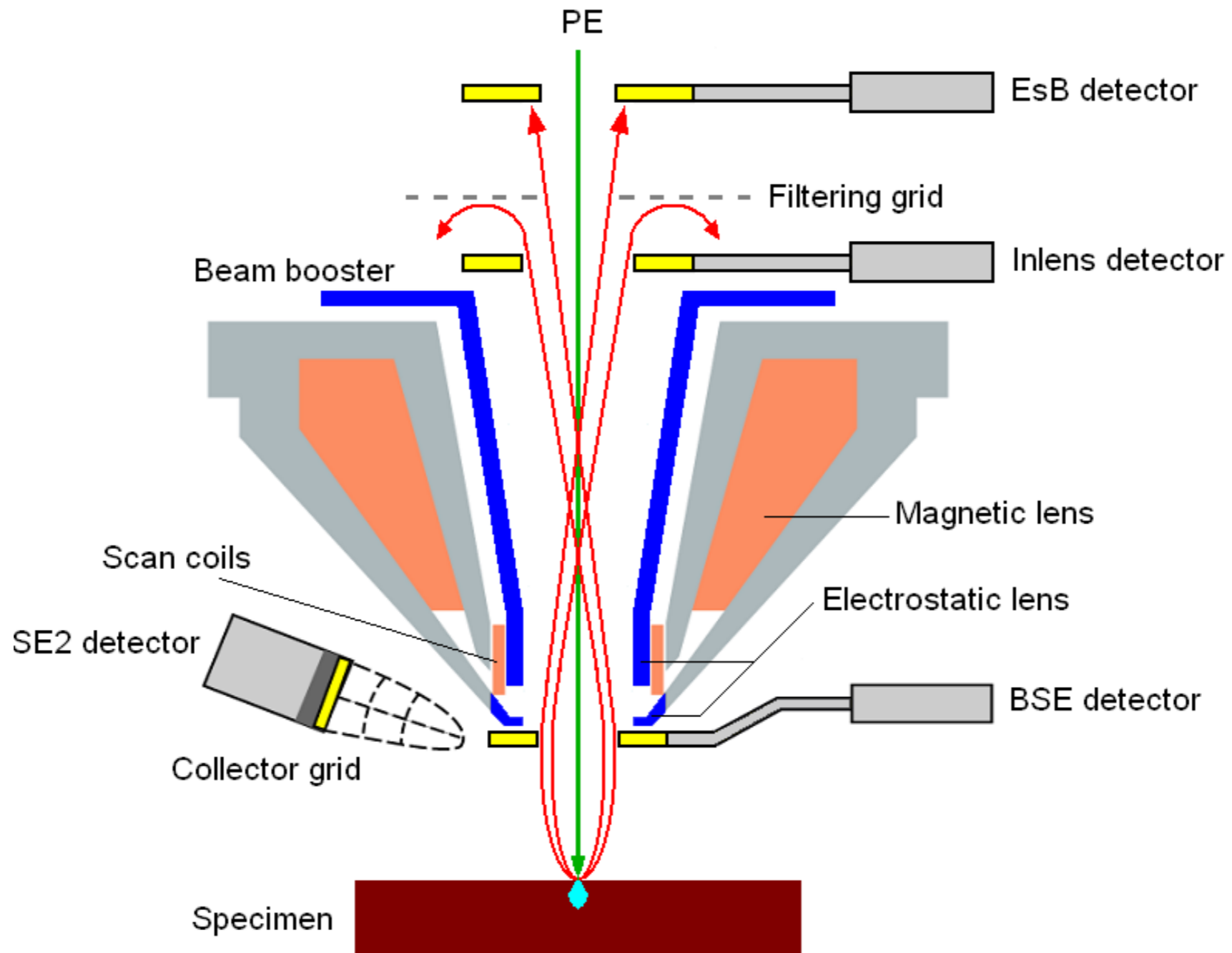


100µm

Signal A = SE2

EHT = 10.00 kV

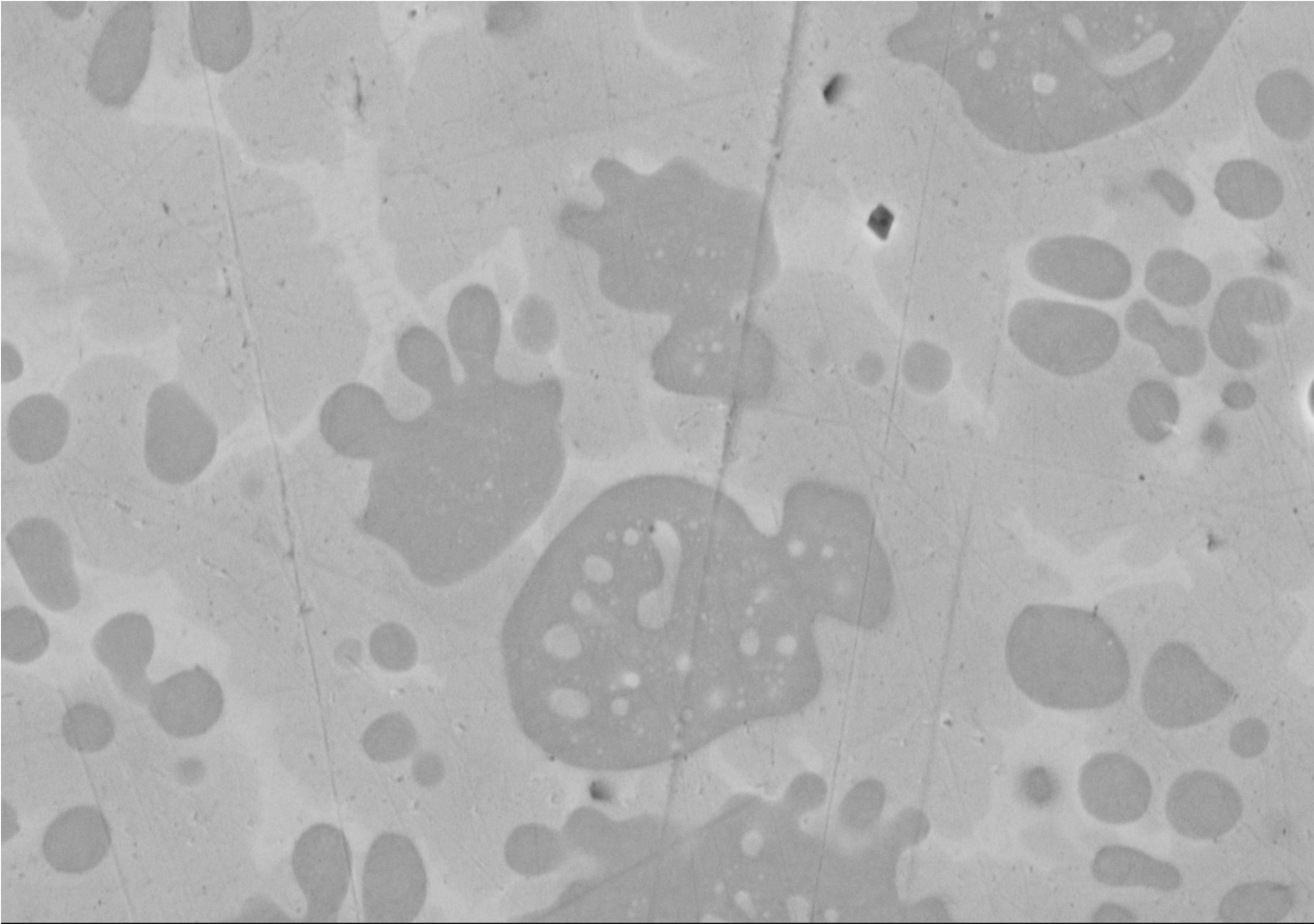
WD = 11 mm



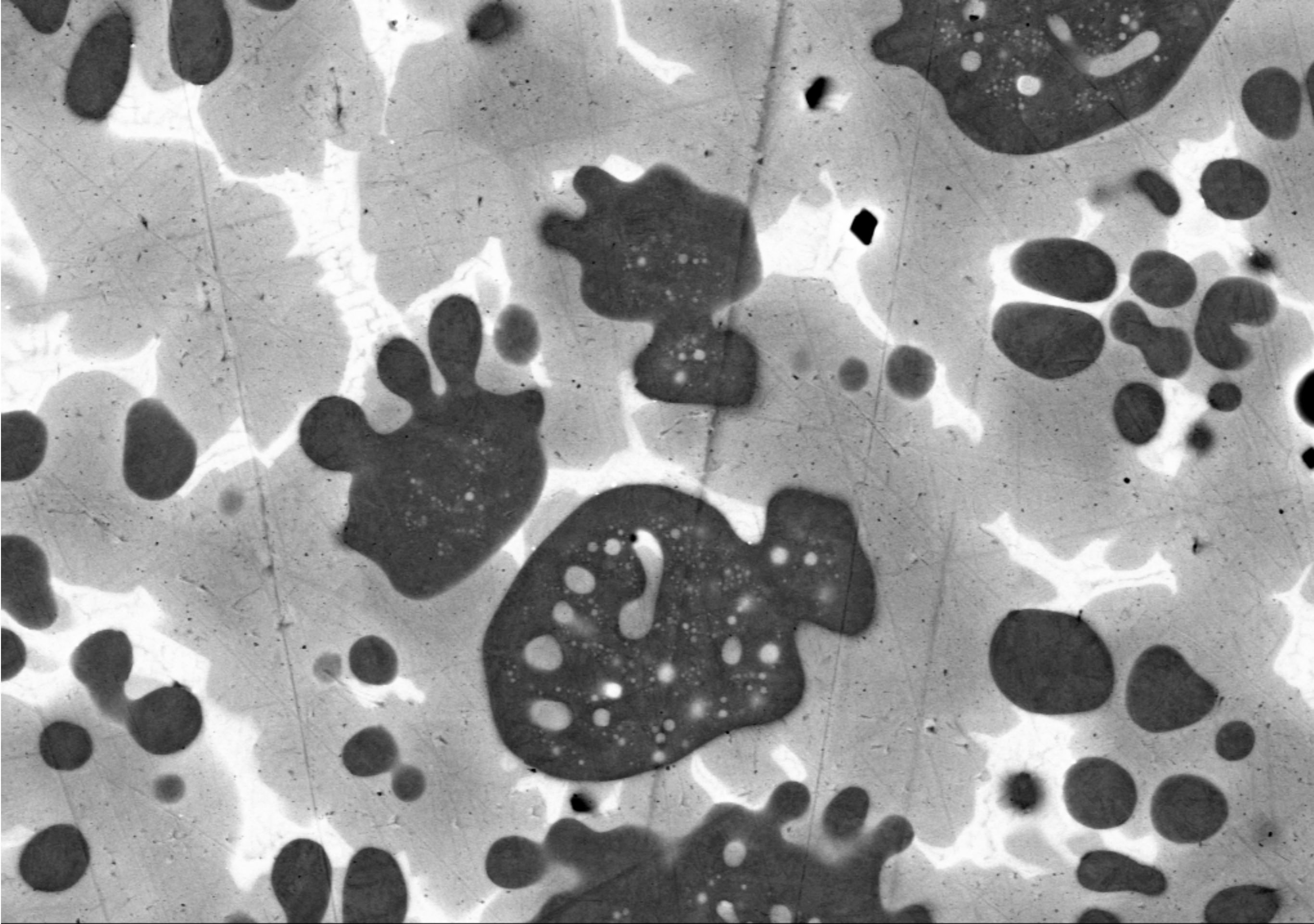
# ESB Detector

*Energy and angle selective BSE*

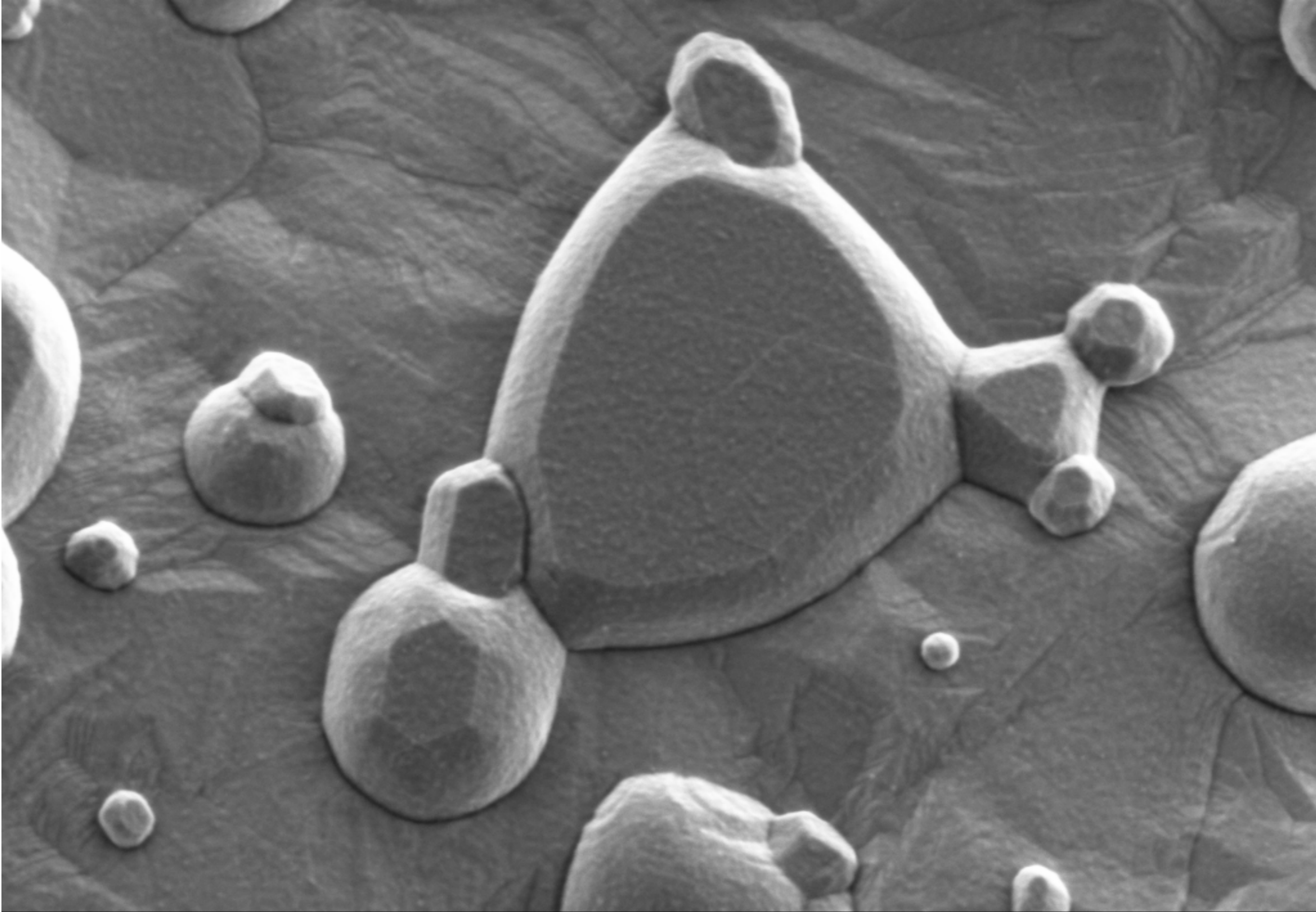




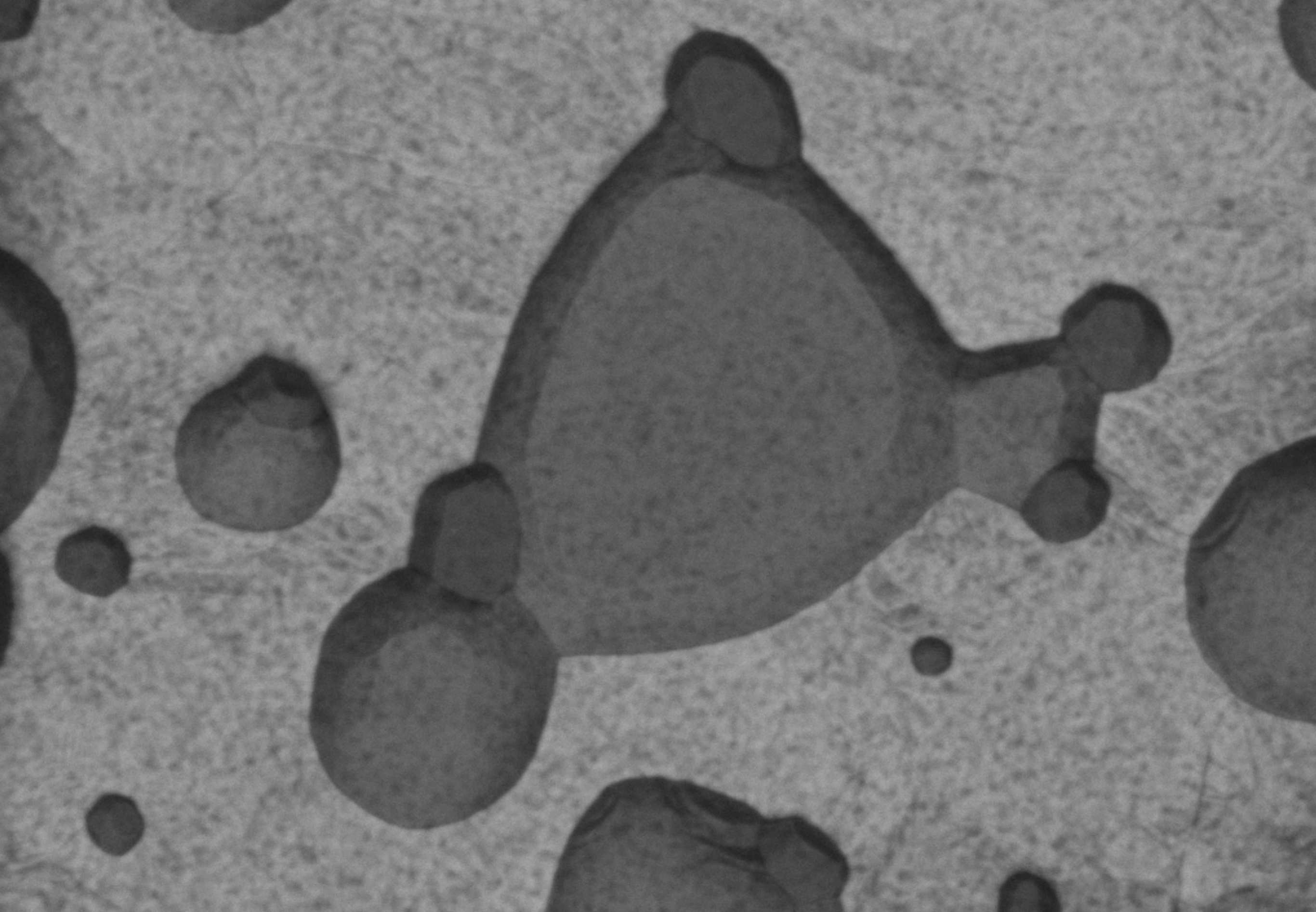
2 $\mu$ m  
EHT = 15.00 kV      WD = 5 mm      Signal A = SE2







1  $\mu$ m      Signal A = InLens      EHT = 1.00 kV      WD = 2 mm



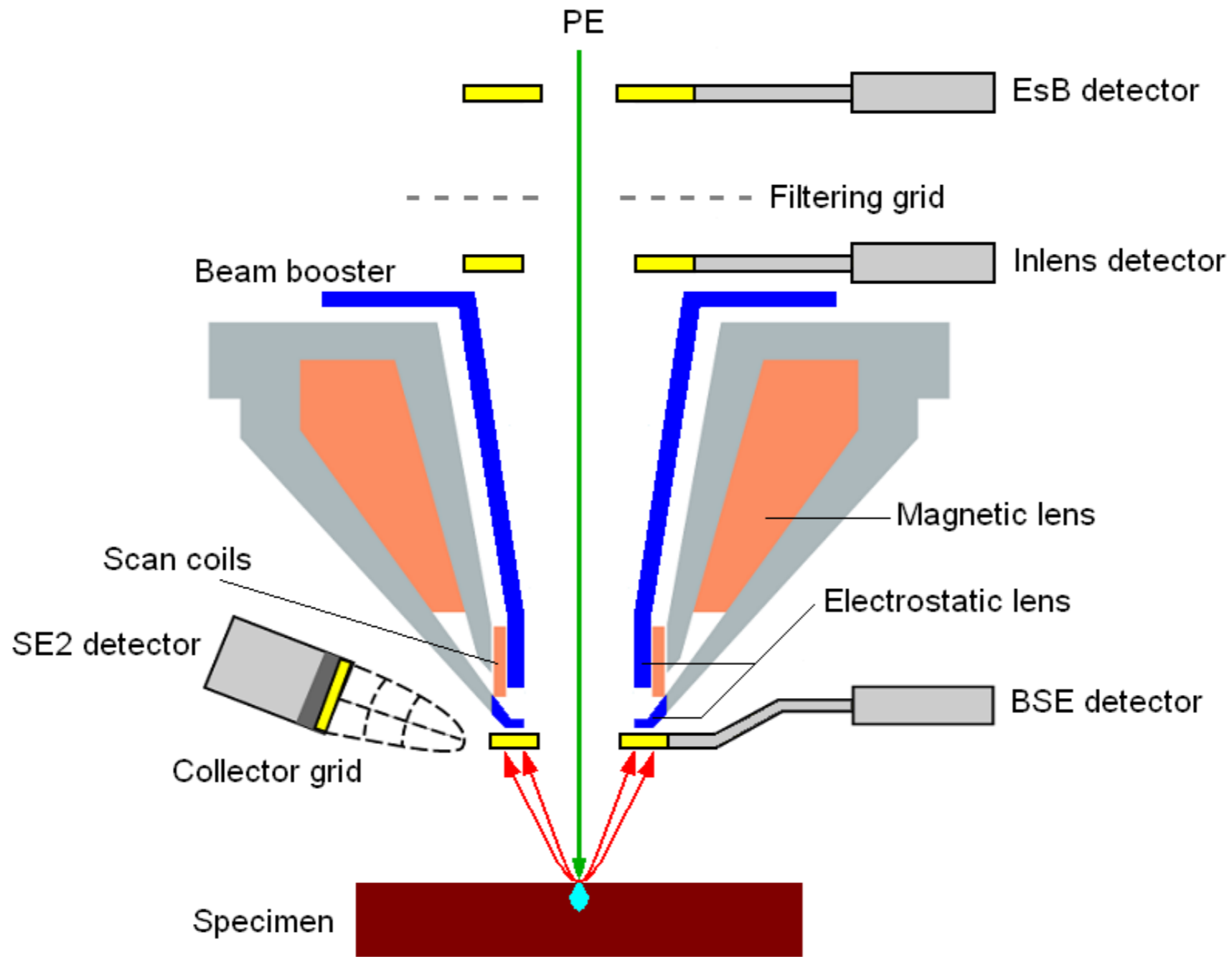
1  $\mu$ m



Signal A = ESB

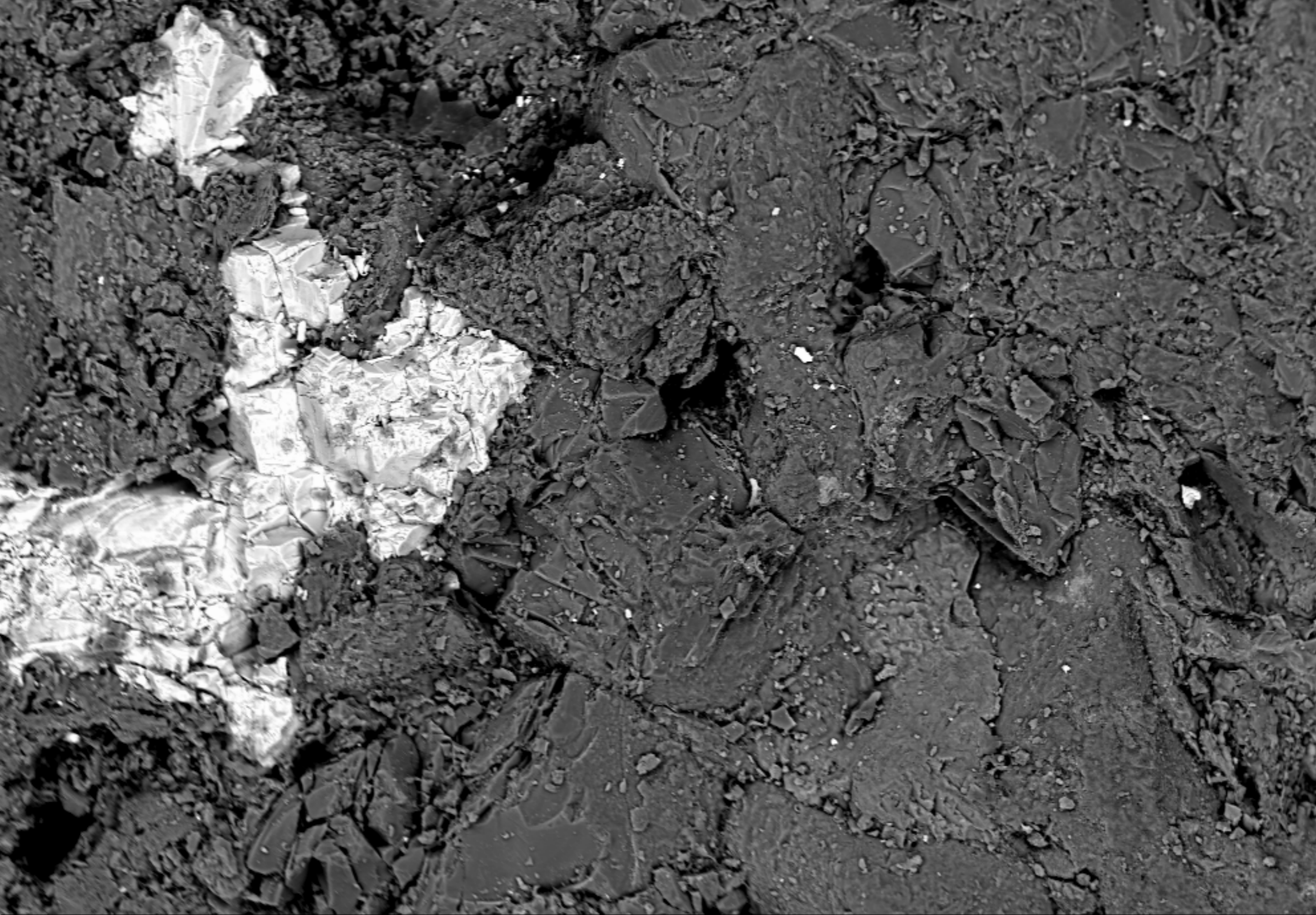
EHT = 1.00 kV

WD = 2 mm



# BSE Detector





100µm

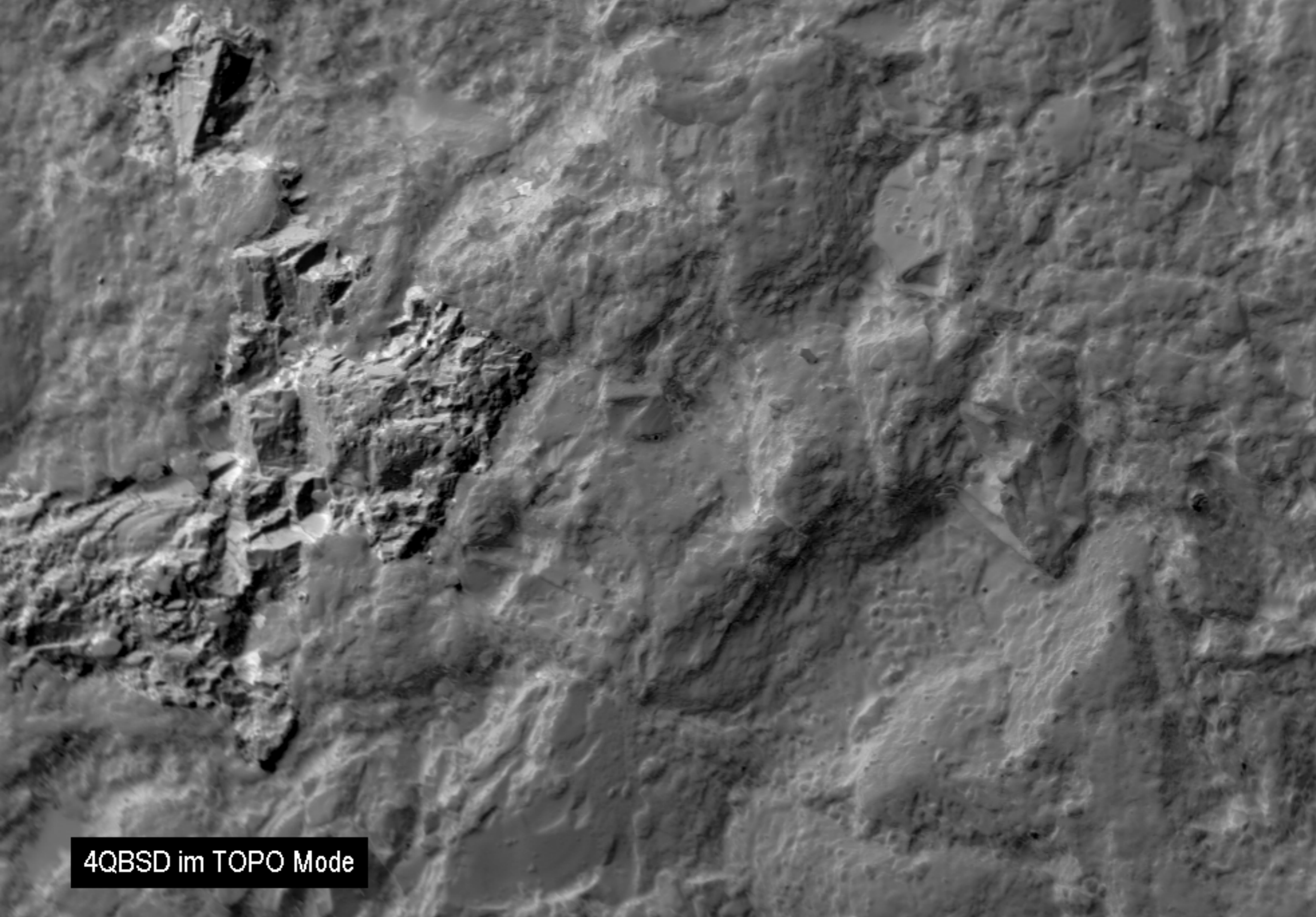


Signal A = QBSD

EHT = 20.00 kV

WD = 10 mm





4QBSD im TOPO Mode

100µm

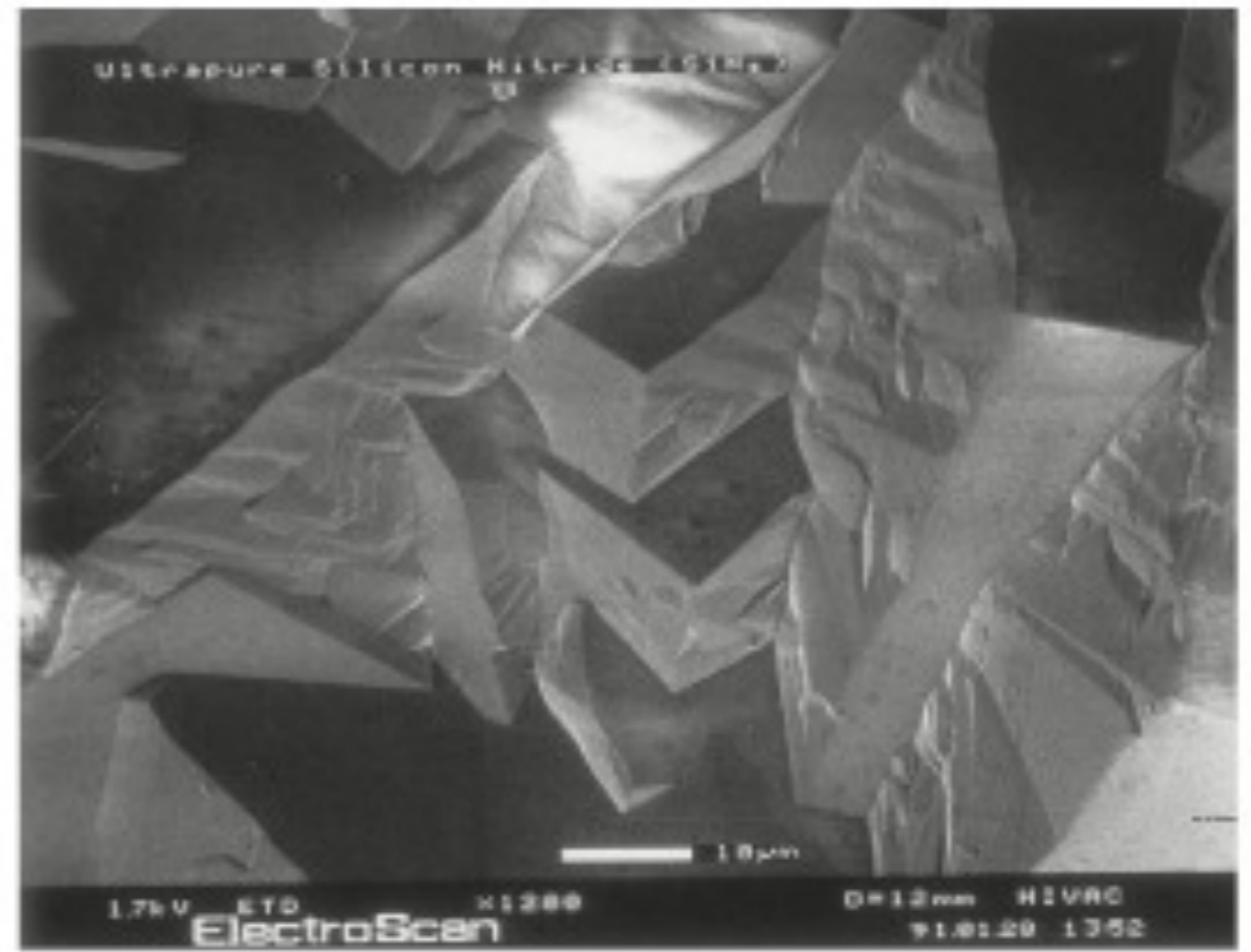
Signal A = QBSD

EHT = 20.00 kV

WD = 10 mm



# Suitable Samples



# Charging Effects





HUMMER II

SPUTTERING SYSTEM



PROCESS SELECT

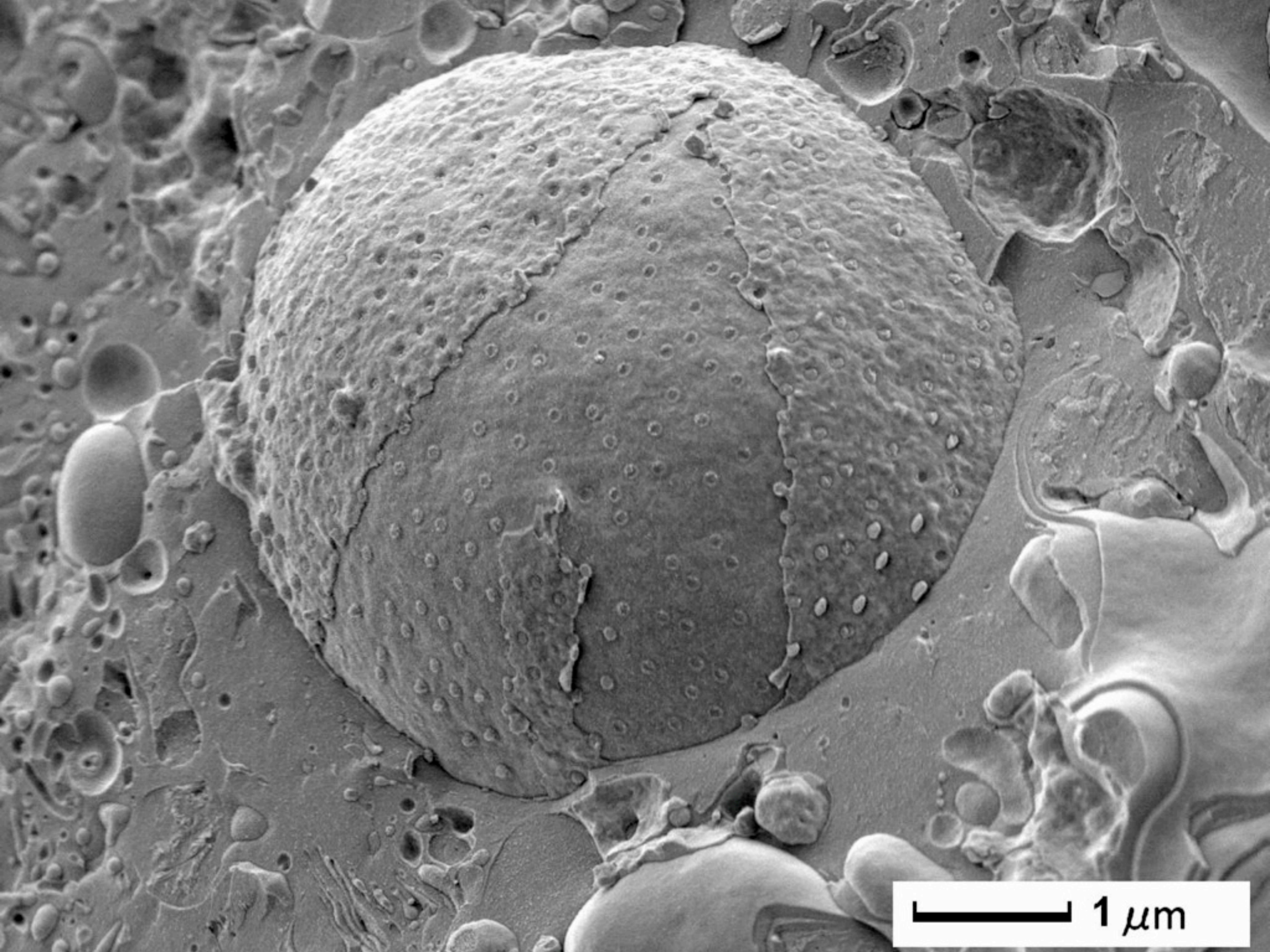
10  
11  
12



# Special SEM

**Cryo-SEM**

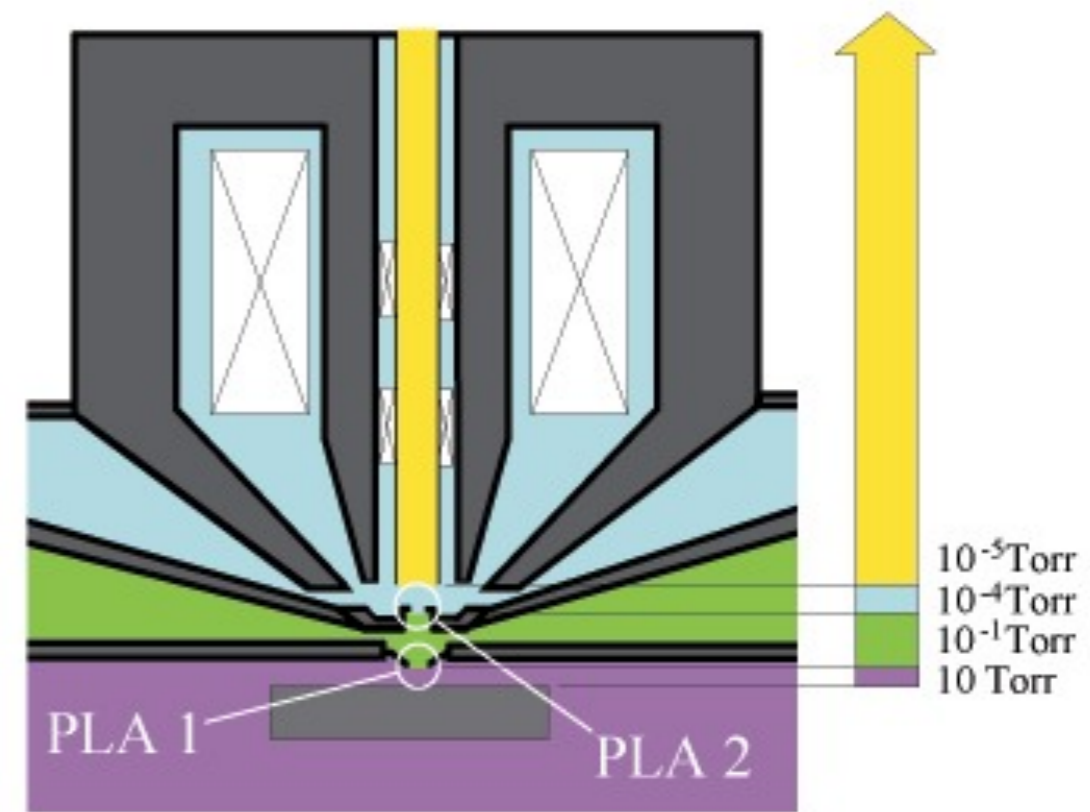
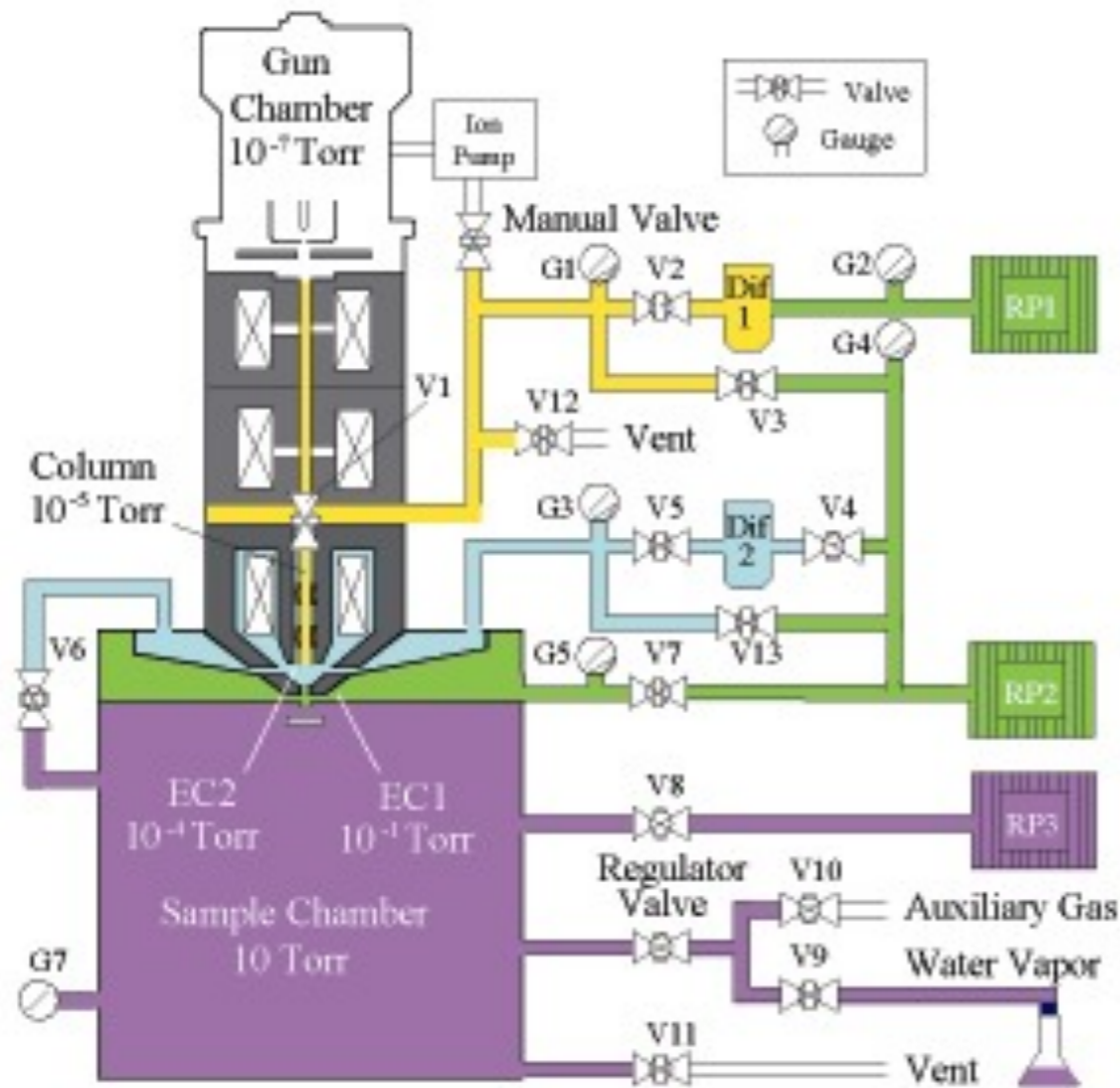




1 μm

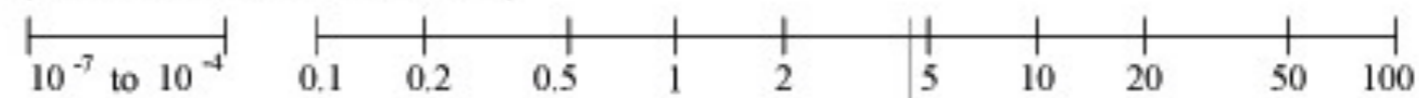
# Environmental SEM





### Vacuum in Torr

(1 Torr = 133 Pascal = 1.33 mBar)



ESEM

SE and BSE

Secondary and Backscattered Electron Imaging

LV-CSEM

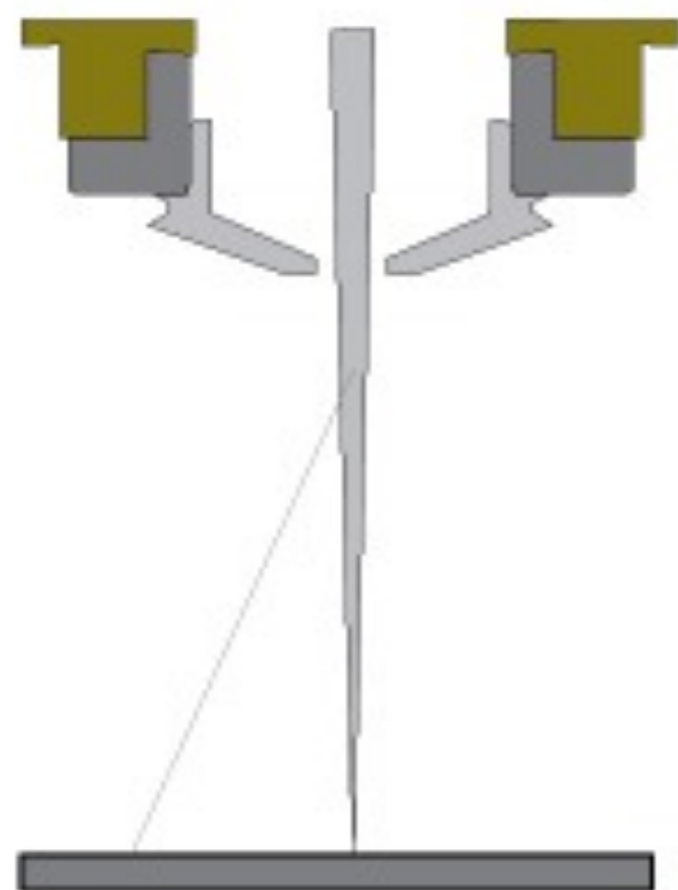
SE and BSE

Backscattered Imaging Only

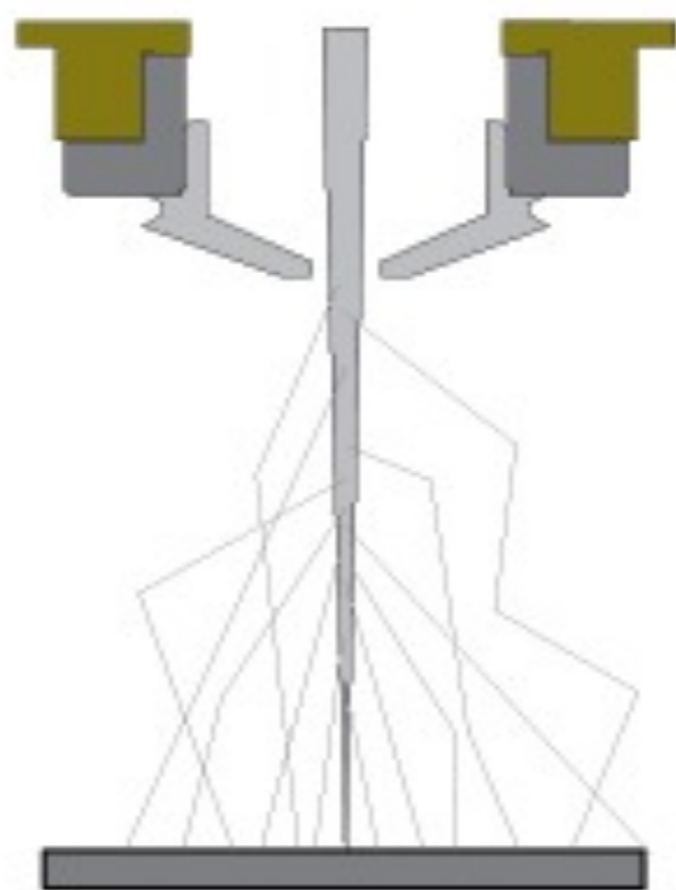
CSEM

SE and BSE

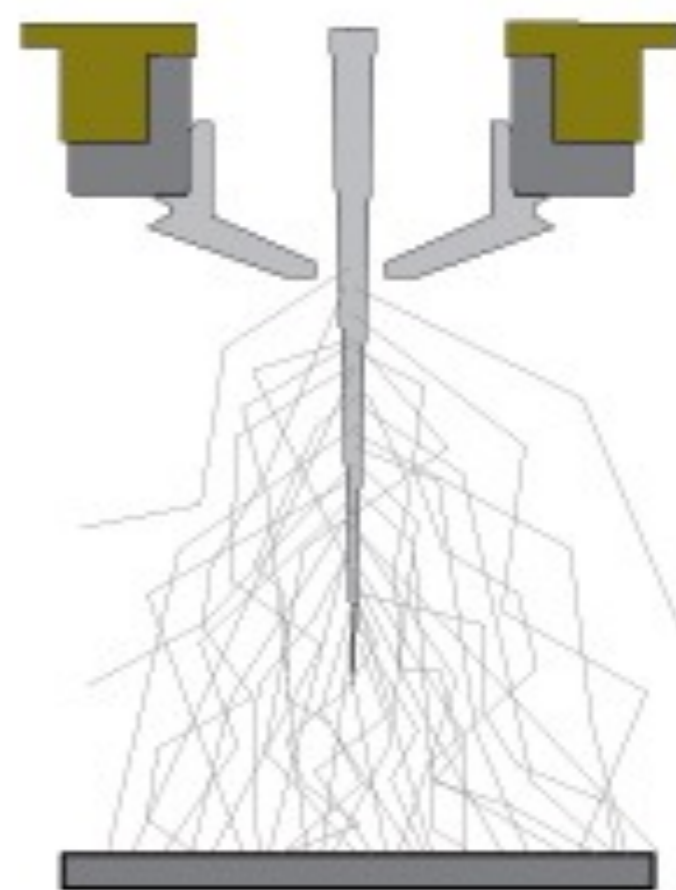
4.6 Torr  
(minimum for liquid water)



**Minimal Scattering**  
Scatter  $< 5\%$   
 $m < 0.05$



**Partial Scattering**  
5% to 95% Scatter  
 $m$  from  $= 0.05$  to  $3.0$



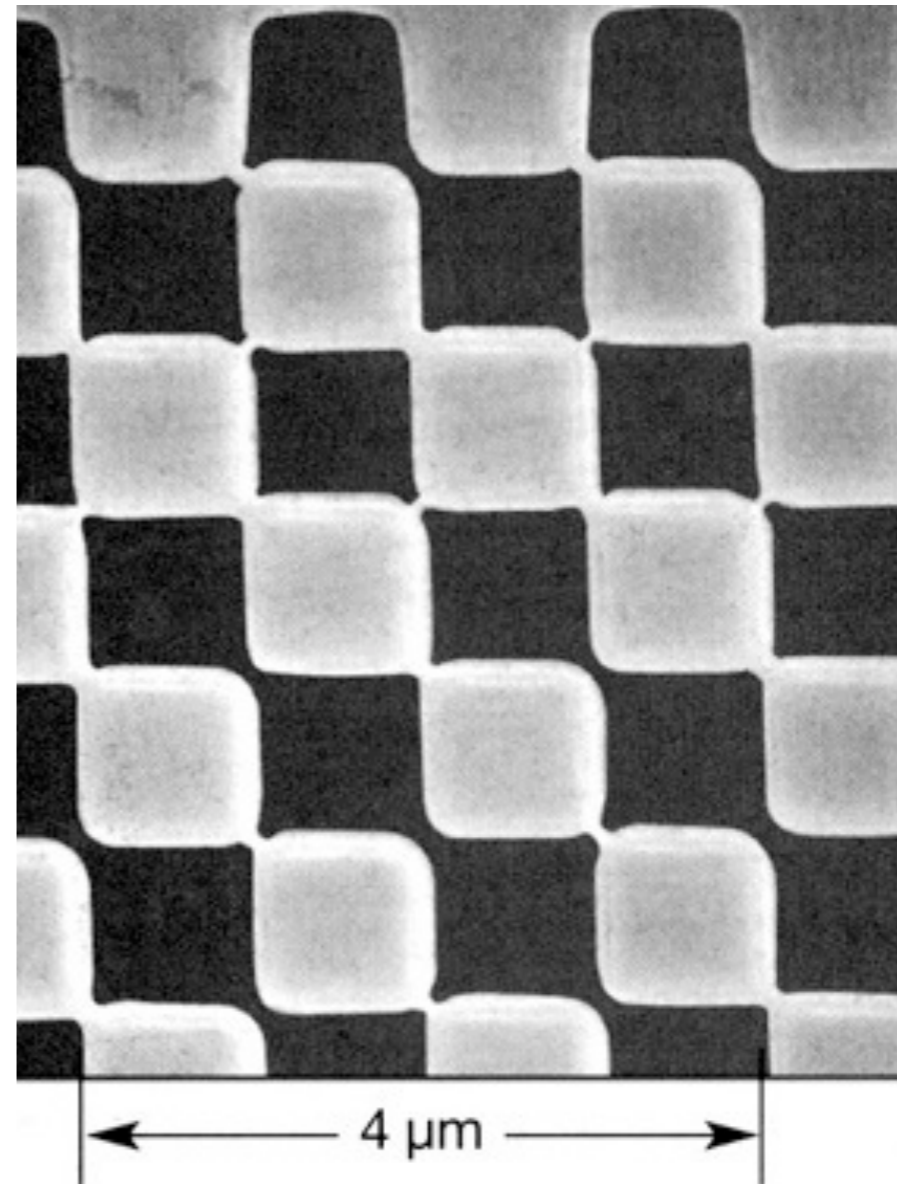
**Complete Scattering**  
Scatter  $> 95\%$   
 $m > 3.0$

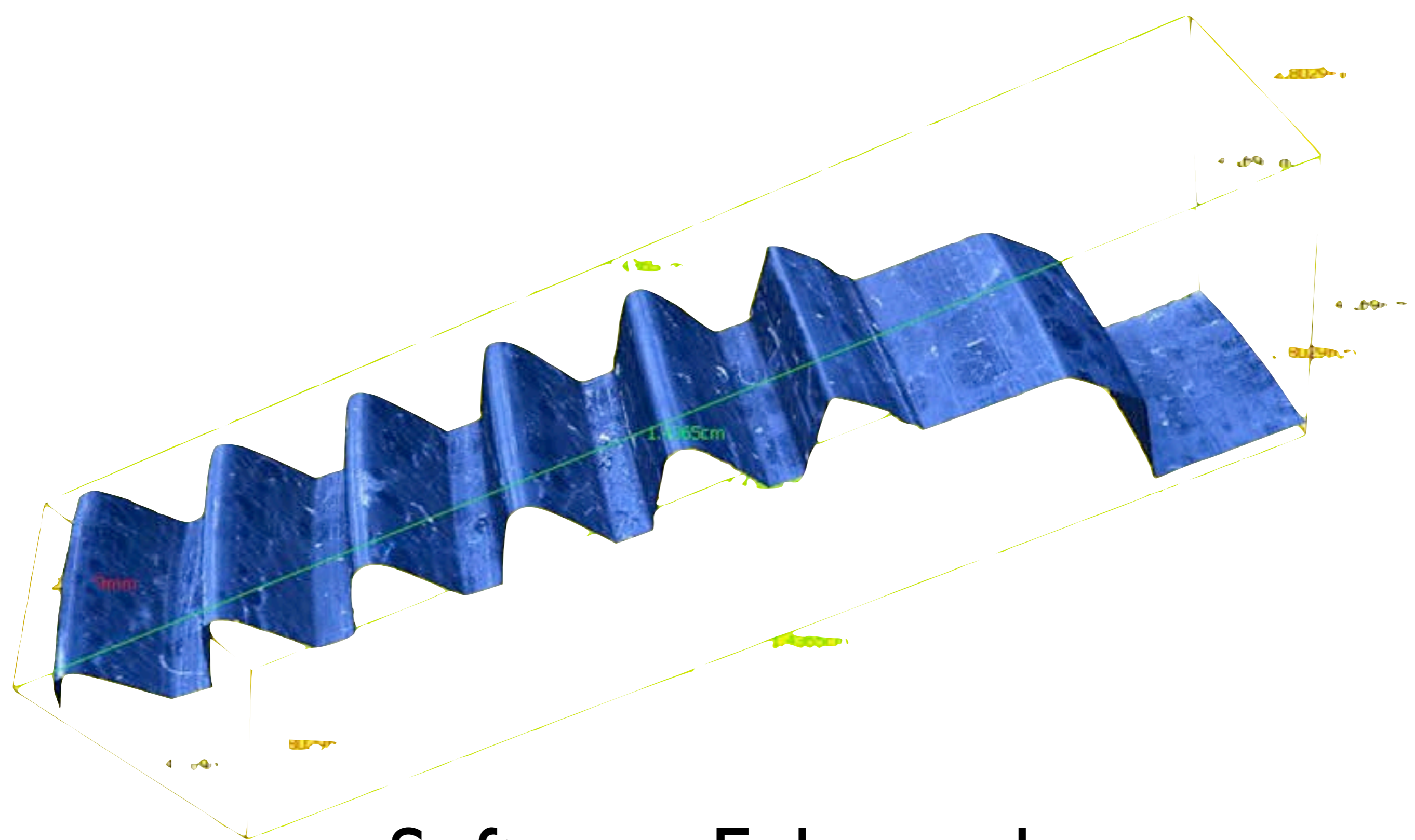
# Analytical Tools



# Measuring

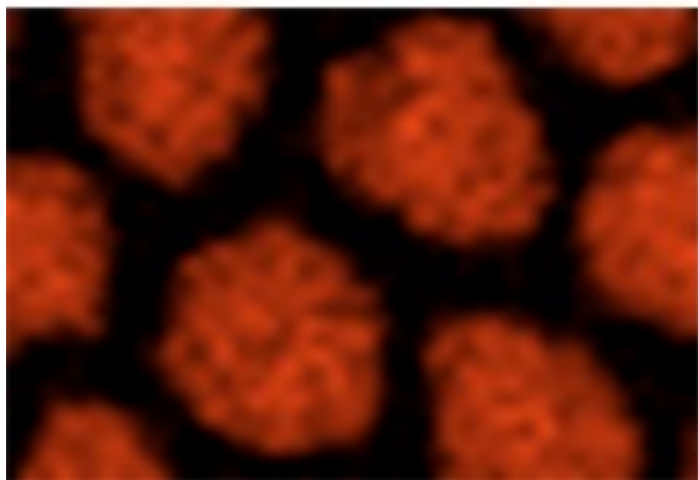
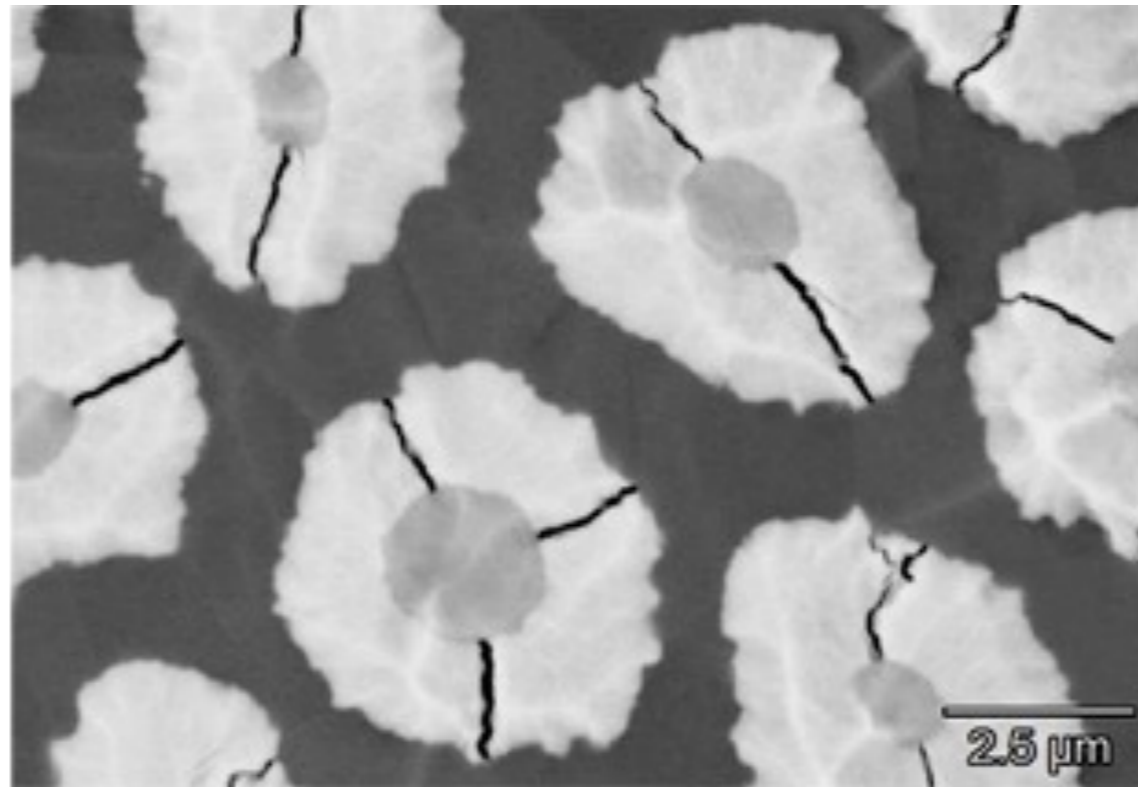
Full 2D  
Measurement capabilities  
After  
Calibration





# Software Enhanced 3D Measurement

# Elemental Analysis

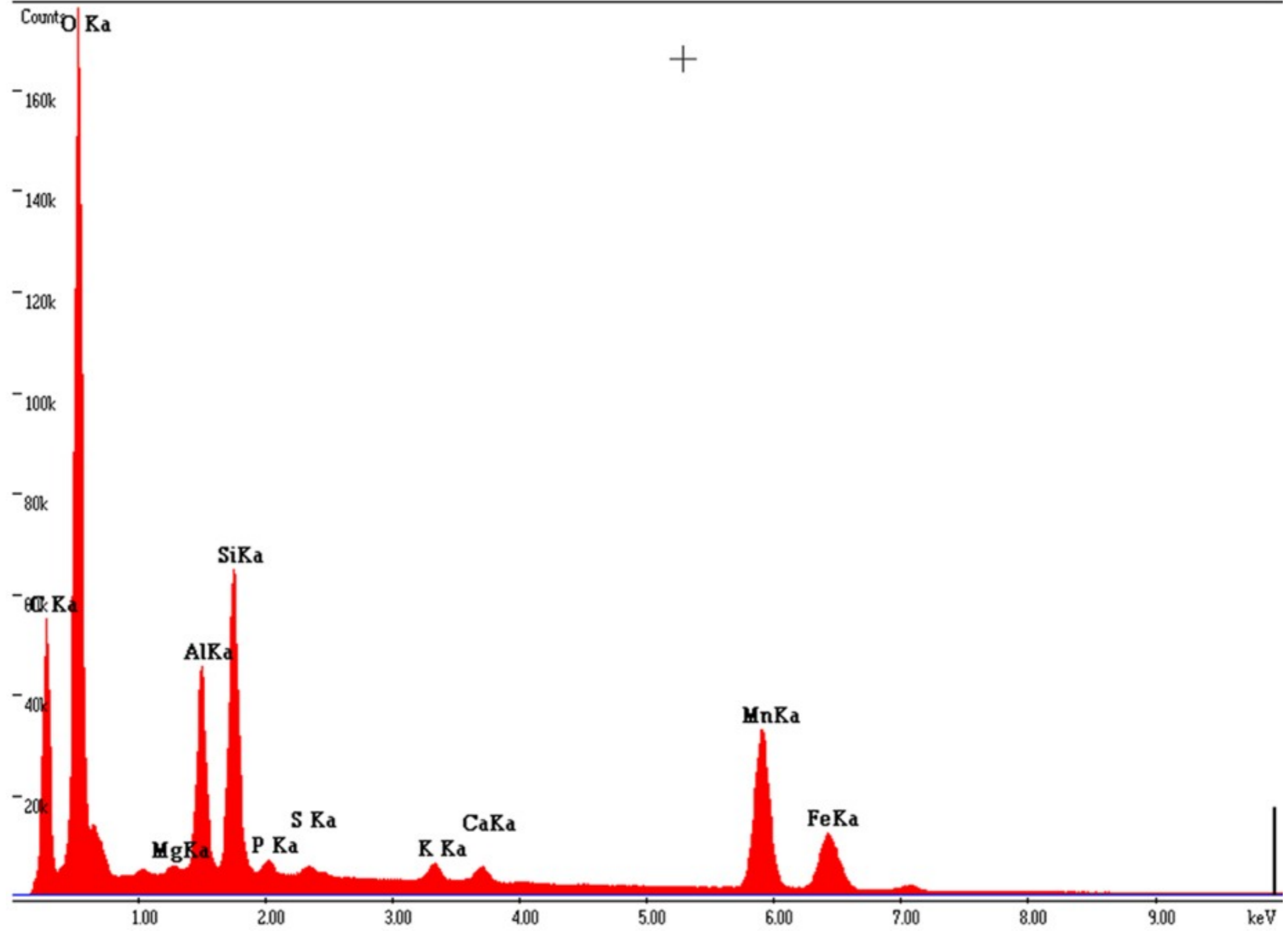


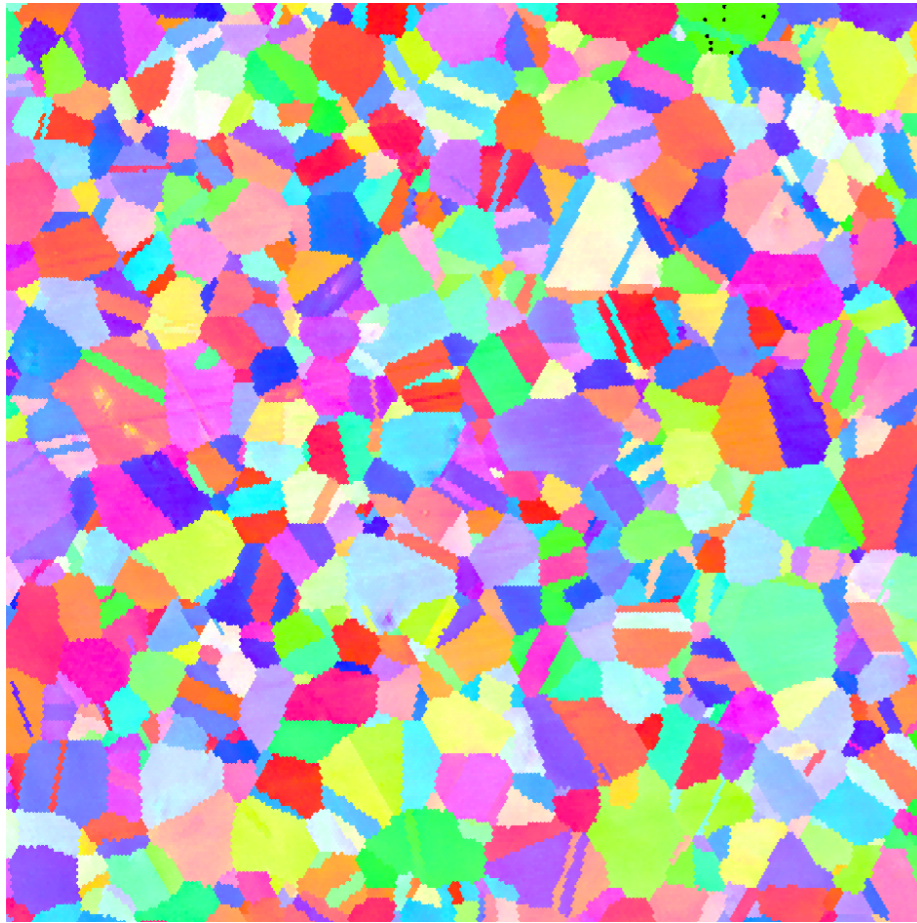
# EDX

*Energy Dispersive X-ray Spectroscopy*



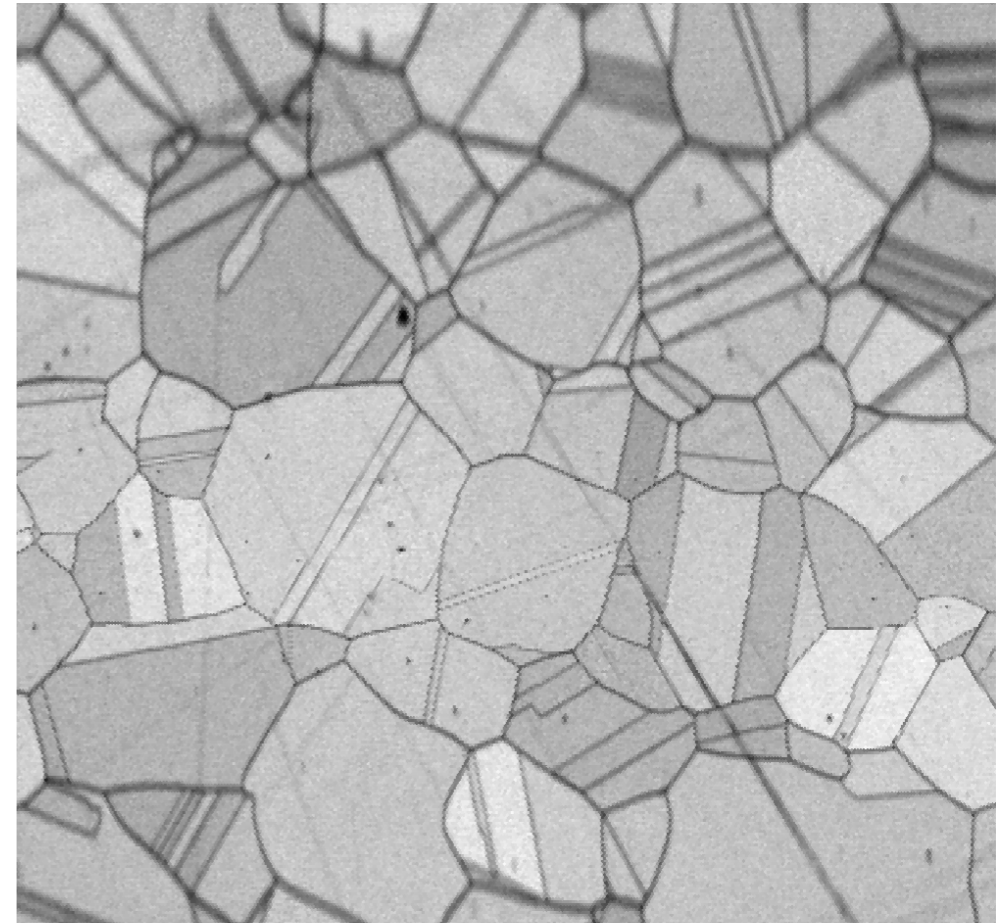
A:





120.0  $\mu\text{m}$  = 60 steps IPF [001]

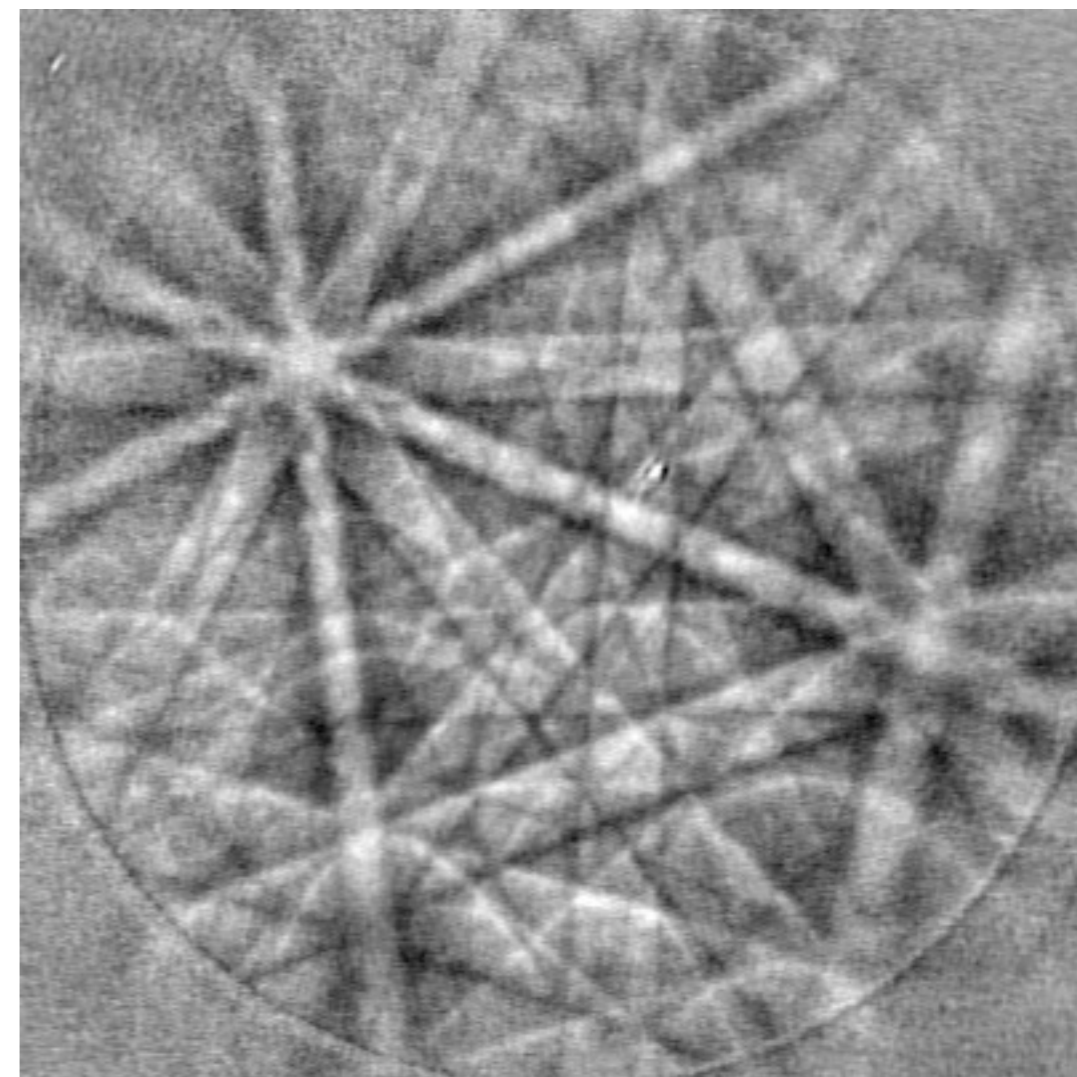
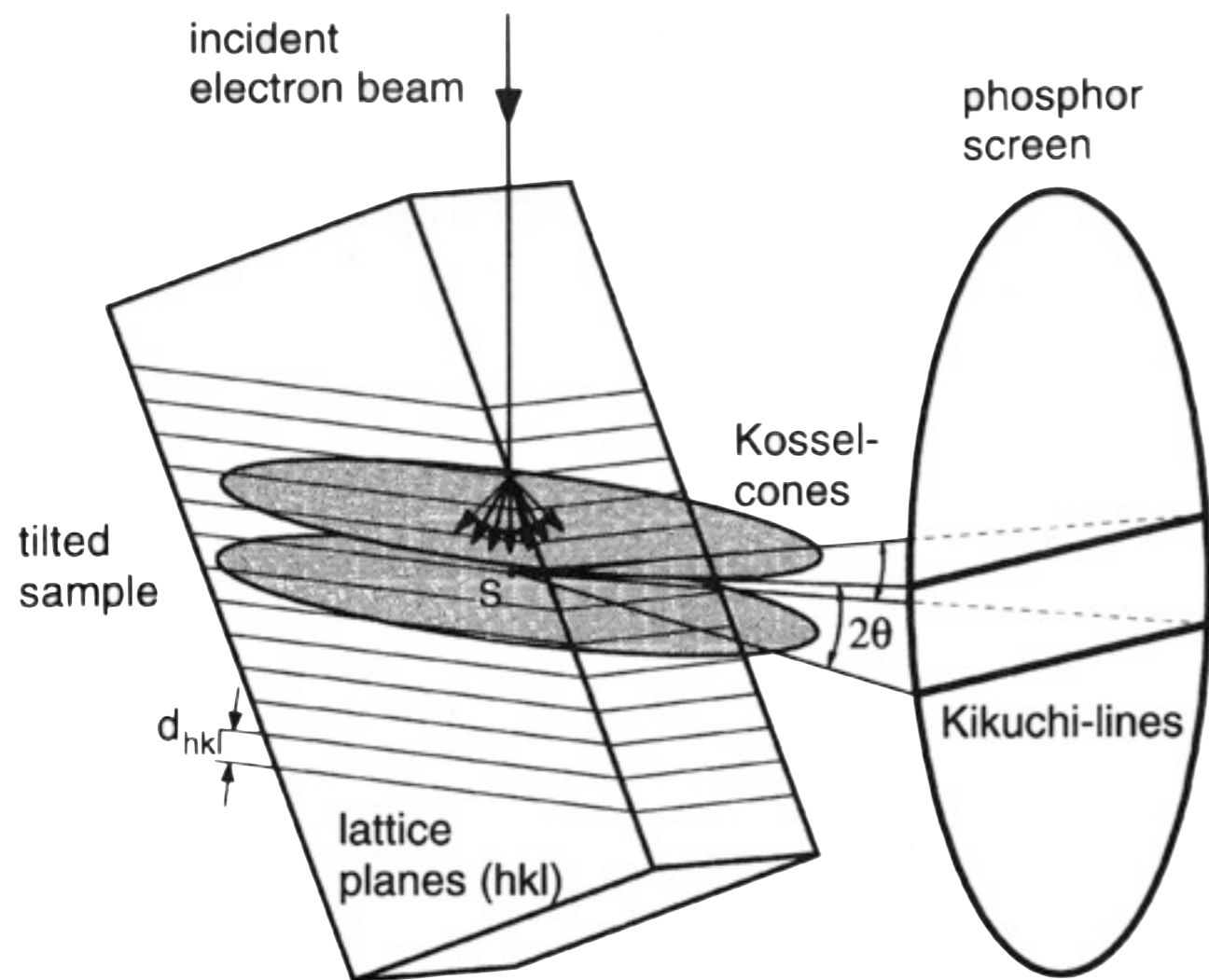
Color Coded Map Type:  
Inverse Pole Figure [001]



175.0  $\mu\text{m}$  = 70 steps IQ 74.352...385.66

# EBSD

*Electron Backscatter Diffraction*



# Summary

- Basic Operating Principles
- SEM Hardware
- Understand/acquire SEM images
- SEM Applications



# Focused Ion Beam Microscopy

**Microscope**

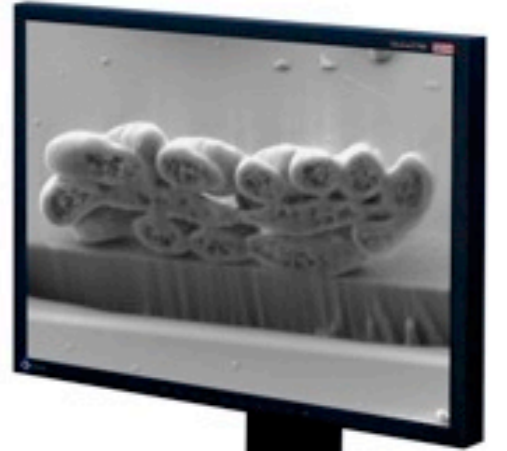


gemini

NVision 40

ZEISS

SII







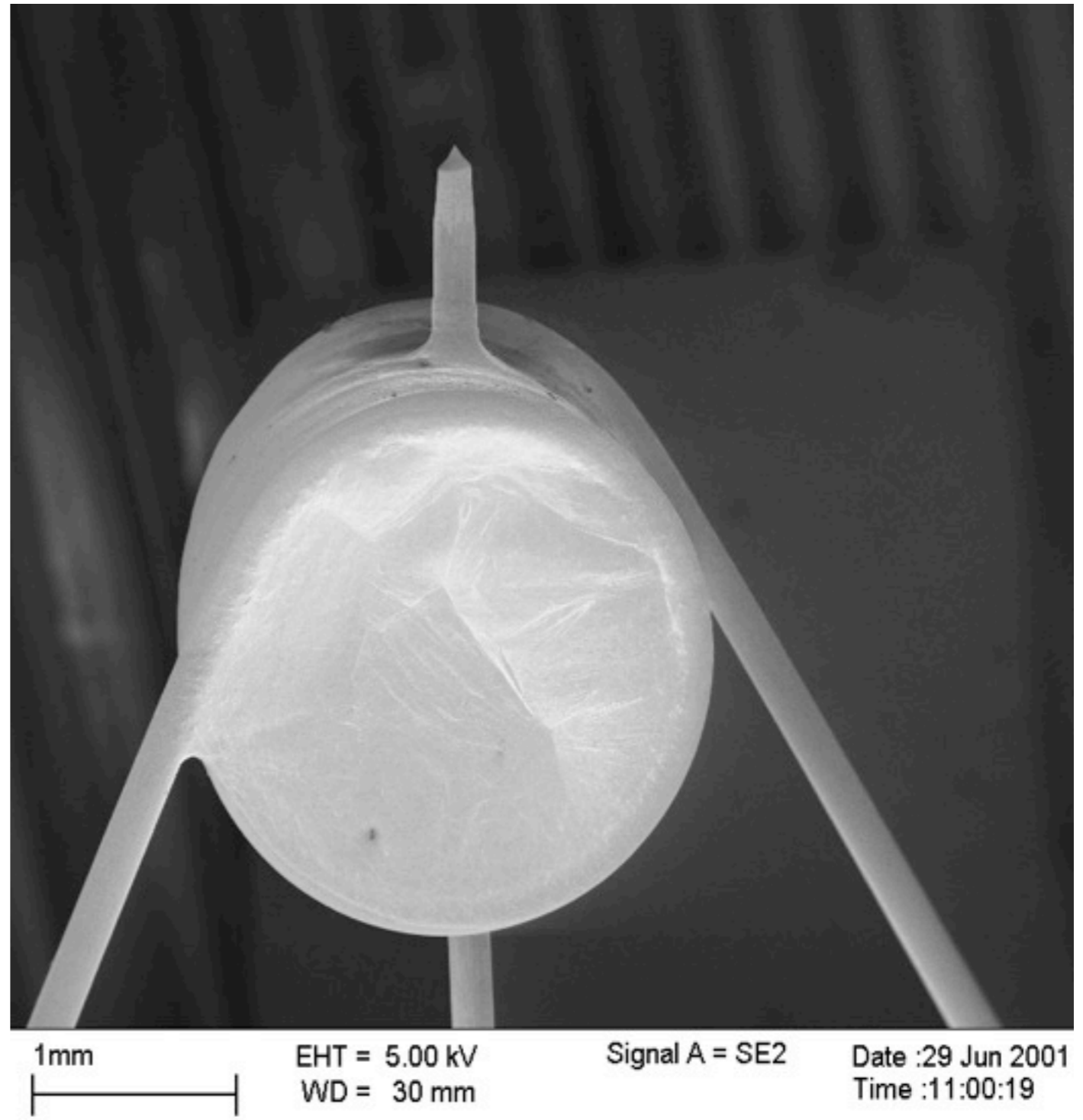
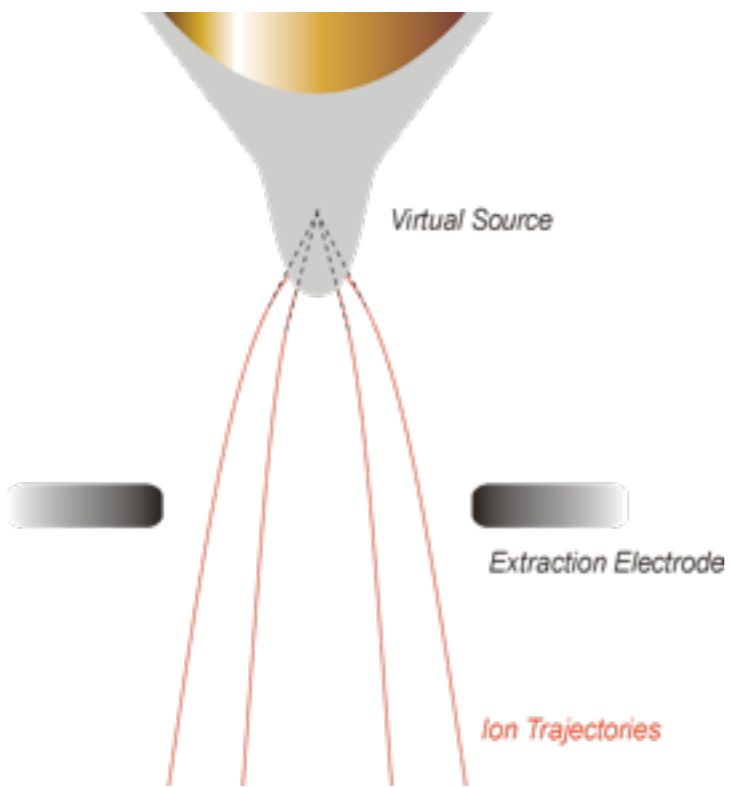
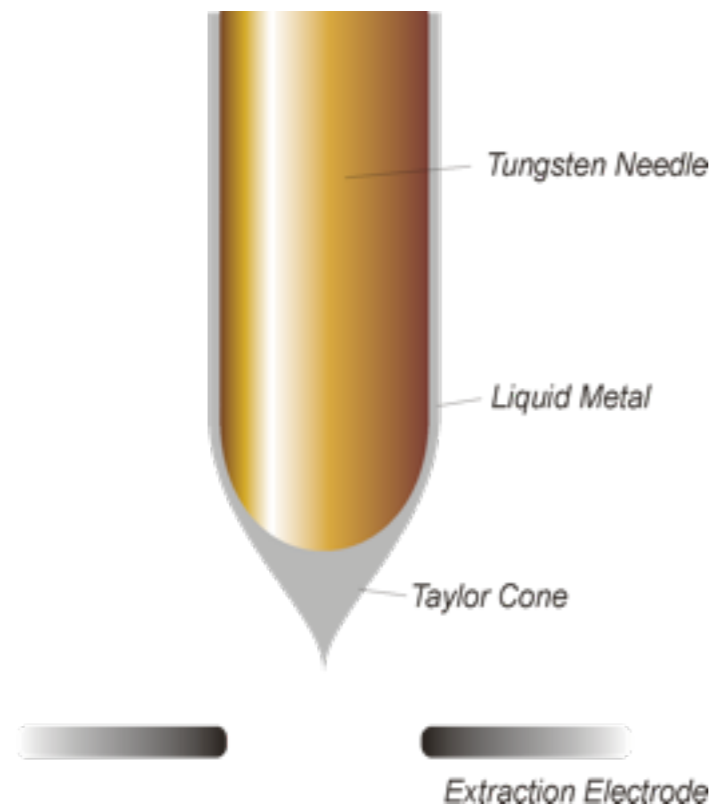
- Helios NanoLab Components
- FIB Column
  - Electron Beam Column
  - X-ray Detector
  - Stage
  - Omniprobe
  - Electronics
  - Gas Delivery System
  - IR-CCD
  - Sample Holders
  - Detectors
  - Work Station
  - Software

Views

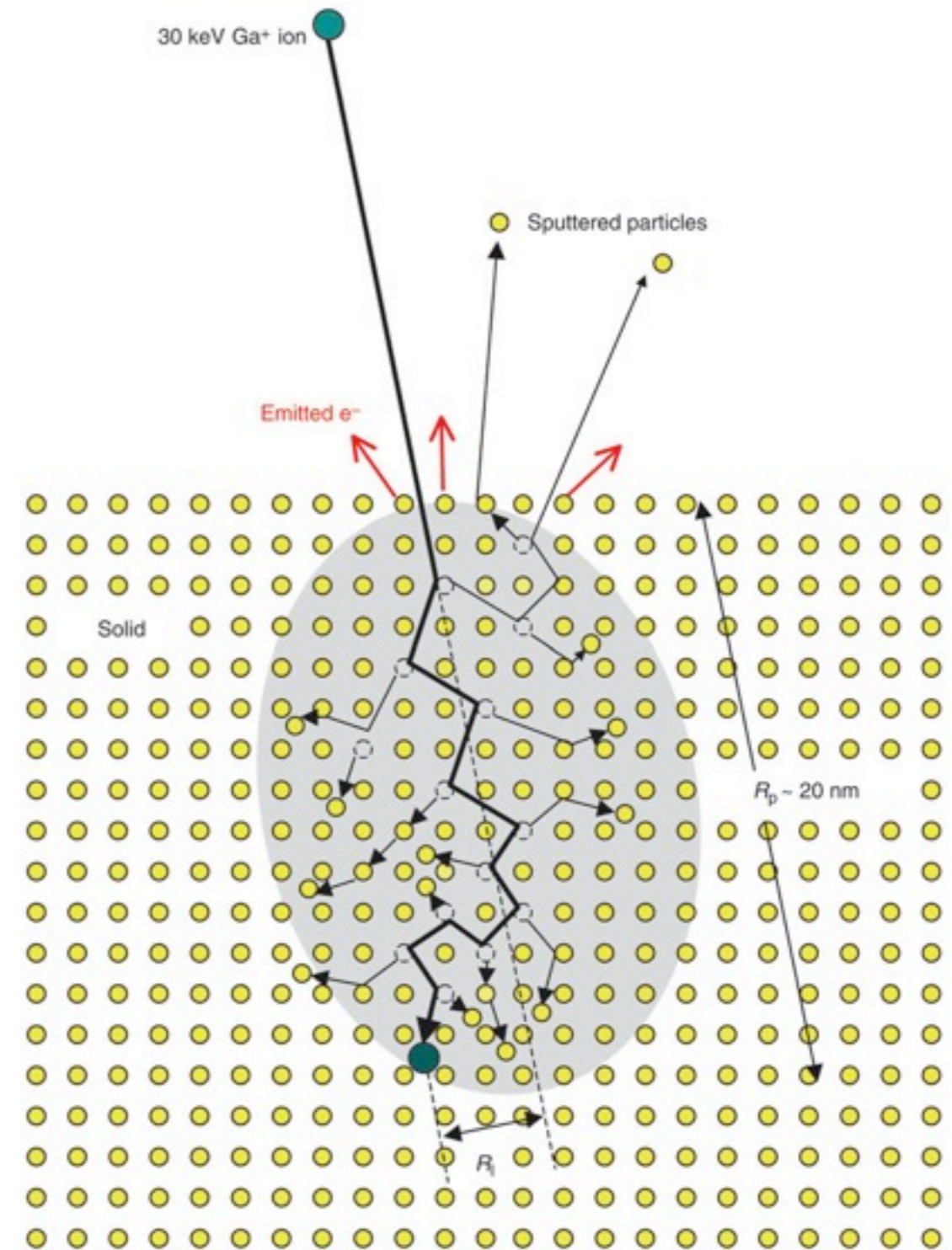


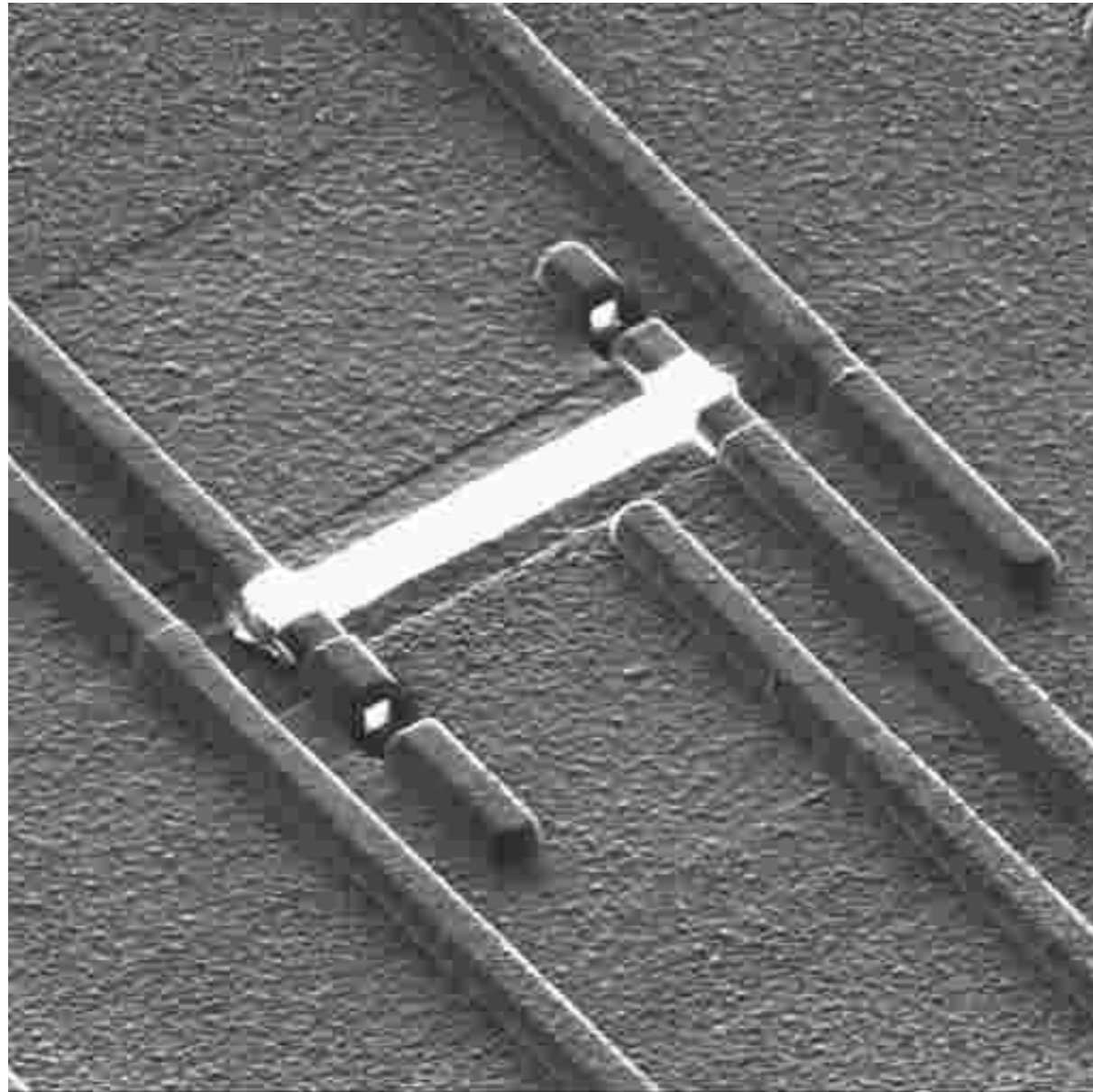




# Ion Interaction

SE, SI, sputtered particles,  
amorphization, etc.





Charge Contrast

Channeling Contrast



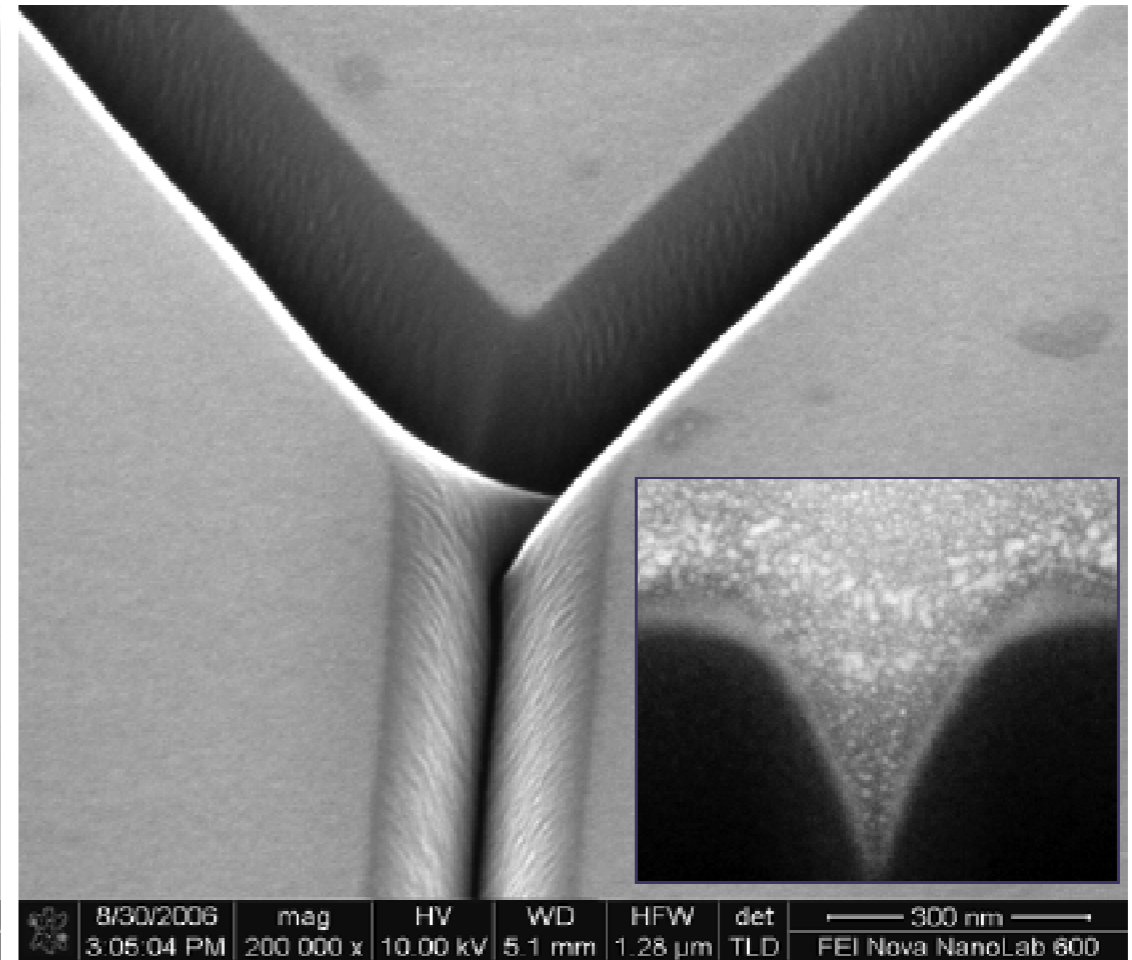
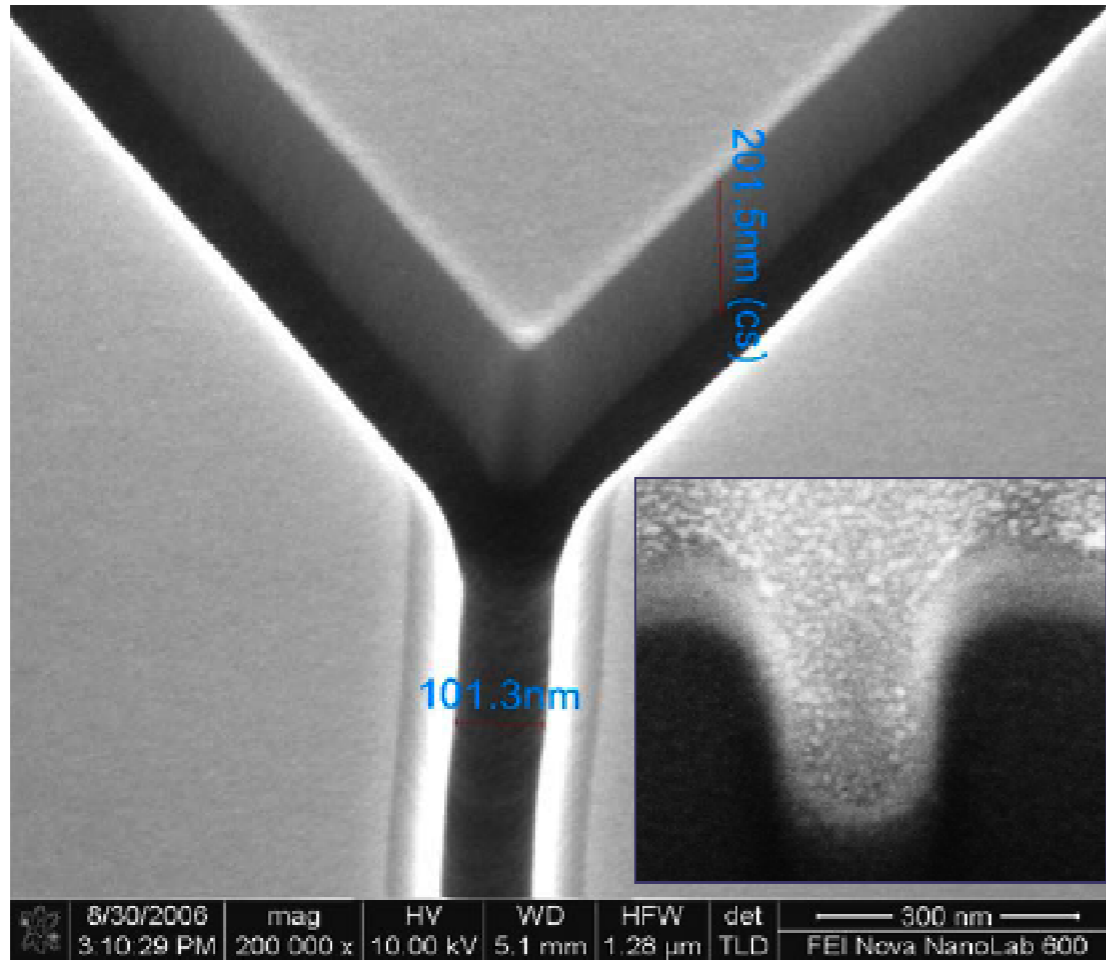
Channeling contrast image of annealed Au film

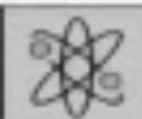
JEOL

10.0kV X20,000 1µm WD4.0mm

**Milling**







4/24/2006  
1:13:39 PM

HV  
10.00 kV

mag  
10000 x

det  
ETD

WD  
5.1 mm

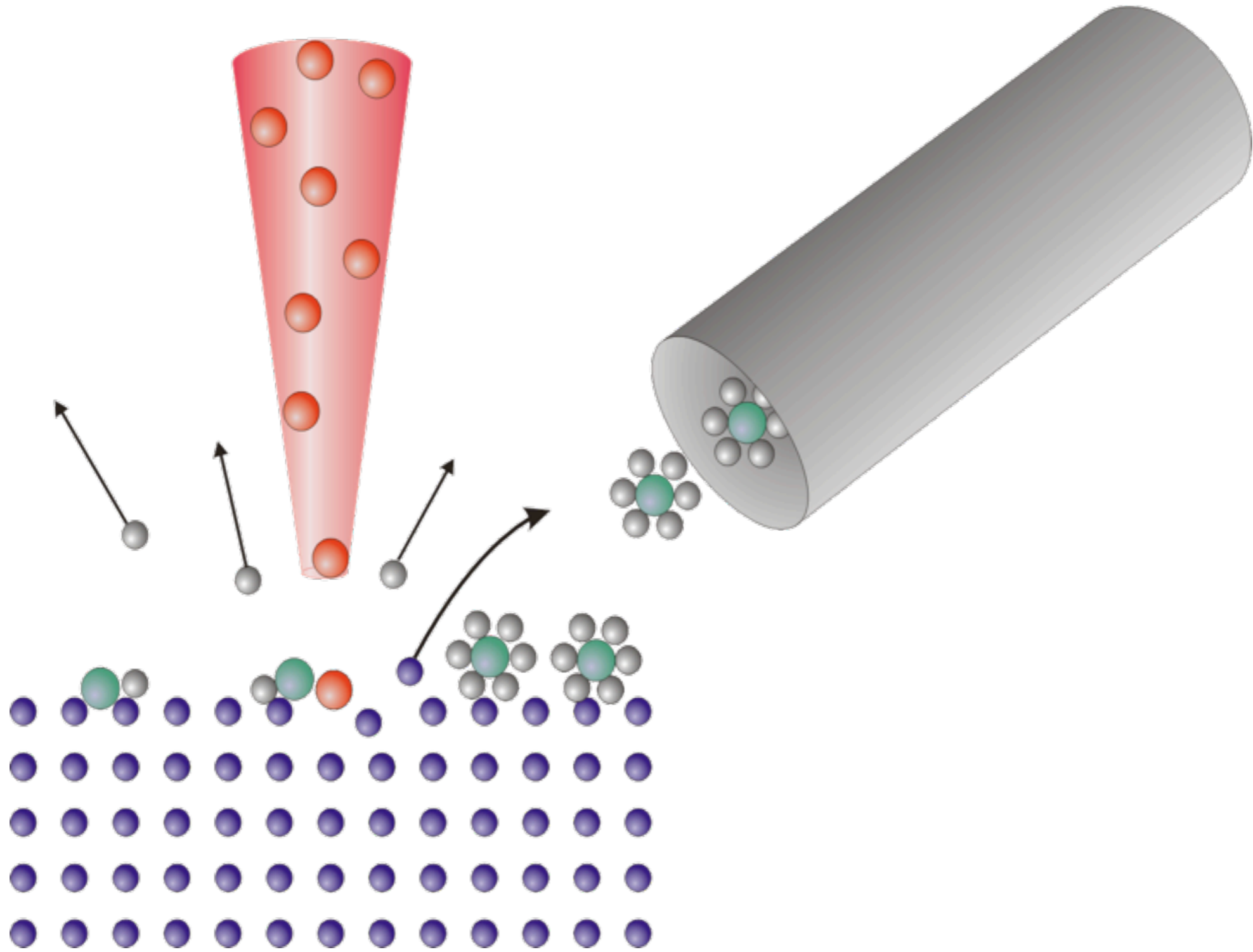
HFW  
24.0  $\mu\text{m}$

← 5  $\mu\text{m}$  →

FEI Nova NanoLab 600

# Gas Deposition

Primary ion beam







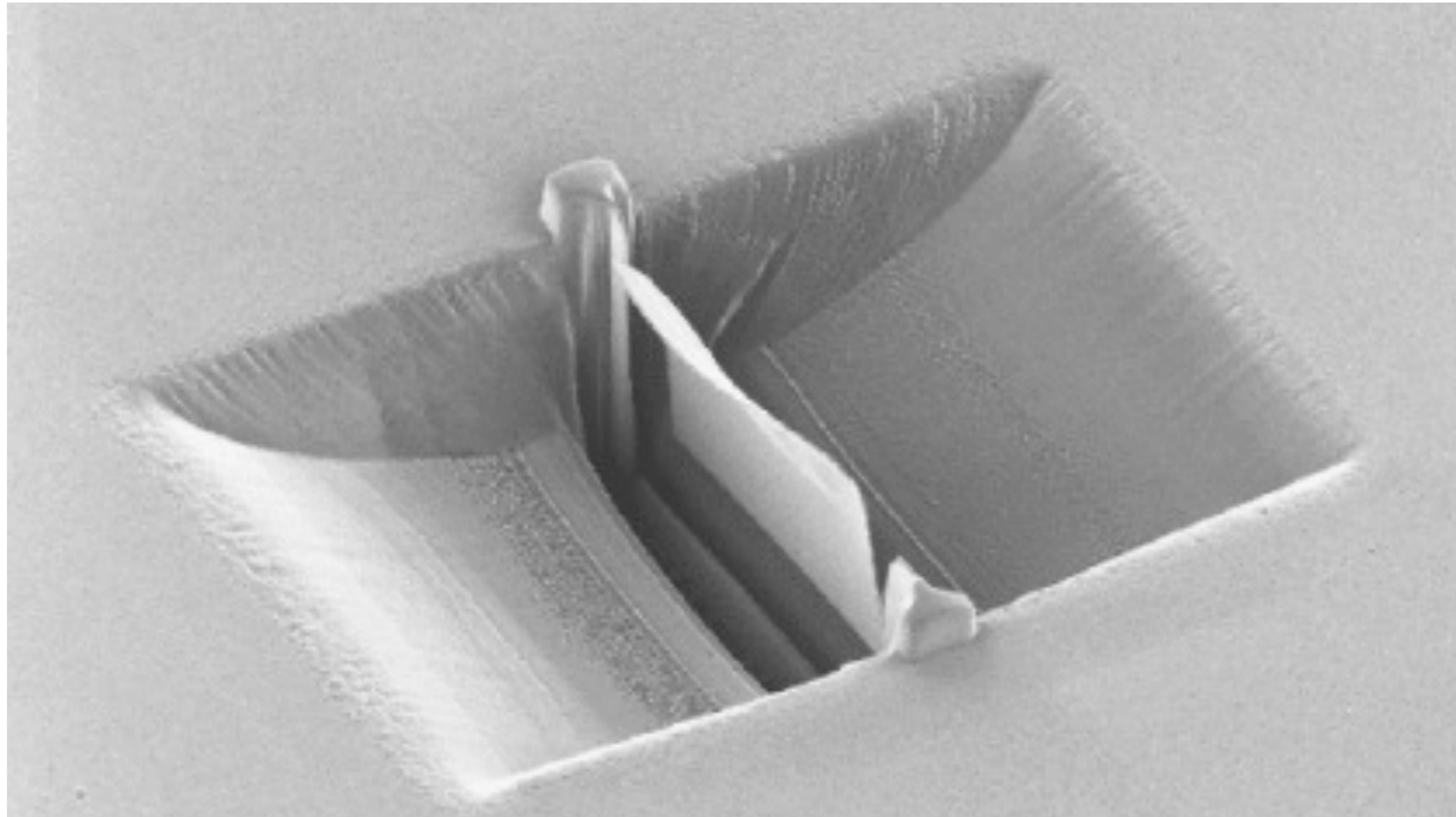
EBID

# Applications



R. Klengel, Fraunhofer IWM

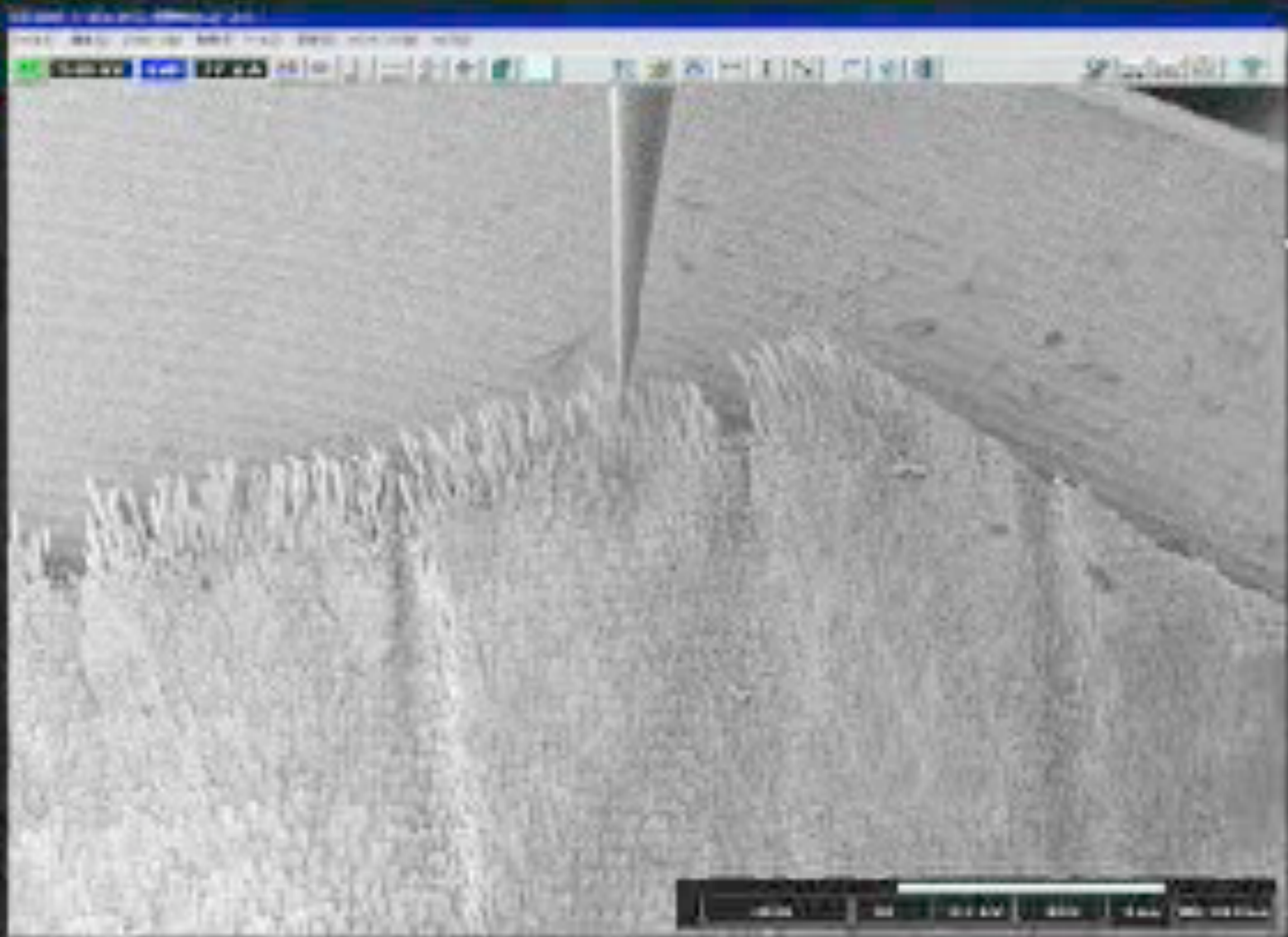
# X-sectioning

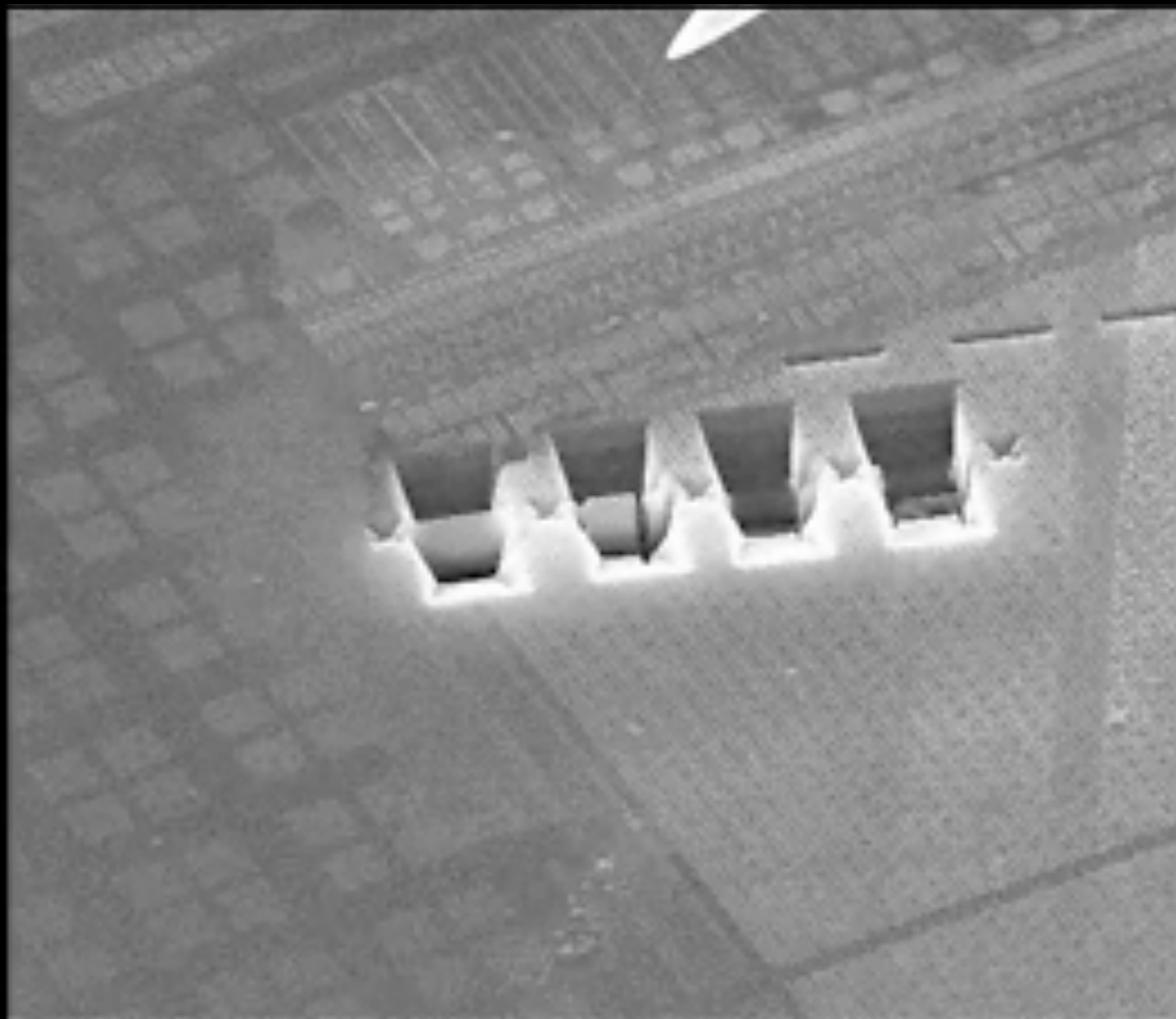




# TEM-Sample Preparation



# NanoProbing





	20.11.2005 14:18:13	VWD 15.0 mm	HFV 30.00 kV	cut 0.35 nA	dwell 100 µs	det ETD	 10 µm Olivetti, New York
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